Japanese Semiconductor Industry Conference

April 11–12, 1988 Hotel Century Hyatt Tokyo, Japan

Dataquest

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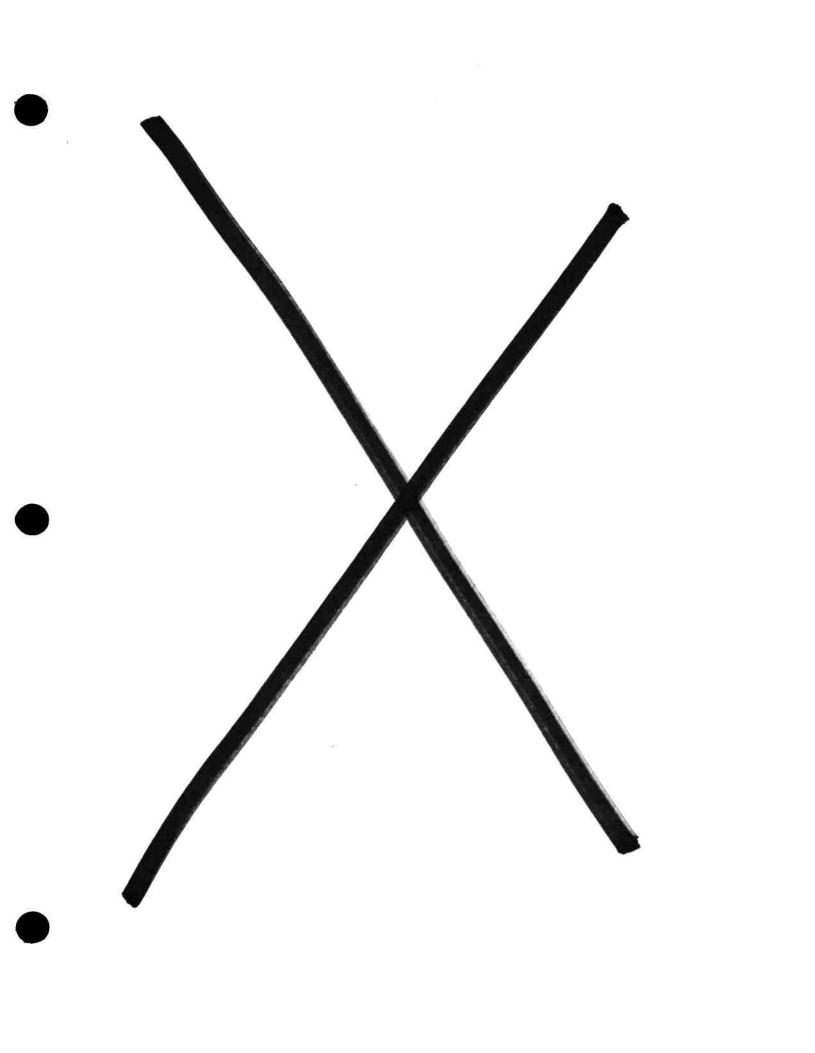
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1988 JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE

Japan's New International Role: Competition and Cooperation

April 11-12, 1988 Hotel Century Hyatt Tokyo, Japan

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MONDAY, April 11

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8:30 a.m.	Registration
9:30 a.m.	Welcome
10:00 a.m.	Japanese Industry Outlook
10:30 a.m.	World Semiconductor Outlook
11:00 a.m.	Who's Winning?
11:30 a.m.	INSEC's Activities to Date
12:00 Noon	Lunch
1:30 p.m.	Luncheon Speech
2:00 p.m.	Status of Japan-U.S. Semiconductor Trade Problems
2:30 p.m.	The Asian Age is Coming
3:00 p.m.	Break
3:30 p.m.	Analysis of European Electronics Technology
4:00 p.m.	Submicron Technology: Market Impacts

(Continued)

4:30 p.m.	Perspective on Semiconductor Applications
5:00 p.m.	Cocktails
TUESDAY, Apr	il 12
9:00 a.m.	Future Trends of 32-Bit TRON Microprocessors
9:30 a.m.	Joint Venture Strategies
10:00 a.m.	Leading ASIC Technologies
10:30 a.m.	Break
11:00 a.m.	Emerging Technologies in the 1990s
11:30 a.m.	Silicon and Epitaxial Wafers: Status and Future
12:00 Noon	Lunch
1:30 p.m.	Future Trends of the World Memory Market
2:00 p.m.	Japanese Semiconductor Equipment Industry: Status and Future
2:30 p.m.	Closing Remarks

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Conference Adjourns

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JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE EVALUATION QUESTIONNAIRE

Tokyo, Japan

April 11-12, 1988

Thank you for attending our Japanese Seminconductor Industry Conference. Would you please assist us in planning our next conference by completing and returning this questionnaire?

1. Please rate each presentation on a scale of 1 to 10 (where 10 is highest in terms of your approval):

	CONTENT	DELIVERY	COMMENTS
	(1 to 10)	(1 to 10)	(Use reverse side if necessary)
			•
Ohtake, Japanese Industry Outlook			
Norrett, World Semiconductor Outlook			
Davis, Who's Winning?			
Nebashi, INSEC's Activities in the Past Year			
Honda, Status of Japan-U.S. Semiconductor Trade Problems			
Wang, The Asian Age Is Coming			
Knorr, Analysis of European Electronics Technology			· · · · · · · · · · · · · · · · · · ·
Mizuno, Submicron Technology: Market Impacts			
Norman, Perspective on Semiconductor Applications			
Kimbara, Future Trends of 32-Bit TRON Microprocessors			
Goldman, Joint Venture Strategies			
Campbell, Leading ASIC Technologies			
Tatsuno, Emerging Technologies in the 1990s			<u> </u>
Sugawara, Silicon and Epitaxial Wafers: Status and Future			
de Dios, Future Trends of the World Memory Market			
Hayashi, Japanese Semiconductor Equipment Industry: Status and Future			

2. At our next conference, would you prefer more or less of the following types of speakers?

	More	Less
Dataquest speakers		
Speakers from large semiconductor companies		
Speakers from small semiconductor companies		
Speakers from semiconductor users		
Speakers from distributors		

(over)

3.	Please suggest other types of speakers you might like to hear:
4.	How would you rate the conference facilities (1 to 10)?
	Location Guest Rooms Meals Meeting Rooms Recreational Facilities
5.	Where would you like next year's conference to be held?
б.	Topics that would be of interest to you for the next JSIS conference:
7.	Comments:
8.	Your primary interest in the semiconductor industry is as a:
	Manufacturer User Other

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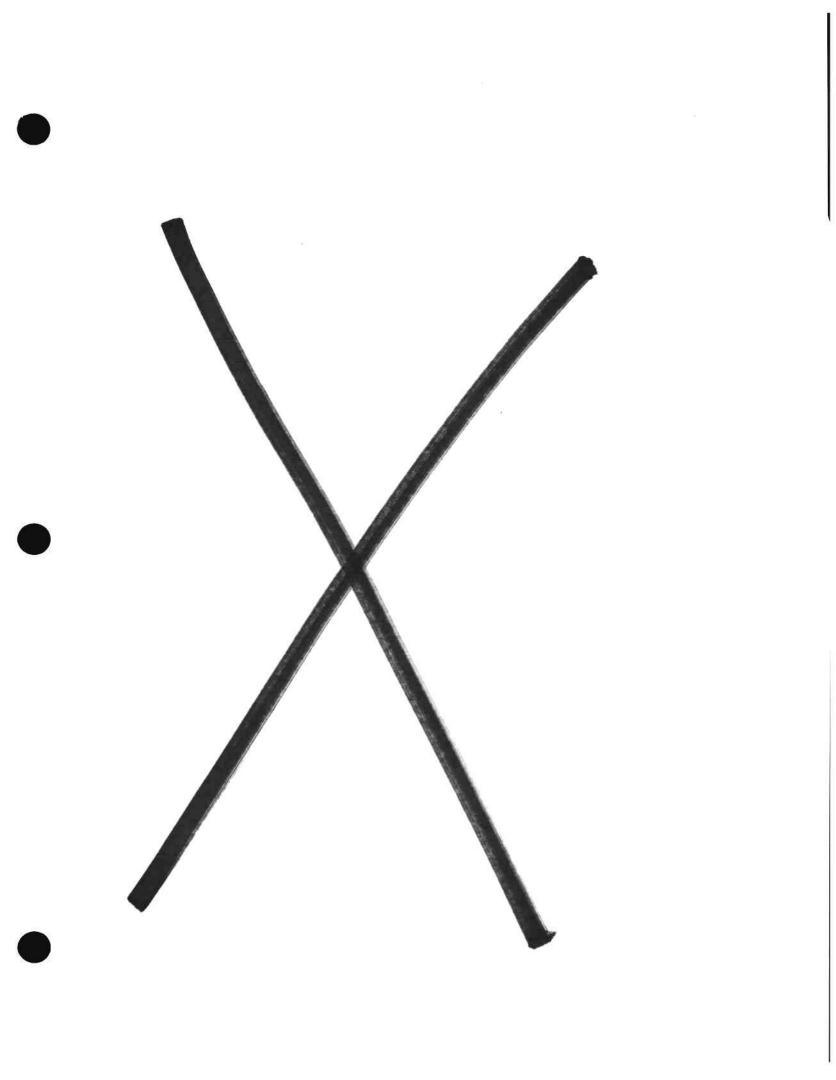
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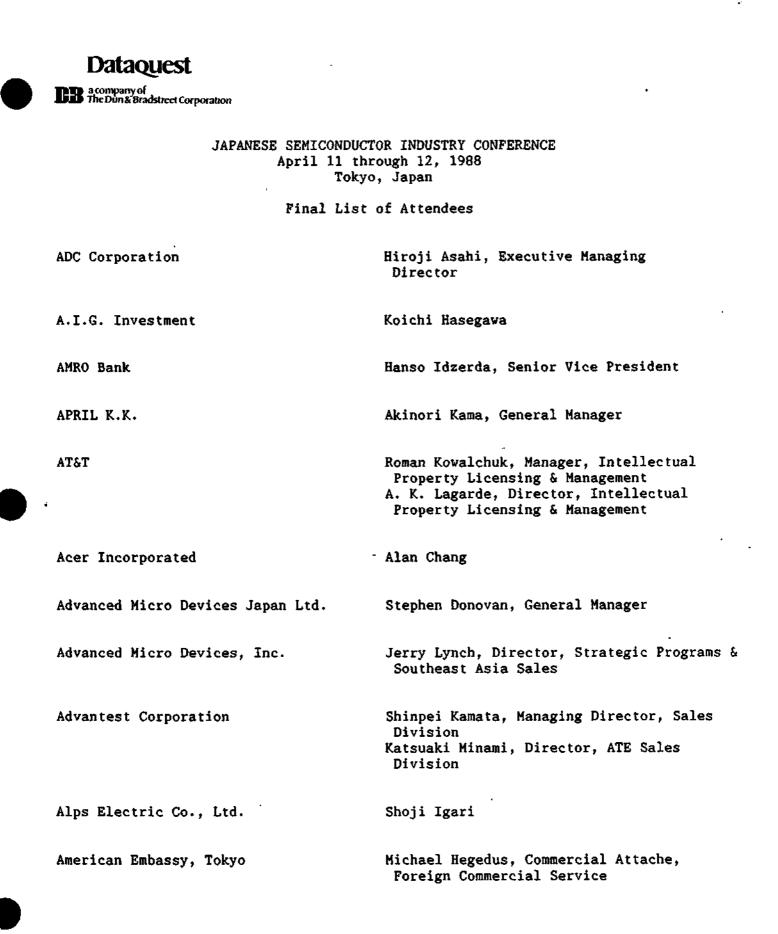
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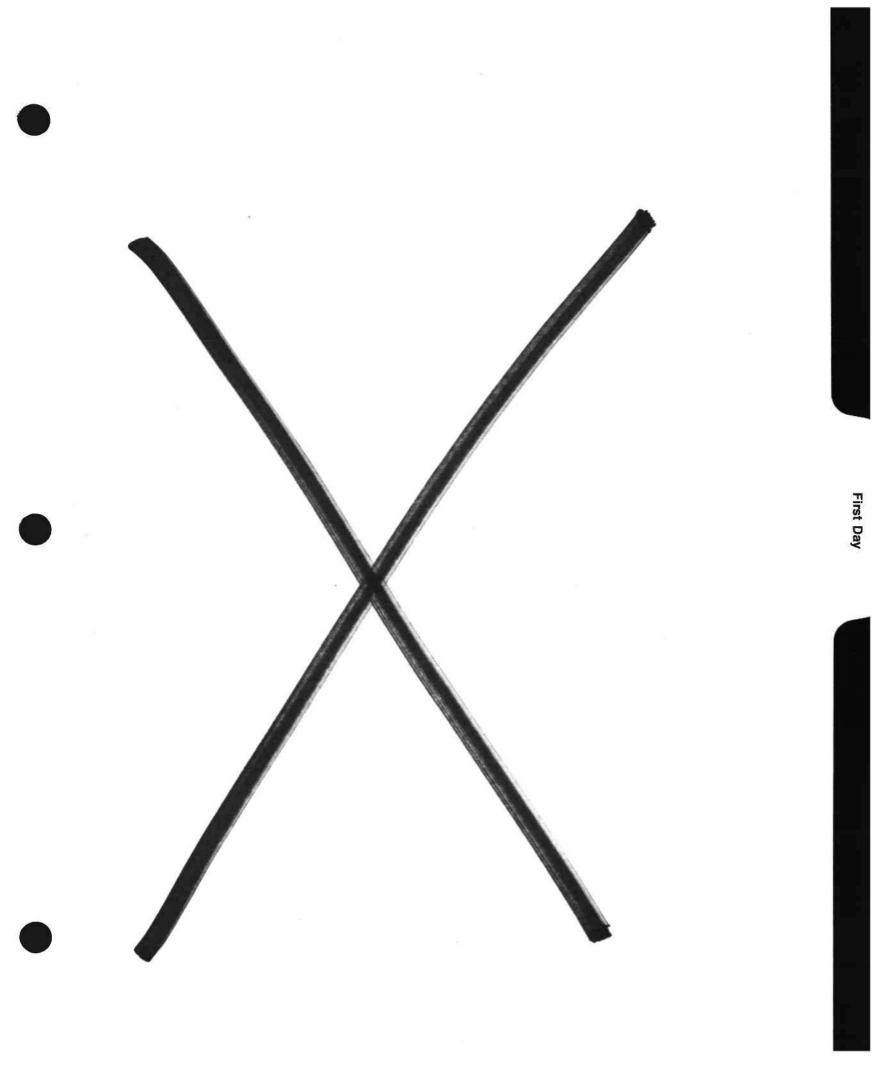
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JAPANESE INDUSTRY OUTLOOK

Osamu Ohtake Director Japan Components Group Dataquest Japan Limited

Mr. Ohtake is the Tokyo-based Director of Dataquest's Japanese Components Group and Director of the Japanese Semiconductor Industry Service. He is responsible for strategic research on technologies, markets, products, and manufacturers. Prior to joining Dataquest, Mr. Ohtake worked for 10 years as a reporter, and most recently as Components Group Manager, for <u>Dempa Shimbun</u>, a daily electronics industry newspaper published in Japan. He has also authored reports on the Japanese VLSI project and on the semiconductor materials and equipment markets. A native Japanese, Mr. Ohtake is a graduate of Tokyo Denki University, where he specialized in Communications.

> Dataquest Incorporated JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE April 11-12, 1988 Tokyo, Japan



Japan's New International Role: Competition and Cooperation

JAPANESE INDUSTRY OUTLOOK

OSAMU OHTAKE

Director Japanese Components Group Dataquest Japan Limited

CONTENT

- Competition
- Cooperation
- Japan's new roles
- Conclusions

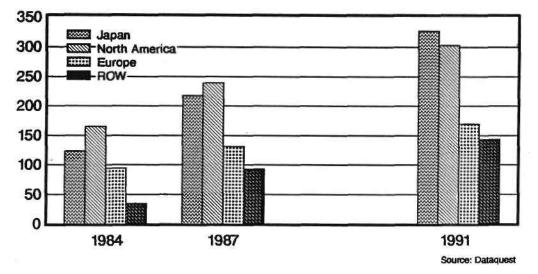
WORLD SEMICONDUCTOR SHARE

	(Millions of Dollars)		
	1977	1982	1987P
Japan	\$1,736	\$5,375	\$17,800
Europe	1,015	1,929	4,000
North America	4,179	7,829	14,200
ROW	14	98	600
Total	\$6,944	\$15,231	\$36,600

Source: Dataquest

ESTIMATED ELECTRONICS EQUIPMENT SHIPMENTS

Millions of Dollars

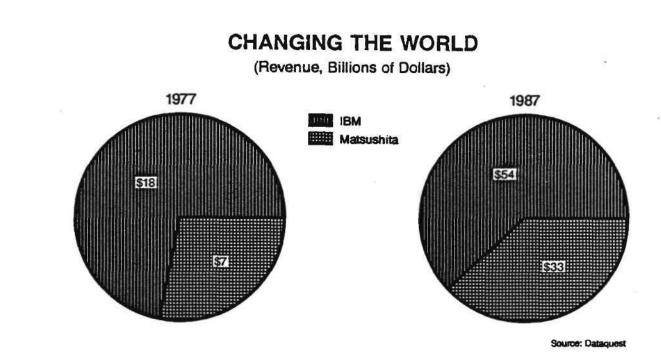


PERCENTAGE OF PAPERS AT ISSCC

(By Country of Origin)

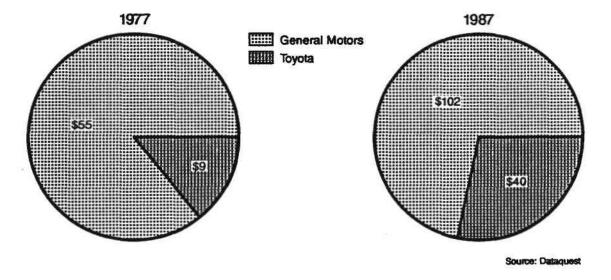
	1986	1987	1988
Japan	37%	44%	35%
Europe	10	13	11
North America	53	43	54
Total	100%	100%	100%

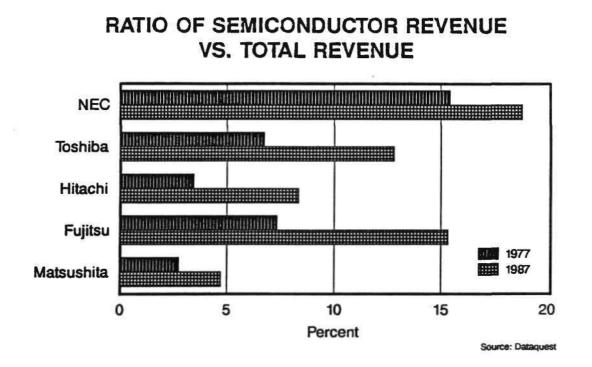
Source: Dataquest



CHANGING THE WORLD

(Revenue, Billions of Dollars)





COMPETITION: MEMORY JAPAN'S SHARE IN THE WORLD

(Percentage	of Production L	Inits)		
1982 19				
64K DRAM	66%	58%		
256K DRAM	100%	65%		
1Mb DRAM	N/A	98%		
N/A = Not Applicable				

Source: Dataquest

COMPETITION: MICRO JAPAN'S SHARE IN THE WORLD

(Percentage of Production Units)

	1982	1987
4-Bit MCU	72%	62%
8-Bit MCU	27%	45%
8-Bit MPU	23%	25%
16-Bit MPU	11%	30%

COMPETITION: ASICs JAPAN'S SHARE IN THE WORLD

(Percentage of Worldwide ASICs)

	1983	1987
ASIC Total	49%	42%
Gate Array	37%	47%
PLD	-	-
CBIC	5%	19%

Source: Dataquest

Source: Dataquest

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COOPERATION: JOINT VENTURES

History of Joint Ventures in Japan

	Japanese		
Year	Company	Partner	Status
1952	Matsushita	Philips	MEC
1960	NJRC	Raytheon	NEW JRC
1963	Kyosan	IR	Nihon IR
1968	Sony	TI	Discontinued
1972	TDK	Fairchild	Discontinued
1973	Alps Electric	Motorola	Discontinued
1985	Kawasaki Steel	LSI Logic	Nihon Semicon.
1987	Toshiba	Motorola	Tohoku Semicon.

Source: Dalaquest ,

COOPERATION: JOINT VENTURES

Joint Ventures Outside Japan by Japanese Companies

Year .	Japanese Company	Partner	Status
1971	Seiko	Micro Power	-
1971	Rohm	Exar	-
1985	Mitsubishi Electric	Westinghouse GE	Powerex
1986	Sharp	RCA	Discontinued

Source: Dataquest

COOPERATION: ALLIANCES

Semiconductor Makers	<u>1980</u>	1981	1982	1983	<u>1984</u>	1985	<u>1986</u>	<u>1987</u>
Joint Ventures	1	1	5	3	11	32	16	30
Licensing Agreements	2	5	5	11	19	22	60	33
Equipment Manufacturers	0	5	12	8	26	17	25	15
Total	3	11	22	22	56	71	101	78*
*Preliminary							Source: D	ataquest

Japanese Semiconductor Strategic Alliances

NEW ROLE: PRODUCTION CONTROL

Advantages:	No dumping
	Positive aspects for suppliers with major market share
Disadvantages:	Negative impact on end users Negative consequences for Europe and ROW
	Source: Dataquest

NEW ROLE: MARKET ACCESS

Advantages: Reduced trade friction

Less expensive imports due to high yen

New technology and software

NEW ROLE: MARKET ACCESS

Disadvantages:

Declining domestic market share (merchant and captive)

Quality and lead time problems

NEW ROLE: OVERSEAS PRODUCTION

Japanese Semiconductor Plants Outside Japan

Year	Company	Location	Status	Remarks
1967	Hitachi	Taiwan	Assembly	
1971	Rohm	U.S.	Full	Exar
1970	Sanyo	Brazil	Assembly	
1972	Sanyo	Korea	Assembly	Tokyo Silicon
	Hitachi	Malaysia	Assembly	-
1974	Toshiba	Malaysia	Assembly	
1976	NEC	Malaysia	Assembly	
	NEC	Ireland	Assembly	
	Sanyo	Taiwan	Assembly	
1978	Matsushita	Singapore	Assembly	
				(Continued)

NEW ROLE: OVERSEAS PRODUCTION

Japanese Semiconductor Plants Outside Japan Year Company Location Status Remarks 1979 Toshiba Mexico Full NEC **U.S**. 1978 Full Electronic arrays 1980 Fujitsu Ireland Assembly 1980 Hitachi W. Germany Assembly 1981 Fujitsu **U.S**. Assembly 1982 Toshiba W. Germany Assembly NEC U.K. Assembly 1984 NEC U.S. Full Roseville, CA PRC Assembly Sanyo

(Continued)

NEW ROLE: OVERSEAS PRODUCTION

Japanese Semiconductor Plants Outside Japan

Year	Company	Location	Status	Remarks
1985	Mitsubishi	U.S.	Assembly	
1986	Fujitsu	Singapore	Assembly	

CONCLUSIONS

• Competition and cooperation will continue

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- Industry needs to have win-win relationships
- Japan is expected to take on new roles in the world

CONCLUSIONS

Japan's New Roles

- Behave as world leader
- No dumping
- Create new products and markets
- One-way exports are unacceptable
- Importance of market access

CONCLUSIONS

Japan's New Roles

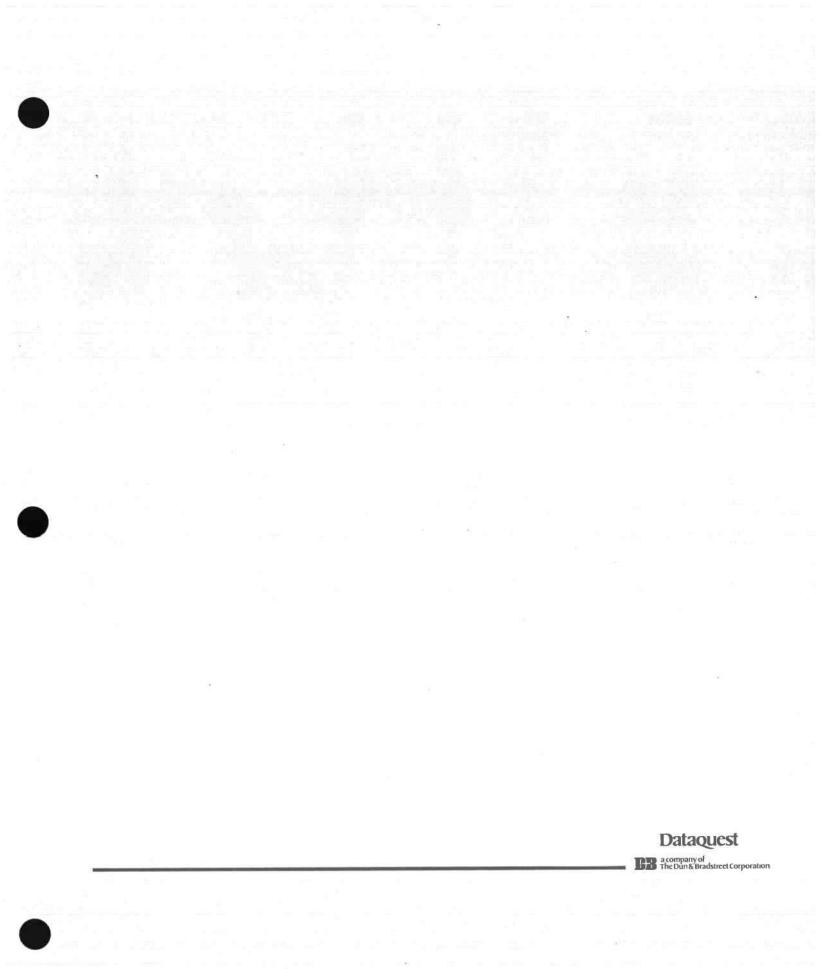
- Technology transfer
- Overseas productions
- Joint ventures and alliances

FAVORITE SHOPPING ITEMS

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- Japan Cameras, camcorders, pocket TVs, and kimonos
- France Gucci, Hermes, Louis Vuitton, and wines
- Germany Mercedes, BMWs, Solingens, and cutlery
- Italy Shoes and belts
- U.S. Beef, hamburger, and chocolate





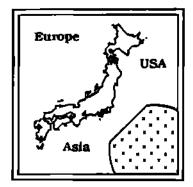


WORLD SEMICONDUCTOR OUTLOOK

Gene Norrett Corporate Vice President and Division General Manager Components Division Dataquest Incorporated

Mr. Norrett is a Corporate Vice President of Dataquest and General Manager of its Components Division. In this capacity, he has direct responsibility for all U.S. research and coordinates European and Japan-based research. Prior to becoming Division General Manager, he founded Dataquest's Japanese Semiconductor Industry Service and was Acting Managing Director of Dataquest Japan K.K. Before joining Dataquest, Mr. Norrett spent 14 years with the Motorola Semiconductor Product Sector, serving in various marketing and management positions. He has traveled extensively in Japan, Hong Kong, Taiwan, Korea, China, and Europe. Mr. Norrett's educational background includes a B.A. degree in Mathematics from Temple University and an M.S. degree in Applied Statistics from Villanova University. He has also taken graduate courses in Marketing from Arizona State University.

> Dataquest Incorporated JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE April 11-12, 1988 Tokyo, Japan



Japan's New International Role: Competition and Cooperation

WORLD SEMICONDUCTOR OUTLOOK

GENE NORRETT

Corporate Vice President and Division General Manager Components Division Dataquest Incorporated

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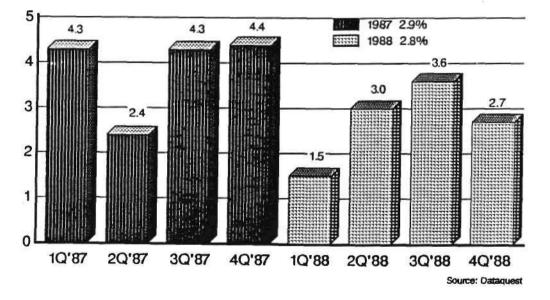
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AGENDA

- Economics
- Electronics industry
- Semiconductor industry
- Forecast
- Summary

U.S. REAL GNP GROWTH

(Estimated Percent Change at Annual Rates)



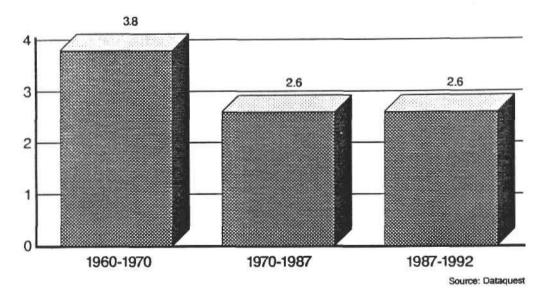
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Recession Unlikely in 1988

U.S. REAL GNP GROWTH

(Estimated Percent Change at Annual Rates)

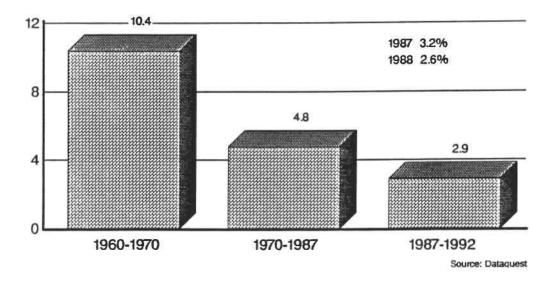


BENEFITS OF MODERATE GROWTH

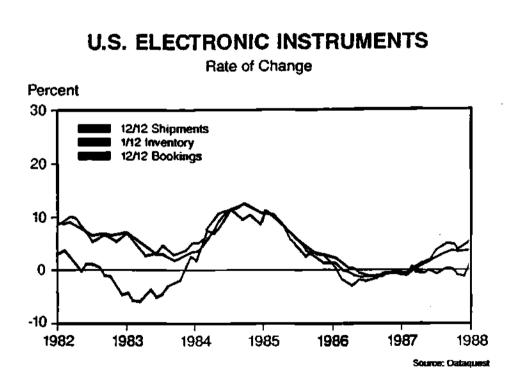
- Lower inflation
- Lower dependence on foreign capital
- More stability

JAPAN: REAL GNP GROWTH

(Estimated Percent Change at Annual Rates)

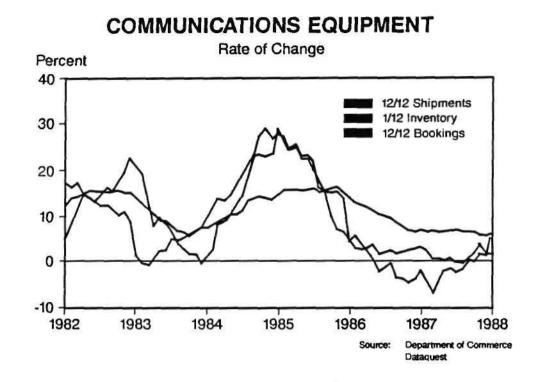


ELECTRONICS INDUSTRY

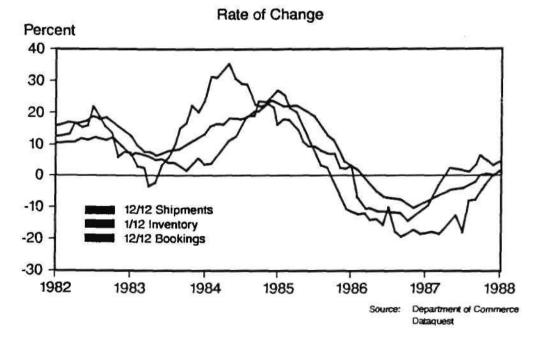


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COMPUTERS AND OFFICE MACHINES



U.S. PERSONAL COMPUTER MARKET

(Millions of Dollars)

	1987	1988	Percent Growth
Personal Computers	\$19,725	\$23,073	17.0%
Less than \$1,000	1,244	1,340	7.7%
\$1,000 to \$5,000	13,958	15,718	12.6%
\$5,000 to \$10,000	4,523	6,014	33.0%
			Source: Dataquest

NORTH AMERICAN ELECTRONIC EQUIPMENT FORECAST

(Billions of Dollars)					
	1986	1987	Percent Change 1986-1987	1988	Percent Change 1987-1988
Data Processing	\$ 92.3	\$101.9	10.4%	\$111.8	9.7%
Communications	24.9	27.0	8.1%	29.5	9.3%
Industrial	32.7	35.2	7.7%	39.1	11.1%
Consumer	17.0	18.4	7.9%	19.1	3.8%
Military	49.7	47.5	(4.4%)	46.9	(1.3%)
Transportation	9.6	10.8	12.8%	11.8	9.3%
Total	\$226.2	\$240.7	6.4%	- <u></u> \$258.2	7.3%

Source: Dataquest

SEMICONDUCTOR INDUSTRY

WORLD SCOREBOARD

	Worldwide	e Semiconductor Mark (Millions of Dollars)	et Shares	
1987 Rank	1986 Rank		1986 Sales	1987 Sales
1	1	NEC	2,638	3,193
2	3	Toshiba	2,276	2,939
3	2	Hitachi	2,307	2,781
4	4	Motorola	2,025	2,450
5	5	Texas Instruments	1,781	2,125
6	6	Fujitsu	1,365	1,899
7	8	Philips - Signetics	1,258	1,597
8	11	Intel	991	1,500
9	10	Mitsubishi	1,136	1,481
10	9	Matsushita	1,206	1,479

Source: Dataguest

THE "REGIONS" SCOREBOARD

Semiconductor Revenue (Billions of U.S. Dollars) United States

		<u>1986</u>	<u>1987</u>	<u>% Change</u>
1	Motorola	1.309	1.684	21%
2	Texas Instruments	.845	.980	16%
3	Intel	.629	.910	45%
4	National/Fairchild	.832	.84 8	2%
5	AMD/MMI	.515	.613	19%

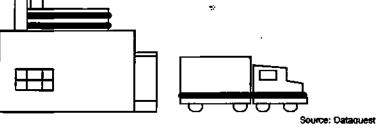
U.S. MARKET STATUS

Source: Dataquest

- Book-to-bill ratio for February = 1.18
- Backlogs rising rapidly
- Third quarter slump?
- Computer, communications, and automotive very healthy
- ASIC revolution
- DRAM shortage!!

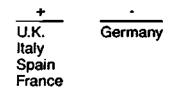
WHAT DID THEY SAY?

Anticipated Shift to Offshore Production 1986 1987 1988 3.3% 10.1% A Great Deal 8.4% 35.9% Some 33.2% 34.0% Not at All 62.7% 55.7% 56.7%



EUROPEAN MARKET STATUS

- Book-to-bill ratio for February = 1.15
- DRAM shortage affecting medium-size OEMs
- Inventories increasing due to imbalances
- U.K. telecom and PC compatibles
- Audi/VW/MB refocusing product strategies
- Capital investments picture:



France privatization

JAPANESE MARKET STATUS

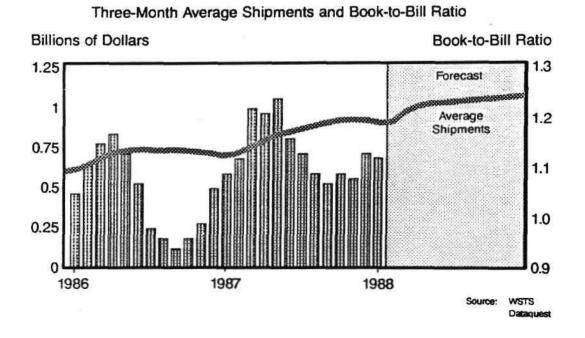
- Consumer electronics market down 8.4% (yen base, 1987/88)
- Industrial electronics up 4.1% (yen base, 1987/88)
- U.S. companies gaining share but very slowly
- 4M DRAM sampling in Q2
- Korea and Taiwan pushing for market access
- Toshiba ramping factories

ASIAN MARKET STATUS

- Total 1988 semiconductor consumption growth = > 35%
- Korean and Taiwanese currencies appreciating
- PC manufacturers not getting 1M DRAMs
- Japanese factories up and running

FORECAST





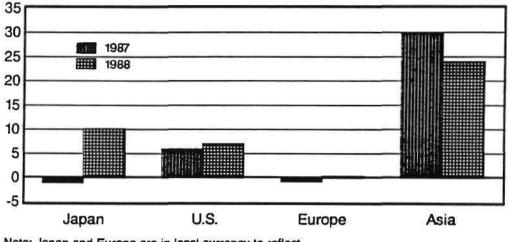
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1988 ELECTRONICS MARKETS

World by Region

Δ % Change, 1988 over 1987

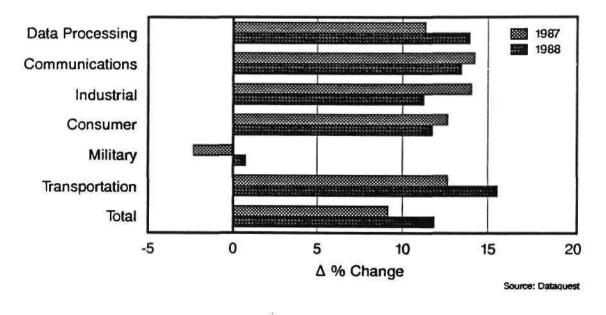


Note: Japan and Europe are in local currency to reflect appreciation of yen and ECU

Source: Dataquest

1988 ELECTRONICS MARKETS





ESTIMATED WORLDWIDE SEMICONDUCTOR CONSUMPTION

March 1987 Percent Change, U.S. Dollars

	1986	1987	1988
North America Japan Europe ROW	6.2% 43.7% 17.2% 52.6%	15.5% 15.9% 21.4% 35.5%	23.9% 19.0% 19.9% 30.3%
Total World	24.8%	18.6%	22.0% Source: Dataquest

ESTIMATED WORLDWIDE SEMICONDUCTOR CONSUMPTION

March 1988 Percent Change, U.S. Dollars				
	1986	1987	1988	
North America Japan Europe ROW	6.2% 43.7% 17.2% 53.9%	21.4% 19.4% 12.2% 62.1%	21.1% 20.7% 14.0% 31.5%	
Total World	24.9%	22.8%	21.1%	

Source: Dataquest

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HIGH-GROWTH PRODUCTS

(Estimated Percent Growth)

	1987	1988
Micros Total	33%	23%
MPUs Total	63%	42%
32 bit	228%	121%
MCUs Total	32%	16%
16 bit	13%	139%
MPRs	26%	24%
ASIC Total	22%	23%
Gate Arrays	34%	32%
PLDs	35%	40%
CBICs (Cell-Based ICs)	36%	37%
Linear ICs	17%	19%
Digital ICs	29%	25%

Source: Dataquest

SOME EMERGING MARKETS

- Chip sets
 - PC system logic
 - Graphics
 - Disk controller
 - Modem/fax
 - Telecom (LAN, ISDN)
 - Micro Channel
- Linear ASIC
- Smart power

SUMMARY

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WHO'S WINNING?

Warren E. Davis Vice President Semiconductor Industry Association

Mr. Davis is Vice President of the Semiconductor Industry Association (SIA), the trade organization that represents the American semiconductor industry. His focus has been international trade policy and more recently, policies and practices to enhance the industry's manufacturing competitiveness. Prior to joining the SIA, Mr. Davis taught courses at San Jose State University on international business finance and management of global enterprises. Earlier, he worked at Fairchild Camera and Instrument Corporation in a senior staff capacity, coordinating projects in strategic planning, international logistics and offshore manufacturing. Mr. Davis received a degree in Political Science from the University of Southern California and an M.S. degree in Business Administration from California State University at Sacramento. He has published several books and articles on the semiconductor industry.

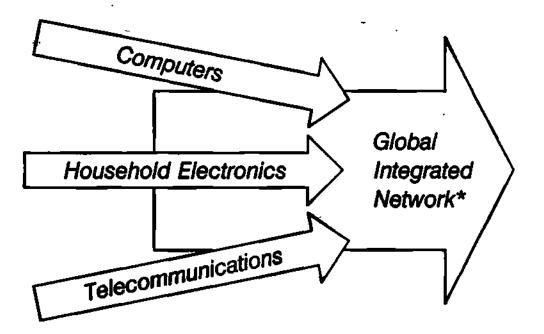
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WHO'S WINNING?

By

Warren Davis Vice President Semiconductor Industry Association

CONVERGENCE OF TECHNOLOGIES



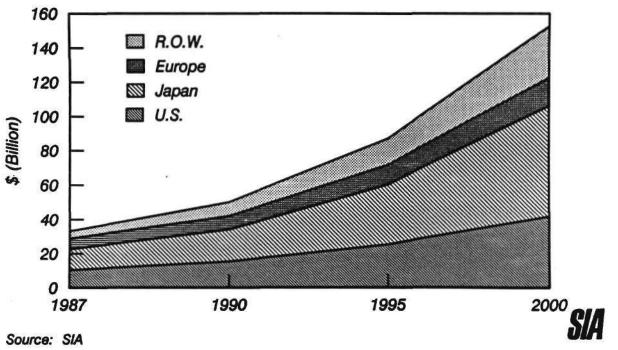
*Digital Broadband Serves All Users: Office, Household, Factory Source: SIA



SIA

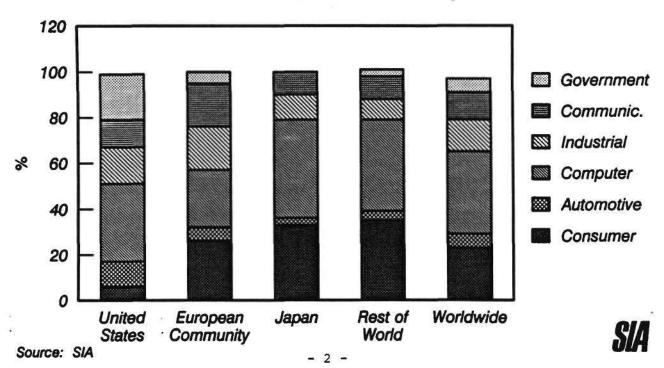
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SEMICONDUCTOR CONSUMPTION FORECAST BY GEOGRAPHIC MARKET



Source: SIA

SEMICONDUCTOR CONSUMPTION - 1986 BY END USE/GEOGRAPHIC MARKET



TERMS OF COMPETITION

- Governments Matter: GATT, Bilateral, National Policies
- New Manufacturing Paradigm: Flexible Response
- International Strategic Alliances

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- Innovation: Auto Fab, Supercomputer on a Chip
- Production Sharing: Silicon Foundries
- New Competitive Parameters: International Standards

SIA

WHO ARE THE PLAYERS?

- Japan
- United States
- Europe
- Rest of World

SIA

- 3 -

JAPAN STRATEGY

- Memory Thrust, Then Diversify to Semi-Custom and Custom
- Overseas Investment to Offset Yen Appreciation
- Heavy Dependence on U.S. Market
- Rapid Application of New Technologies
- Set National Standards, Then Use Marketpower to Impose Internationally

S/A

U.S. STRATEGY

- Trade Policy Leadership
- Manufacturing Development Collaboration
- Restructure: Mergers, "Virtual" Integration
- Bring Product Strengths to Bear on All High Volume Customer Segments

SIA

- 4 -

EUROPE STRATEGY

- Unification of EC 1991
- Cooperation Between National Champions
- More Aggressive in International Markets
- Leverage on Under-Utilized Market Base in Western Europe

REST OF WORLD STRATEGY

• Asian NICs (Korea, Taiwan):

- Graduated to Technology Intensive Capability
- Emulate Japan Financial Model for High Powered Growth
- Shifting Exports to Alternative Markets to Lessen Dependence on U.S. Market



SIA

- 5 -

REST OF WORLD STRATEGY (CONTINUED)

• Asian City States (Singapore, Hong Kong):

- Gravitational Pull from China
- Incentives for Foreign Investments with High Technological Content

REST OF WORLD STRATEGY (CONTINUED)

- Latin America (Brazil, Mexico):
 - Import Substitution Model
 - Limited Export Emphasis

SIA

S/A

REST OF WORLD STRATEGY (CONTINUED)

• China

- Seeks GATT Membership
- Stressing Lowest Cost Assembly and Silicon Foundry Services
- Gigantic Market/Technology Transfer Trade-Off

SIA

CRYSTAL BALL (1990s DIMLY PERCEIVED)

- Commodity IC Manufacturing Shift to Asian NICs, China
- New International Division of Labor Knowledge Worker Scarcity
- Global Information Services International Consortia in Triad

S/A

- 7 -

CRYSTAL BALL (CONTINUED)

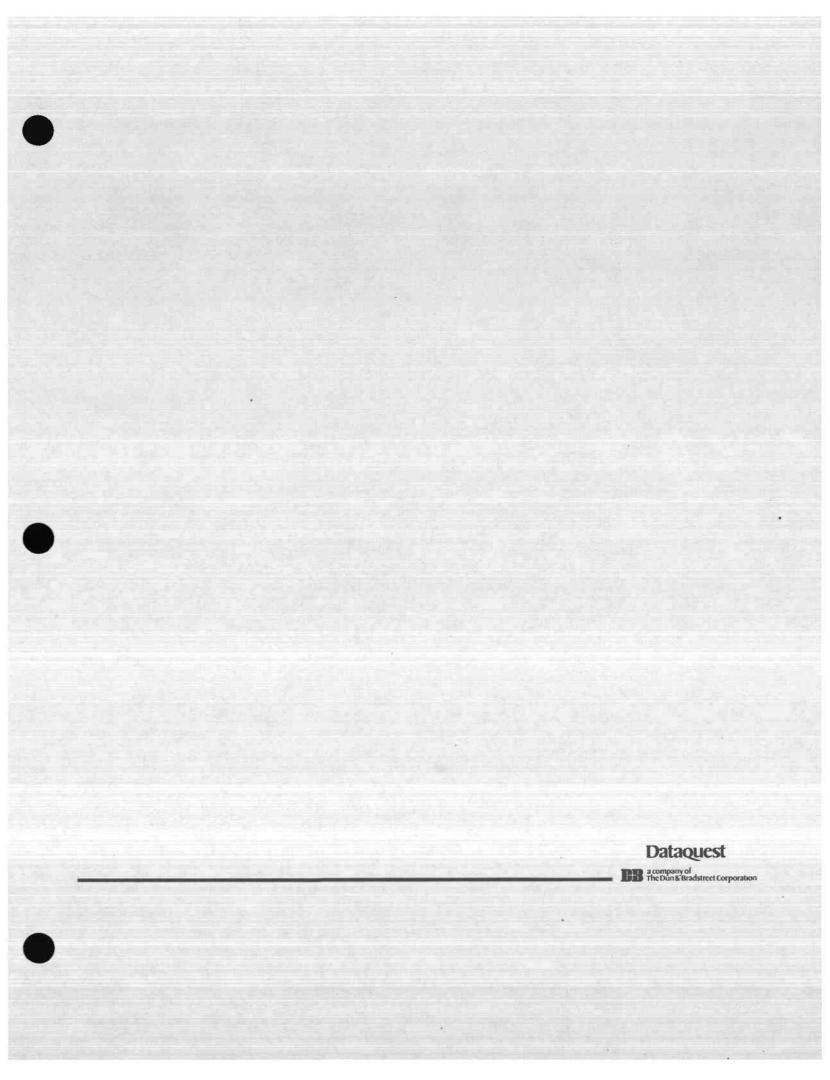
- R&D Internationalized
- Leading IC Companies Reorganized for Design Creativity, Production Flexibility, "Augmented Product" Marketing

SIA

20

 GATT Rules Negotiated for Establishment of International Standards in Electronics

- 8 -





INSEC'S ACTIVITIES IN THE PAST YEAR

Masato Nebashi President International Semiconductor Cooperation Center

Mr. Nebashi is President of the International Semiconductor Cooperation Center and of the New Media Development Association. Previously, he was Vice President of the Interactive Basic Information System Development Corporation. Earlier, he held a variety of administrative positions with IBM Japan, Ltd., the VLSI Technology Development Association, the Agency of Industrial Science and Technology, and MITI. Mr. Nebashi received a B.S. degree in Electrical Engineering from Nagoya University.

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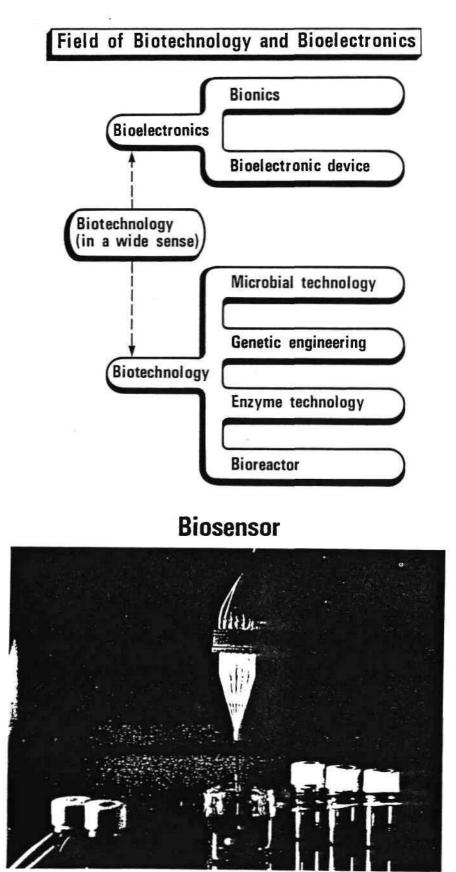


Atsuyoshi Ouchi Vice President of the Board and Representative Director NEC Corporation

Dr. Ouchi is Vice President of the Board and Representative Director of NEC Corporation. He has been with NEC since 1942 and has held a variety of senior-level management positions over the past 20 years. He is a member of several electronics organizations and has received many awards and commendations. He has also written books, two of which are entitled <u>Medical Electronic Circuits</u> and <u>Introduction to Microcomputers</u>. Dr. Ouchi graduated from the Electrical Engineering Department, Faculty of Technology, Tokyo Imperial University and received a B.E. degree. He also received a D.E. degree from the University of Tokyo for research in the applications of negative impedance converters.

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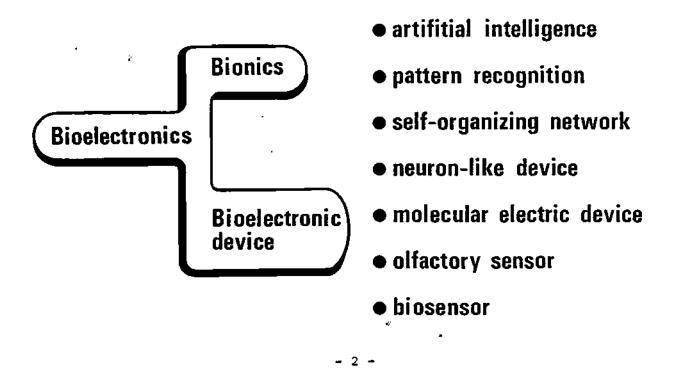
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Process of Technological Innovations

	I	II	Ш	IV
Technological	Batteries• Electromagnets	Vacuum Tubes Telecommunications	Semiconductor IC Computers Optical Communication	Molecular Devices• Quantum Effect Devices Artificial Intelligence
Innovations	Electricity Nuc Internal Combustion Jet Engines	Nuclear Power Jet Engines Robots	Nuclear Fusion Maglev Trains	
Materials	Smelted Metals	High Purity Materials Synthesized Materials	Semiconductors Functional Materials	High Tc Superconductors Biotechnology
Social Change	Industrial Revolution	Industrialization	Information Oriented Society	Software and Service Oriented Society



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STATUS OF JAPAN-U.S. SEMICONDUCTOR TRADE PROBLEMS

Yukio Honda Director, Industrial Electronics Division Machine and Information Industries Bureau Ministry of International Trade and Industry (MITI)

Mr. Honda is Director of the Industrial Electronics Division in the Ministry of International Trade and Industry (MITI). Since joining MITI in 1967, Mr. Honda has held a variety of positions including Technology Deputy Director of the Ocean Department Office, Agency of Natural Resources, and Information Industries Bureau; and Director of the Space Industry Office, Machine and Information Industries Bureau. Prior to being appointed to his present position, Mr. Honda was temporarily transferred to the Technological University of Nagaka as a professor for two years.

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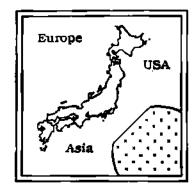


THE ASIAN AGE IS COMING

Tom Wang Director, Asian Components Group Associate Director Asian Semiconductor and Electronics Technology Service Dataquest Incorporated

Mr. Wang is Director of Dataquest's Asian Components Group and Associate Director of the Asian Semiconductor and Electronics Technology Service. He is responsible for strategic research of the semiconductor and electronics industries of Korea, Taiwan, Hong Kong, Singapore, China, India, and other parts of Asia. Prior to joining Dataquest, Mr. Wang was employed at National Semiconductor as Applications Manager and Market Research Manager. Earlier, he worked as a Project Leader designing mainframes, personal computers, and disk drive controllers at several systems houses. He has also taught graduate courses at San Jose State University. Mr. Wang received B.S.E.E. and M.S.E.E. degrees from National Cheung Kung University in Taiwan, an M.S.E.E. degree from San Jose State University, and an M.B.A. degree from Golden Gate University in San Francisco. He has also completed courses toward a Ph.D at the University of California at Berkeley. In addition, he has published a textbook and 25 technical papers and is fluent in Mandarin, Cantonese, and Taiwanese.

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Japan's New International Role: Competition and Cooperation

THE ASIAN AGE IS COMING

TOM WANG

Associate Director Asian Semiconductor and Electronics Technology Service Dataquest Incorporated

AGENDA

- Asian semiconductor industry outlook
- Semiconductor manufacturers in Asia
- Key issues in 1988
- Summary and conclusion

ASIAN SEMICONDUCTOR INDUSTRY OUTLOOK

- Market growing drastically
- Competition increasing significantly
- Manufacturing moving offshore
- Business opportunities growing



SEMICONDUCTOR CONSUMPTION

(Millions of U.S. Dollars)

	1985	1986	1987*
South Korea Taiwan Hong Kong Singapore	\$436 \$496 \$334 \$271	\$624 \$694 \$478 \$350	\$1,101 \$1,171 \$806 \$590
* Estimated		•	

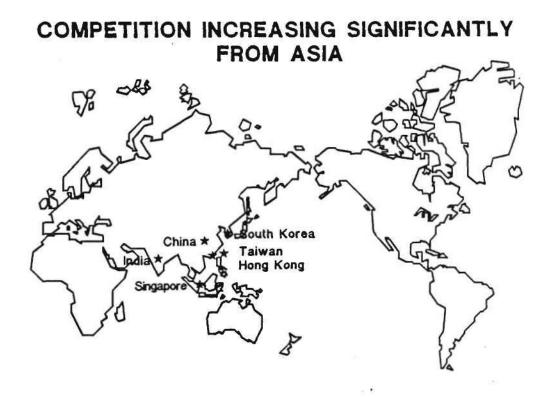
ESTIMATED SEMICONDUCTOR CONSUMPTION

(Billions of U.S. Dollars)

	1986	1987	1988	1992
ROW	\$ [°] 2.9	\$ 4.9	\$ 6.3	\$1 1.8
Europe	\$ 5.5	\$ 6.8	\$ 7.5	\$11.9
Japan	\$12.4	\$14.5	\$17.4	\$27.5
United States	\$10.2	\$12.5	\$14.2	\$20.2

Source: Dataquest

Source: Dataquest



COMPETITION FROM THE 4 "Cs"

- Consumers
- Computers
- Communications
- Semi-Conductors

SEMICONDUCTOR PRODUCTION

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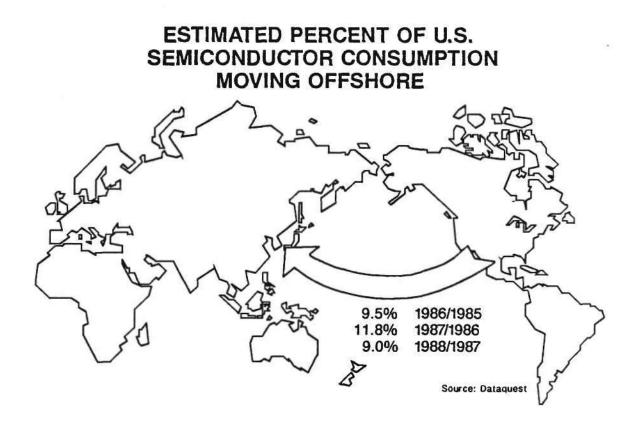
(Millions of U.S. Dollars)

Company	1986	1987*	Growth Rate
Samsung GoldStar KEC UMC	\$170 \$48 \$50 \$68	\$317 \$68 \$78 \$90	86.5% 41.7% 56.0% 32.4%
* Estimated			Source: Dataquest

COMPETITION IN MEMORY CHIPS

	Samsung	GoldStar	Hyundai
1M DRAM Mass Production Wafer Size Design Rule	2Q '88 6" 1.2µm	3Q '88 6" 1.2µm	4Q '88 6" 1.2µm
Capacity (Wafer/Day) 4M DRAM	100-600	600	300
Mass Production	3Q '89	3Q '89	3Q '89

Source: Dataquest



MAIN REASONS FOR MOVING OFFSHORE

Before:

Low labor cost

Now:

Low labor cost + superior talent + closeness to market

FUNCTIONS OF OFFSHORE FACILITY

Before:

Assembly and testing

Now:

Design + fabrication + assembly and testing

OPPORTUNITY

Economic Growth Real GDP Growth Rates (%)

	1986	1987*	1988
Taiwan	11.0	10.1	7.3
South Korea	12.4	11.1	8.0
Hong Kong	11.0	12.6	8.9
Singapore	1.9	6.9	5.5
China	8.0	9.7	9.1
Japan	2.4	2.5	3.0
United States	2.2	3.1	2.8
Europe	2.5	2.2	2.0
* Estimated			

Source: Dataquest

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OPPORTUNITY

High-Technology Business Opportunities

- Semiconductor manufacturing
- Semiconductor equipment and materials manufacturing
- Systems manufacturing
- Financial opportunities

SEMICONDUCTOR MANUFACTURERS IN ASIA

SEMICONDUCTOR MANUFACTURERS -SOUTH KOREA

- Samsung
- Goldstar
- Hyundai
- Daewoo
- KEC

SAMSUNG

Sales	\$316 million	Sales Channels	Asia - agents Europe - agents
Rank	22		U.S reps/dist'rs. Big OEMers - direct
Products	256K DRAMs - 25%		-
	64K DRAMs - 20%	New Products	1M DRAMs
	CMOS Logic - 25%		512K EPROMs
-	Linear (Cs - 10%		256K SRAMs
	Transistors - 20%		CTV/VTR ICs
			Codec/Combo
Capacity	4" BIP - 360,000		
(Wafers/year)	5* MOS - 600,000		
•	6" MOS - 200,000		

Source: Descuelt

GOLDSTAR

Sales	\$69 million	Sales Channels	Asia - agents Europe - agents
Products	TTL - 30%		U.S reps/dist'rs.
	Gate arrays - 20% 74HC/HCT - 10%		Big OEMers - direct
	Hybrids - 30%	New Products	1M DRAMs
	Linear ICs - 10%		256K DRAMs
			2Kx8 SRAMs
Capacity	4" BIP - 200,000		8Kx8 SRAMs
(Waters/year)	5" MOS - 250,000		Fast TTLs

Source: Oathquest

HYUNDAI

- Sales \$40 million Products 256K DRAMs - 50% 16K SRAMs - 15% Mask ROMs - 15% MPUs - 10% Others - 10%
- Capacity 5* MOS 120,000 (Wafers/year) 6* MOS - 480,000

Sales Channels Asia - agents Europe - agents U.S. - reps/dist^{*}rs. Big OEMers - direct

New Products

1M DRAMs

Source: Determent

DAEWOO

Sales Products	\$10 million Audio ICs - 50% Custom - 50%	Sales Channels	Asia - agents Europe - agents U.S reps/dist'rs. Big OEMers - direct
Capacity (Wafers/year)	4" BIP - 90,000	New Products	ICs for PC ICs for telecom

Source: Detabauent

KEC

Sales	\$78 million	Sales Channels	Domestic - direct International -
Products	Transistors - 70% Linear ICs - 30%		through Toshiba
Capacity (Wafers/year)	4" BIP - 200,000	New Products	Linear ICs

Source: Detectuest

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SEMICONDUCTOR MANUFACTURERS - TAIWAN

- UMC
- ERSO
- TSMC
- Rectron
- Fine
- Others

UNITED MICROELECTRONICS CORPORATION (UMC)

Sales	\$90 million	Sales Channels	U.S reps./dist'rs.
Rank	50	New Products	PS/2 Model 30 Chip Set SCSI Chips
Products	Microcomponent &		Modem Chip Set
	Memory ICs - 36.7%		Data Communication Chips
	Consumer ICs - 26.3%		
	Telephone ICs - 18.4%	•	
	Custom ICs - 18.6%		
Capacity	4" MOS - 490,000		
(Wafers/Year)	6" MOS - 120,000		
	(Available Nov. 1988)		

Source: Determent

ELECTRONICS RESEARCH AND SERVICE ORGANIZATION (ERSO)

Sales

\$30 million

Products

PC Chip Set Consumer ICs Custom ICs Combo

Source: Onteques

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY (TSMC)

Product

Foundry

Capacity (Wafers/Year) Fab I - 6" MOS - 120,000 Fab II - 6" CMOS - 360,000 (Available 1989)

Source: Oetacuest

SEMICONDUCTOR MANUFACTURERS -HONG KONG

- Hua Ko
- Elcap
- RCL

HUA KO

Products

Consumer ICs Custom ICs

Capacity (Wafers/Year) 4" MOS - 60,000

Source: Ostaquest

ELCAP

Products

EL6116 74HC/HCT Series Consumer ICs Custom ICs Gate Arrays (up to 3,000 gates) Packaging Service

Capacity (Wafers/Year) 4" CMOS - 60,000

Source: Delinquest

SEMICONDUCTOR MANUFACTURERS -SINGAPORE

- SGS-Thomson*
- HP
- Chartered

* Only SGS-Thomson is in production now

SGS-THOMSON

Products

EPROMs Power Transistors Consumer ICs Microcomponent ICs

Capacity (Wafers/Year) 5" - 360,000

Source: Deleguest

CHARTERED SEMICONDUCTOR

6" wafer fab will be finished in early 1989.

SEMICONDUCTOR MANUFACTURERS -CHINA

- Wuxi
- BETF
- Beijing Semiconductor Factories #3, 6, and 109
- Shanghai #5, 7, 14, and 19 Radio Components Factory
- Li shan
- Others

WUXI MICROELECTRONICS COMPLEX

Products

- Toshiba 5-chip set @ 5 million units/yr.
- Discrete semiconductor components (mostly for consumer electronics ar plications)
- 64K memories, 4-bit MCUs, and telecom devices in small quantities

WUXI MICROELECTRONICS COMPLEX

Sales channels

• Not well developed, manufacturers almost entirely under exclusive agreement

Trends

- Capable of 3-micron technology
- Most production is of 4-inch wafers
- Future emphasis on telecom ICs, converters, and op amps

KEY ISSUES IN 1988

KEY POSITIVE ISSUES IN 1988

- Government support
- Capital spending
- Partnerships/alliances
- Local demand
- Yen appreciation
- Manufacturing move to Asia
- GNP growth
- Technology perception
- Emerging market

KEY NEGATIVE ISSUES IN 1988

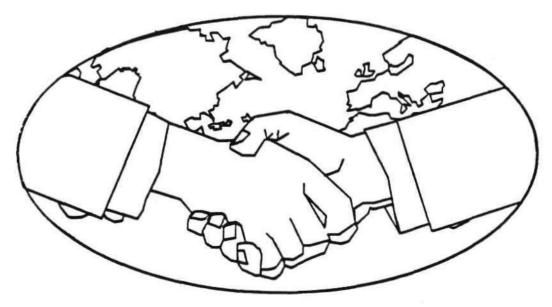
- Currency value appreciation
- Protectionism
- Competition from non-NICs
- U.S.-dependent industry

SUMMARY

- Asian semiconductor industry's worldwide influence will grow
- Asia will be worldwide leader in semiconductor consumption growth
- South Korea will be a significant DRAM producer
- Taiwan will become a major ASIC design center

Source: Datacuest





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ANALYSIS OF EUROPEAN ELECTRONICS TECHNOLOGY

Jürgen Knorr Senior Vice President Components Group Semiconductor Division Siemens AG

Mr. Knorr is Senior Vice President of the Components Group in the Semiconductor Division at Siemens AG. He has been with Siemens since 1957. Earlier positions have included corporate management for the Electrical Installation Equipment Division, the Lighting Systems Division, the Automotive Electronic Components Division, and the Electronics Contracting and System Business Division, and a variety of other management and engineering positions. Mr. Knorr received a Dipl.-Ing. from the Technische Universität Berlin, where he majored in Mathematics and Electrical Engineering.

5

Dataguest Incorporated JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE April 11-12, 1988 Tokyo, Japan As a member of Siemens corporation I feel (slide 1) honoured to give a presentation analysing European Electronics Technology. It is not an easy task to speak as a citizen of <u>one</u> European country and as a manager of <u>one</u> European company on behalf of total Europe. So you will understand that I cannot avoid answering some of the questions from a somewhat one-sided point of view, and that I will have to extrapolate certain lines of view. I nevertheless hope to be able to present to you a worthwhile overview on the trends of micro-electronics development in Europe. Last not least this might be the case because of inputs to my speech representing the opinions of the EECA, of which I am the vice-president.

Let us first ask the question:

What do we mean by the term "Europe"? (slide 2) Well - perhaps you know "Rothenburg ob der Tauber", (slide 2a) a romantic old town in the heart of Germany. It is one town out of many European towns with a long history and a past background of richness, based on handcraft and trade. This town is completely surrounded by a wall, for it used to be a state of its own. Insofar this town is representative for peculiarities which characterize all of Europe: Europe is a conglomeration of many countries defending their individuality, their languages und their cultures. Hence Europe's technologies are diverse and driven by many kinds of creativities.

- 1 -

The Europe which I am concerned with in my (slide 3) presentation comprises only a small section of the map of Europe *). It is the European Economic Community, and because I am going to talk about electronics, only a group of eight countries of the European Community with major electronics industries is concerned: Belgium, Netherlands, Luxemburg, Federal Republic of Germany, Italy, Spain, France and Great Britain.

On this small, densely populated portion of Europe (slide 3a) 7 different languages are spoken, and the economic regions are separated by borders, duty regulations and different technical standards. Major mergers of industrial firms are made difficult or even prevented by anti-trust laws. Some of these barriers such as duty regulations are not expected to disappear until 1992, giving way also to more uniform standards, and thereby paving the way to a completion of the internal market in Europe.

To illustrate the current situation of Europe, I would like to introduce some figures relating Europe within the triad. Compared with Japan there are 2.4 as many people living on a 5 x larger area in Europe, which means that in Japan there are double as many people per sq.km. In the USA the density of population is only 1/5 of that of Europe. The industrial production/capita is in comparison lower both to the USA (0.8 x) and Japan (0.6 x). This again

*) which extends up to the right edge of the slide.

is explained by substantial differences of the industry structures among the different member countries in the EEC. West-Germany's industrial production/capita e.g. equals the one of Japan and is higher than the one in the US. But, above all, Europe's production in Electrical Engineering & Electronics/capita totals only to 30 % compared to Japan and only to 60 % of that of the USA.

This shows today's predominance of the US and Japan in the Electrical Engineering & Electronics sector. Another way to explain these relations is to look at the production values and trade figures in the 3 regions, as shown in: (slide 4) Europe imports more IC's than it produces - I will present more detailed figures later - and its IC-production only amounts to about 20 % of the IC production of Japan or the US, a figure which sums up to only 11 % of the world production.

On the other hand the IC consumption of Europe (slide 4a) is only 50 % of that of the USA and 40 % of Japan. In fact Europe imports 64 % of its IC consumption while Japan imports only 8 % and the US only 19 %; that means, that both countries are mainly export-oriented.

This indicates that Europe has recognized at a late stage the importance of building up its own microelectronics development and production.

Let us concern ourselves for a moment with the question: How did the Europeans get into this unsatisfactory situation? -3 -

After all - Europe has a remarkable tradition of (slide 5) achievements in the historical development of semiconductors. Major physical theories, leading to decisive insights into the composition and behaviour of solid-state materials, paving the way into semiconductor technology, had their cradle in Europe. Names such as Rutherford, Niels Bohr, Sommerfeld and Heisenberg are representative for this period of time. Cognition of the material properties of germanium and silicon as well as the discovery of III/Vcompounds were achieved in Europe since the early thirties, to a significant extent also by scientists working for Siemens, such as Schottky and Welker.

Even the development of today's processes for the production of semiconductor materials, including crystal pulling and refining, is largely based upon European patents, some of them coming directly from Siemens. However, since the invention of the transistor in the Bell-laboratories (1948) many development and applications of scientific findings including integrated circuit technology were taken over by the USA. Japan later succeeded to develop IC manufacturing technologies to remarkable perfection.

Since then Europe fell behind in the development of microelectronics. There are several reasons for this, one of them being the great successes of Europe in (slide 5a) conventional electrical engineering with a special focus and strength in mechanical engineering, the automotive industry and communications.

Far more critical is that we didn't realize the fact that the share of electronics increased from 30 % of a small volume to 65 % of a much bigger volume.

(slide 6) Apart from these facts there are further considerations making a direct comparison of microelectronics development in Europe, Japan and USA difficult: Taking a look at the IC-markets by applications (1987) - here you see a comparison of Japan and Western Europe reveals great differences in emphasis: While in Japan the entertainment- and consumer industry play a dominant role (50 % of the electronic market) -in the USA it would be data processing - in Europe the application sectors automotive-, industrial- and telecommunication - electronics prevail, together amounting to almost 50 % of the total electronic application market. These markets used to have a rather moderate rate of growth in the past, but are now forecasted to have an above-average market growth rate of between 18 and 23 % p.a. in the mineties! Looking at the average IC-usage in these sectors (slide 6a) of application - the parameter being the value of ICs used divided by the equipment value - another interesting characteristic of the European microelectronics market

shows up:

- 5 -

On average, in data processing and entertainment the IC-share in value is more than twice as big than in those sectors, in which Europe has its strength: automotive-, industry- and telecommunications electronics.

These different application areas within the triad (slide 7) have necessarily led to substantial differences in the kind of ICs mainly produced, as is shown by the next slide: (slide 7a)

In the area of non-standard-ICs, Europe's IC production share is almost equivalent to that of Japan and USA, for example because the consumption of ASICs in telecom- and industrial electronics applications is large. On the other hand, the standard-IC-business has traditionally been overwhelmingly dominated by the USA and Japan. Which conclusion do we draw from this analysis?

- The tradionally important market segments like the automotive industry, mechanical engineering and communications will remain important market segments in the age of microelectronics.
- Corresponding to its product structure Europe is relatively strong in the important field of NON-Standard IC's.
- 3. Europe has a need to make up for the development and manufacturing of Standard IC's which are at the same time a "locomotive" for mass production. Now, what should the strategies of Europe be in the future? Permit me to now present the view of Siemens Corporation,

as I am best acquainted with the strategy of this company. -6 -

Siemens - a big company in the field of Electrical (slide 8) Engineering & Electronics - worldwide employs 360,000 people with sales of 28.5 billion US \$. It is divided into 7 groups being represented in 123 countries: Components Energy and Automation Electrical Installations and Automotive Communication and Information Systems KWU (Power Plants) Medical Engineering Telecommunication Networks and Security Systems (slide 8a) Siemens has concentrated on 3 major strategic areas: Network of the future Office of the future Factory of the future In all these strategic growth sectors microelectronics is the key technology. This is the reason why in 1984 we started a (slide 9) corporate project, named MEGA. We have set ourselves the objective, by means of this project, to substantially reduce the lead of our competitors in this global business. The key products of the MEGA Project are (slide 9a) the 1M DRAM, the 4M DRAM and Logic IC's, which are developed in the adequate technologies.

- 7 -

The project included

- o the hiring and training of a highly qualified developmentand manufacturing 'team
- o the setup and the installation of equipment for development and production halls with a cleanroom class of 10 and
- o the installation of design systems with data banks as well as CIM Systems.

After two years the cleanrooms had been completed and the production of the pilot and manufacturing lines started. 2 of those most modern halls are shown in: (slide 10) There is a common cleaned air supply for both halls. A cross section of the hall is shown in (slide 10a) By an optimized technology a clean room class of better than 10 was achieved.

The filter efficiency is 99.99997 %.

The hall offers an effective area of about 2000 sq.m In 1984, the catch-up race started; until now we have noticeably reduced the gap to our leading competitors. Landmarks on this way are:

o We are the only European manufacturer (slide 11) offering 1M DRAMs of own production on the market.

o 4M DRAM development is well within schedule.

We have an acknowledged position in the (slide 11a)
 leading group of logic circuit manufacturers.

- 8 -

As an example I show you a photo of a 4M DRAM-sample and its specification. (slides 12 and 12a) These are the short-term goals the Siemens corporation has set for itself. We are confident to achieve them.

Let me return to the point of view from the European microelectronics industry, asking the question: Which road will microelectronics pursue in the years to come?

- We shall carefully try, not to let any new technological or design gaps come about.
- In defining new objectives, we shall substantially take the economic particularities of Europe into consideration.

These I will briefly characterize by two illustrations:

- The FRG is burdened by having (slide 13)
 the worldwide highest labor costs, due to its
 demanding social security system and low working hours.
- The increase of average production costs per unit
 is high in Europe. (slide 13a)

It is highest in France and Great Britain. Our common European objective must therefore be (slide 14) o to improve the economy of microelectronics,

which means reducing the costs per function.

- 9 -

 by means of design-cleverness to get to fault-free, ingenious circuits designs in shorter time and thereby more economically.

to achieve a maximum of production quality and
 flexibility through "intelligent" production lines,
 making use of CIM, robots and efficient equipment.

These objectives are more important to us than a reduction of the size of circuit structures at any cost. To achieve them will require enormous resources.

As Europeans we can pursue these objectives (slide 14a) successfully only by strengthening our own capabilities, through closer cooperation within semiconductor industries, by involving the equipment manufacturers and by cooperating with the materials producers. The completion of the internal market in Europe which is supposed to be realized by 1992, as I already mentioned, will be instrumental in accomplishing this purpose.

In addition the governments have agreed on common programs as ESPRIT and EUREKA, which fulfill the above goals and which are very successful.

The newest one is JESSI (Joint European Submicron Silicon) which will promote the European microelectronics manufacturers through coordination of activities and common initiatives. I am sure, Siemens and all other ambitious European semiconductor manufacturers will cope with the challenge in microelectronics and close the gap to global competitors during the nineties.

SSO 84 uropean Electronics Technology

1

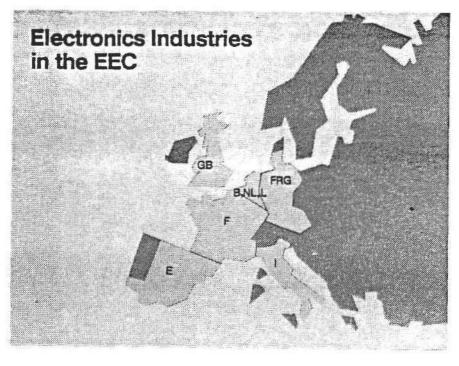
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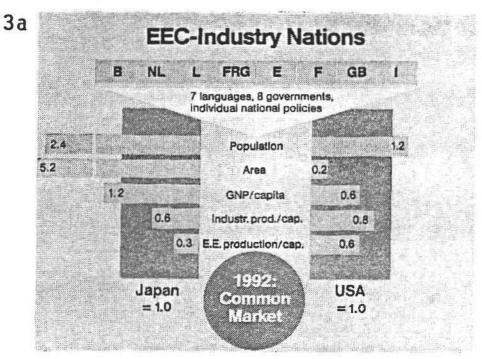
- 11 -



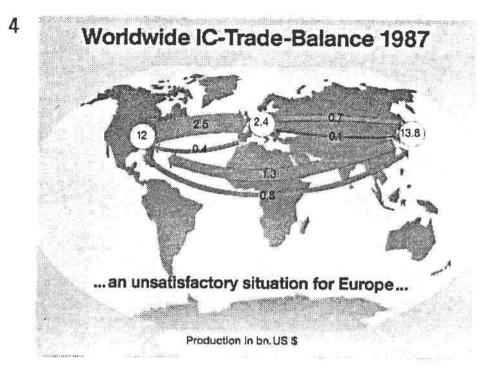
- 12 -

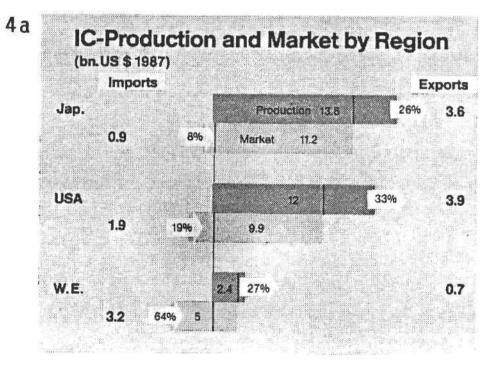
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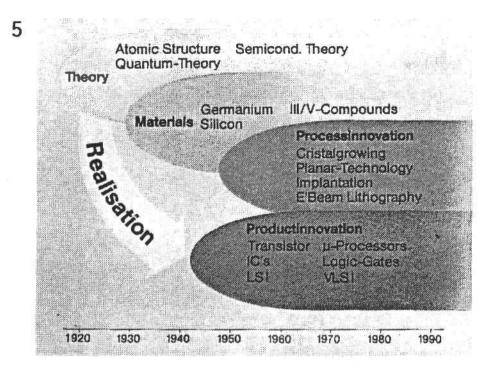


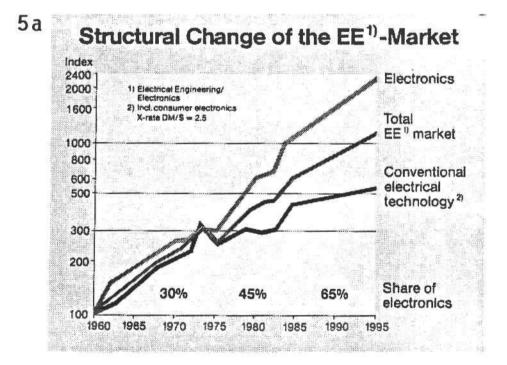
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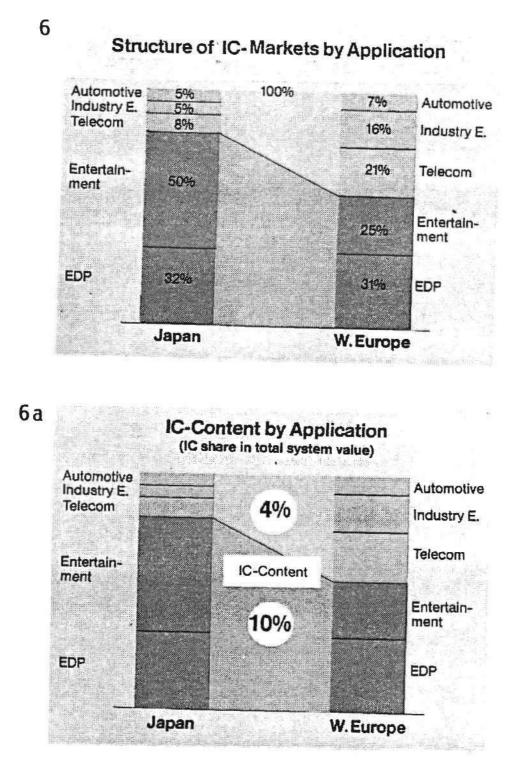


- 14 -

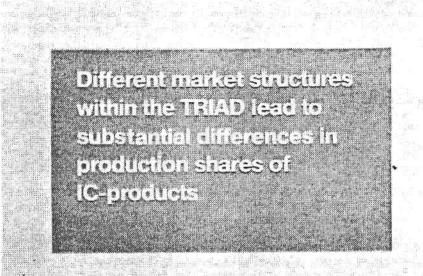




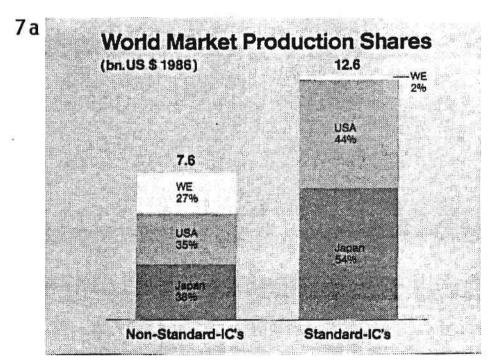
- 15 -



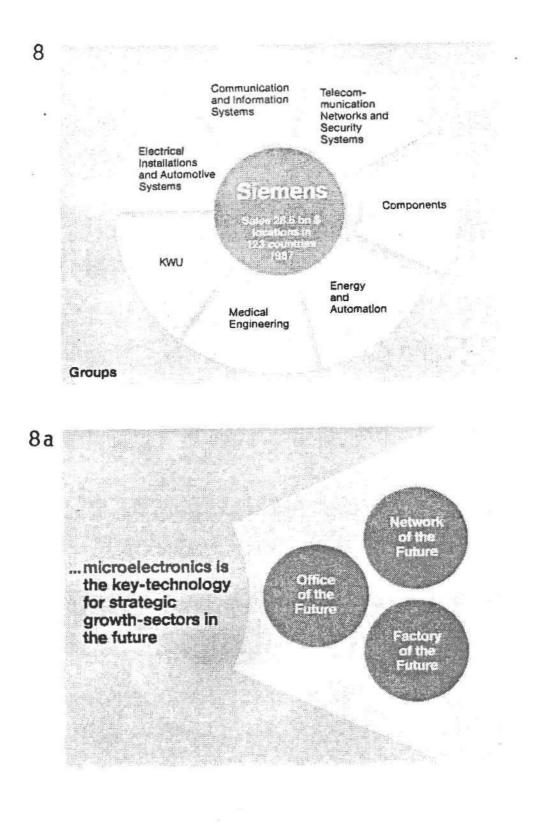
- 16 -



7



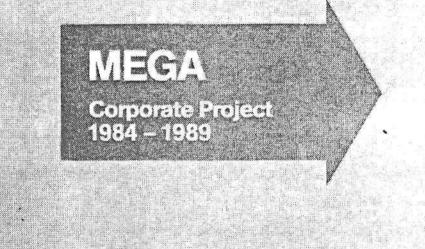
- 17 -



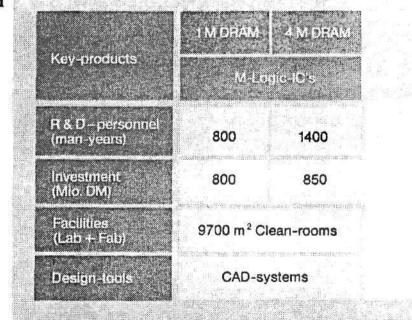
- 18 -

9

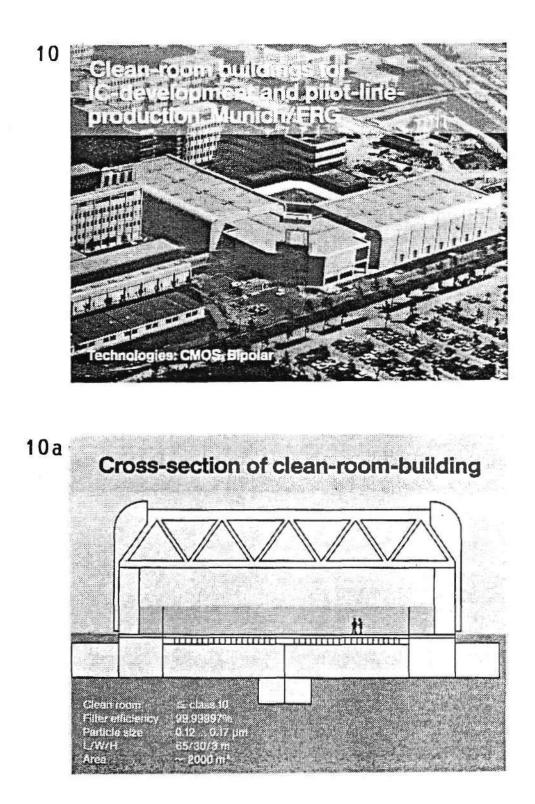
... closing the technology-and designgap in microelectronics:





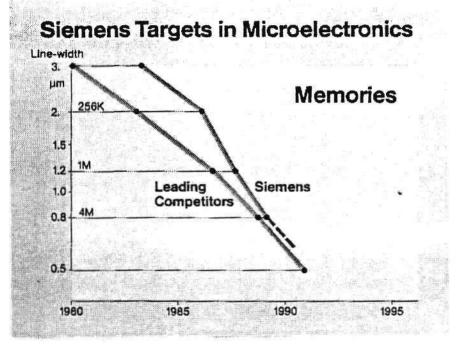


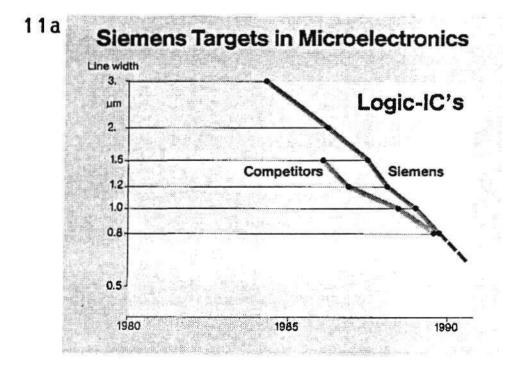
- 19 -

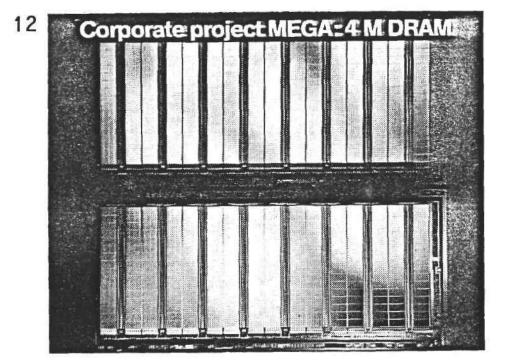


- 20 -

11





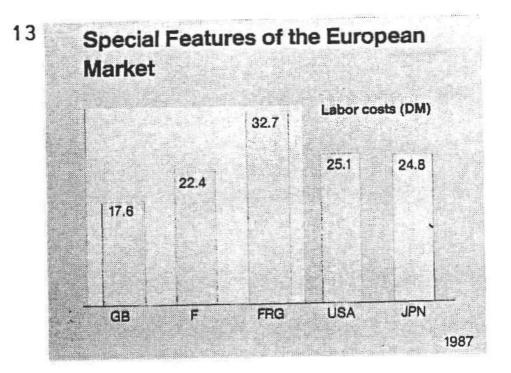


12

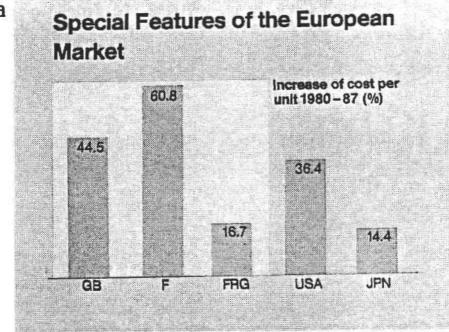
12a

Organization	4M×1 and 1M×4
Technology	Advanced twin-tub CMOS 0.9 µm, FOBIC-cell, trench
Cell size	$2.3 \times 4.6 = 10.58 \mu m^2$
Chip size	6.5 × 14.05 = 91.3 mm ²
Access/Cycle	70/150 ns at 5 V typical
Static column	45 ns cycle time at 5V typical
Package	SOJ 350 mil 26/20
Modes	Static column, fast page mode (fuse option)
Test mode	8 bit, acc. to JEDEC

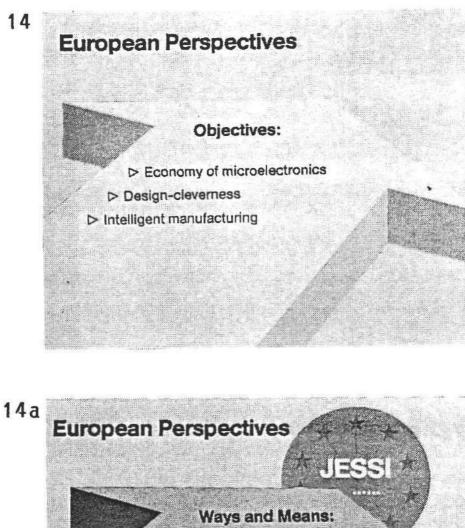
- 22 -



13a

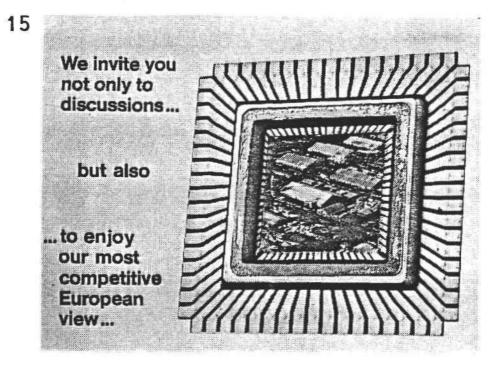


- 23 -



JESS JESS Ways and Means: • Strengthening of own capabilities • Coser cooperation within semiconductor industries

- 24 -





- 25 -

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SUBMICRON TECHNOLOGY: MARKET IMPACTS

Hiroyuki Mizuno Managing Director, Member of the Board Matsushita Electric Industrial Co., Ltd.

Dr. Mizuno is Managing Director and member of the board at Matsushita Electric Industrial Co., Ltd. He has worked for Matsushita since 1952, specializing in the research and development of silicon and GaAs devices. During his career at Matsushita, he has held a variety of management positions in both Matsushita Electronics Corporation (MEC), a subsidiary company specialized in making active electronic components, and Matsushita Electric Industrial Co., Ltd. (MEI). Dr. Mizuno received a B.S. degree in Physics and a Ph.D. degree from Kyoto University. He also studied at the University of Illinois for two years.

> Dataquest Incorporated JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE April 11-12, 1988 Tokyo, Japan

> > \$

IMPACT OF SUBMICRON TECHNOLOGY ON MARKET

Panasonic

WHY 16Mb DRAM ?

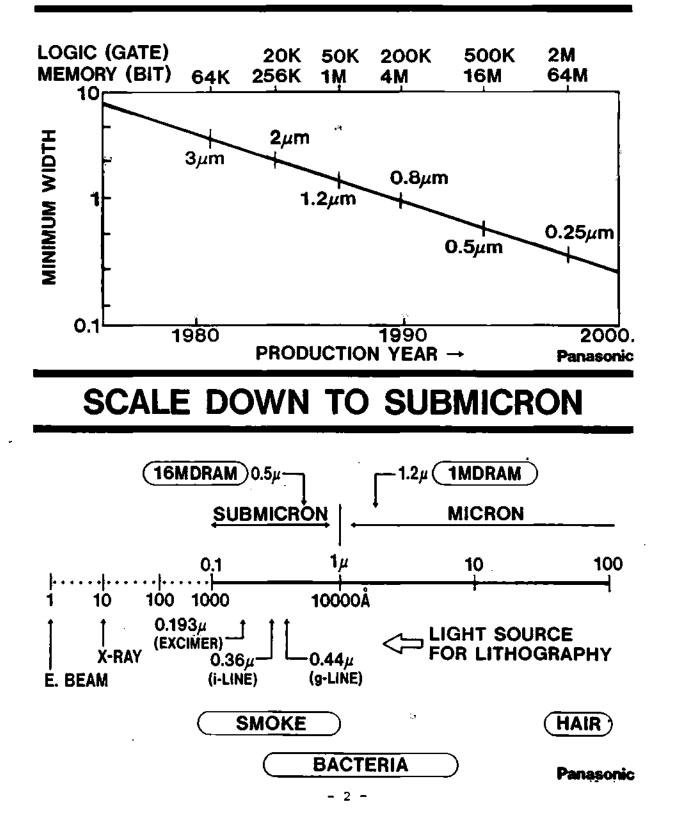
■DRAM IS A VEHICLE OF TECHNOLOGY

SUBMICRON ERA

Panasonic

- 1 -

TREND OF SUBMICRON TECHNOLOGY



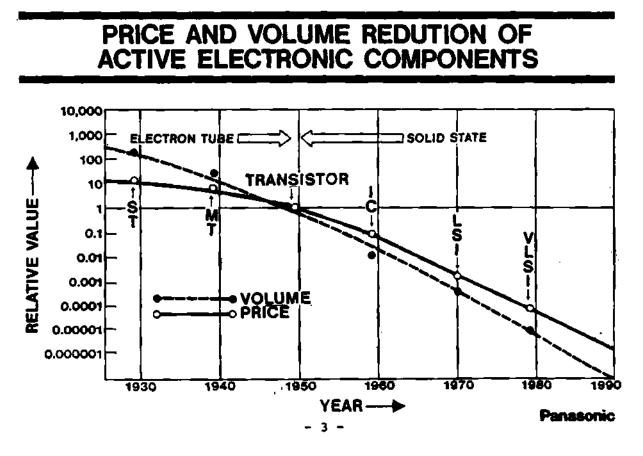
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IMPACT OF SUBMICRON TECHNOLOGY ON ELECTRONICS

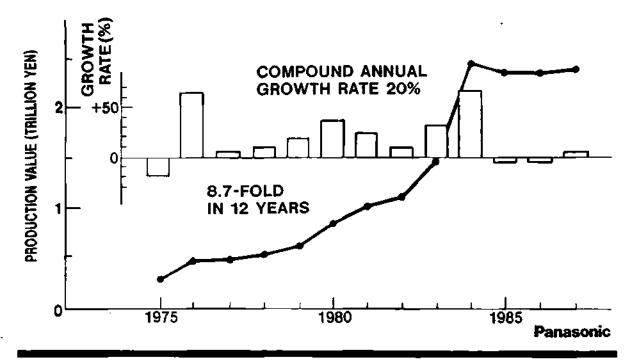
■ SO FAR, WHAT HAPPENED ?

■THEN, WHAT WILL BE ?

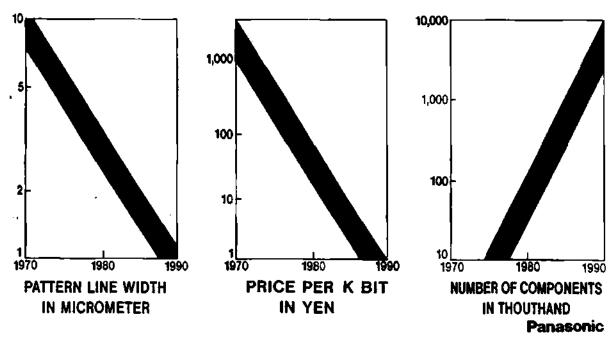
Panasonic



JAPAN'S SEMICONDUCTOR PRODUCTION



TREND OF MOS MEMORY



- 4 -

TOWARD HOME INTELLIGENCE

TECHNOLOGY

■INFRASTRUCTURE

- OPTICAL FIBER NETWORK
- SATELLITE SYSTEM

Panasonic

THEME

ALL INNOVATION SHOULD FINALLY BURST IN HOME APPLICATION MARKET

- 5 -

Panasonic

IMPACT OF SUBMICRON TECHNOLOGY -1

COMBINATION OF HOME ELECTRONICS AND COMPUTER

•INTERACTIVE •BETTER INTERFACE hidden/domesticate/AI COMPUTER •HOUSE KEEPING/NURSING ROBOT speech/image recognition

Panasonic

IMPACT OF SUBMICRON TECHNOLOGY -2

COMBINATION OF HOME ELECTRONICS AND COMMUNICATION

- HOME BUS (HA) → ISDN information socket
- STRONGER LINK TO SOCIETY
- MAN-TO-MAN ENTERTAINMENT, INFORMATION EDUCATION, MEDICAL CARE especially of the aged

- 6 -

Panasonic

CRITERIA OF HOME ELECTRONICS

- **EASY TO HANDLE**
- ■HIGH QUALITY

■VOLUME PRODUCTION

LOW COST

Panasonic

THEN, WHAT WILL BE ?

■HIGH DEFINITION SYSTEMS

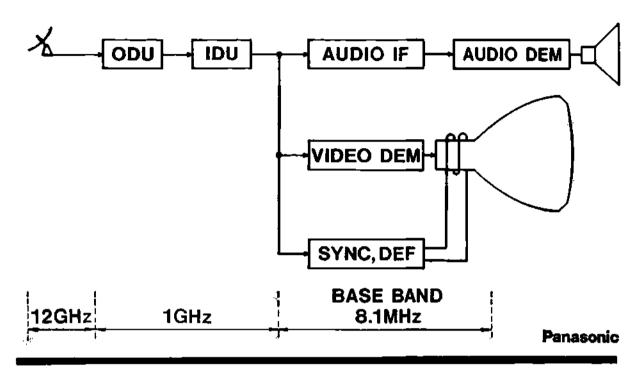
CD-I

■OTHER IMPACTS

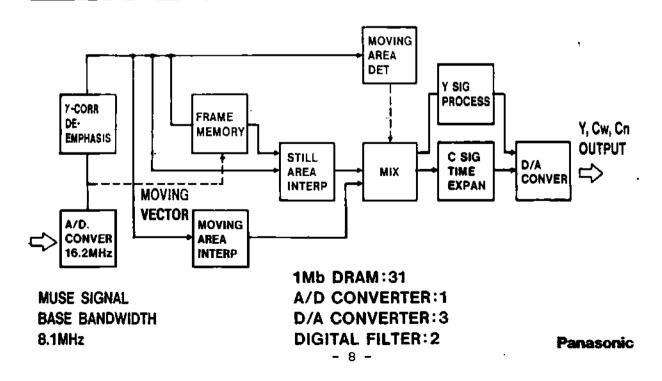
Panasonic

7 -

BLOCK DIAGRAM OF HD TV



VIDEO DEMODULATION OF HDTV (MUSE)



CD-I DIVERSITY

AUDIO

- (LEVEL) (QUALITY)
- •CD-PCM ULTRA HIFI
- •CD-I ADPCM

_	Α	LP
•	B ·	FM
	C	AM

■<u>VIDEO</u>

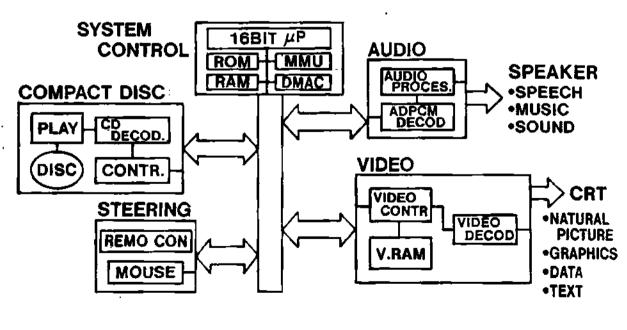
NATURAL PICTURE
 GRAPHICS
 RGB
 CLUT 8
 RLC (ANIMATION)

■INTERACTIVE

SYNTHESIZE

Panasonic

CD-1 BLOCK DIAGRAM



Panasonic

9

KEY SEMICONDUCTOR DEVICES IN CD-I

PROCESSORS:

16 bit μC→system control.
Graphic processor
DSP→audio processor
8-bit/4-bit microcontrollers→mecha./remote

MEMORIES:

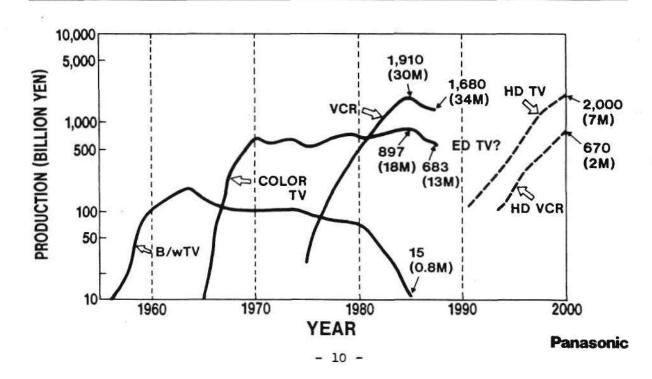
8Mb DRAM→video RAM, main memory 3Mb Mask ROM→system control Chinese chara. dictionary

GATE ARRAYS:

90K gates→video decoder/controller AD PCM decoder

Panasonic

JAPAN'S PRODUCTION OF TV & VCR



FURTHER····

COMBINING STUDIES

OF ORGANISM WITH

VLSI TECHNOLOGY

Panasonic

DNA & CELL

■GENE → DESIGN BOOK OF ORGANISM

S

Ρ

S

P

С

S

MAGNETIZATION

FILM BASE

DEOXYRIBO NUCLEIC ACID

Ρ

G

S

P PHOSPHATE: SSUGAR BASE

P

■RECOMBINANT DNA→STRUCTURING A DEVICE ■DNA IN A CELL→CUSTOM ROM IN A MICROCOMPUTER

Panasonic

- 11 -

CONCLUSIONS

SUBMICRON TECHNOLOGY OPENS THE GATE TO NEW ERA OF HOME ELECTRONICS.

- HOME ELECTRONICS WILL CONSUME MORE MEMORIES AND MICROCOMPUTERS.
- MERGENCE OF HOME ELECTRONICS COMPUTER, AND COMMUNICATION WILL BEGIN SOON.

■NEXT STAGE INNOVATION WILL BE PREPARED WITH STUDIES OF ORGANISM SYSTEM BASED UPON VLSI TECHNOLOGY.

Panasonic

Dataquest The Dun & Bradstreet Corporation



PERSPECTIVE ON SEMICONDUCTOR APPLICATIONS

David G. Norman Research Analyst Semiconductor User and Applications Group Dataguest Incorporated

Mr. Norman is a Research Analyst for Dataquest's Semiconductor User and Applications Group. His responsibilties include researching the consumer electronics market, maintaining and enhancing the electronic equipment forecast data bases, and supporting Dataquest's Japanese Semiconductor Application Markets product in the United States. Mr. Norman's previous experience at Dataquest includes three months in the company's Tokyo office, where he assisted in developing the Japanese Semiconductor Application Markets product. Mr. Norman received a B.S. degree in Electrical Engineering from the University of California at Santa Barbara.

> Dataquest Incorporated JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE April 11-12, 1988 Tokyo, Japan



Japan's New International Role: Competition and Cooperation

PERSPECTIVE ON SEMICONDUCTOR APPLICATIONS

DAVID G. NORMAN

Research Analyst Semiconductor User and Applications Group Dataquest Incorporated

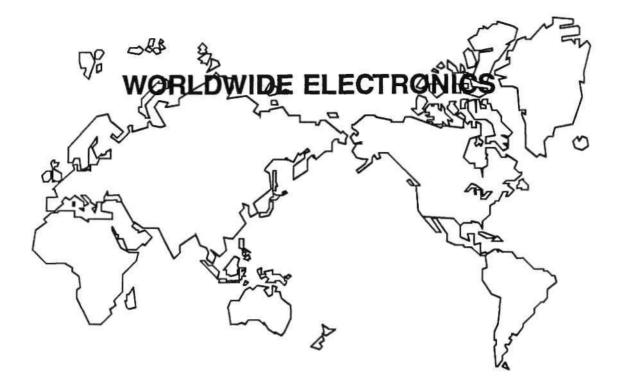
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AGENDA

- Worldwide electronics
- Regional electronics
 - Japan
 - North America
 - Europe
 - Rest of World
- Application market issues
- User issues

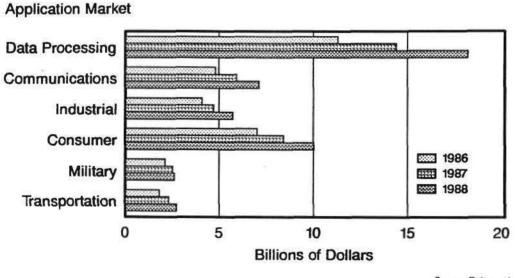
MAIN POINTS

- Critical markets
- Demand drivers
- Issues

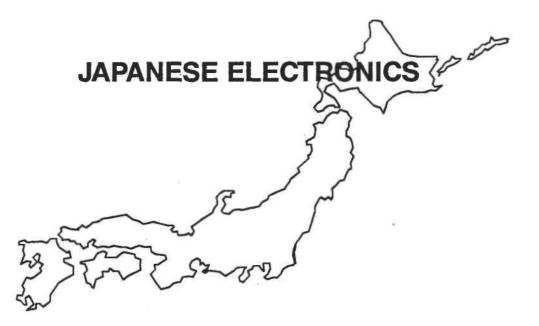


WORLDWIDE SEMICONDUCTOR CONSUMPTION

By Application Market

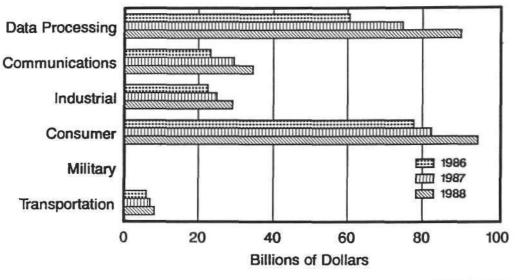


Source: Dataquest



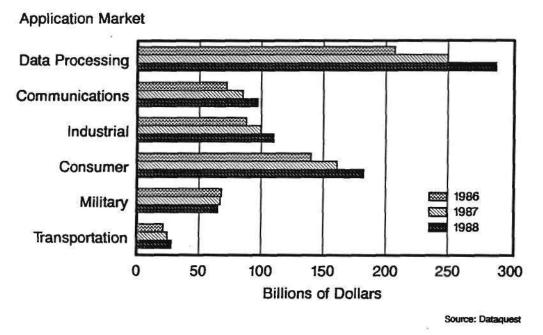
JAPANESE ELECTRONICS PRODUCTION





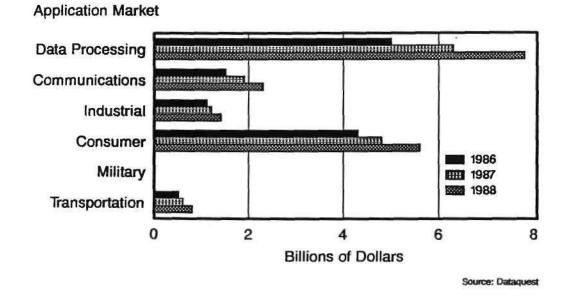
Source: Dataquest

WORLDWIDE ELECTRONICS PRODUCTION



JAPANESE SEMICONDUCTOR CONSUMPTION

By Application Market



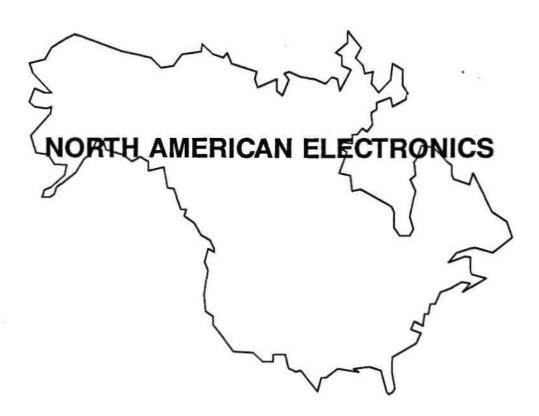
OUTLOOK FOR JAPAN'S MAJOR SEMICONDUCTOR MARKETS

(Billions of Dollars)

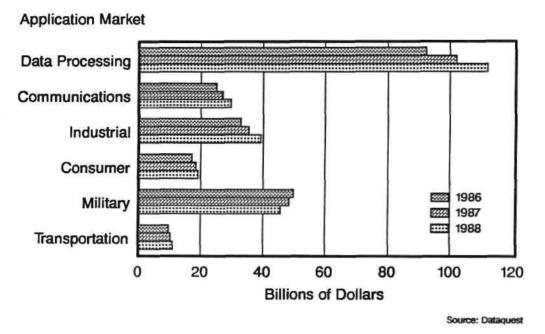
	1987	1991	CAGR 1987-1991		
VCRs	\$8.6	\$11.1	6.6%		
Mainframe	\$8.1	\$13.6	13.8%		
Personal Computers	\$2.6	\$ 5.3	18.4%		
Terminals	\$5.0	\$ 8.3	12.9%		
Color TVs	\$5.3	\$ 7.1	7.6%		

Note: Based on production value

Source: Dataquest

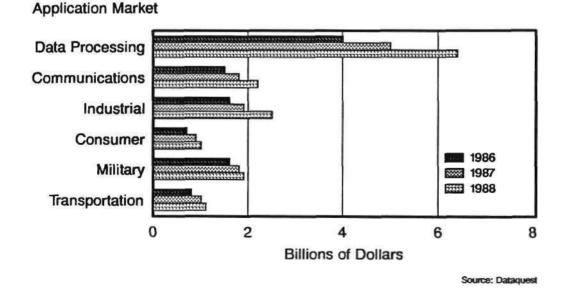


NORTH AMERICAN ELECTRONICS PRODUCTION



NORTH AMERICAN SEMICONDUCTOR CONSUMPTION

By Application Market

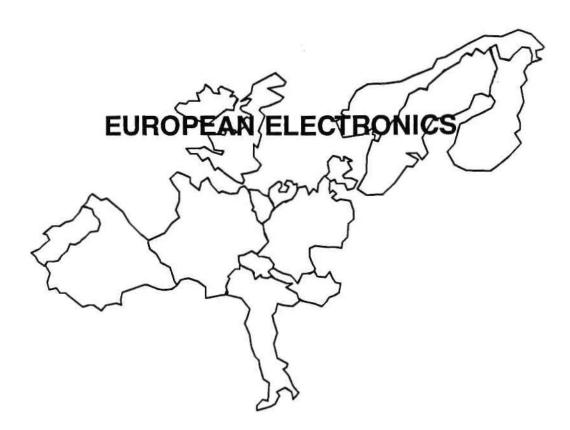


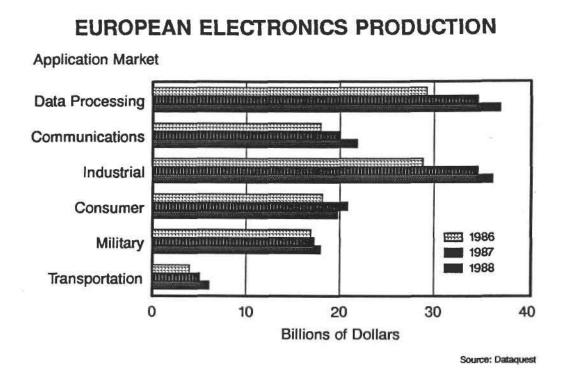
OUTLOOK FOR NORTH AMERICA'S MAJOR SEMICONDUCTOR MARKETS

(Billions of Dollars)

			CAGR
	1987	1991	1987-1991
Personal Computers	\$19.2	\$26.3	8.2%
Automotive Power Train/			
Engine Control	\$ 3.2	\$ 4.2	7.1%
Rigid Disk Drives	\$17.3	\$21.2	5.2%
Corporate Resource Computers	\$13.6	\$16.7	5.3%
Large Department Computers	\$ 9.4	\$12.3	6.8%

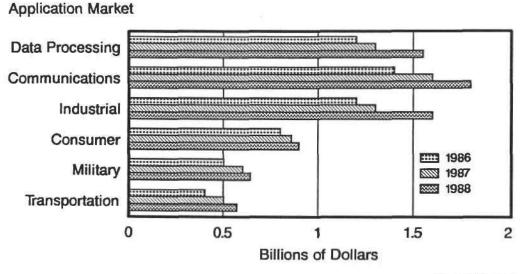
Source: Dataquest





EUROPEAN SEMICONDUCTOR CONSUMPTION

By Application Market



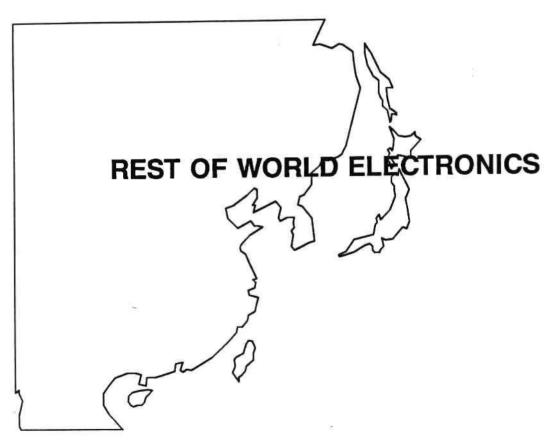
Source: Dataquest

OUTLOOK FOR EUROPE'S MAJOR SEMICONDUCTOR MARKETS

(Millions of Dollars)

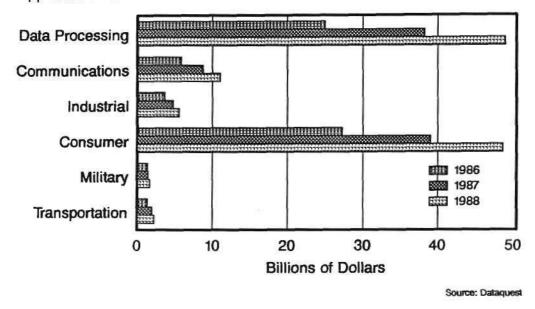
			CAGR
	1987	1991	1987-1991
Compact Disk Players	\$ 447	\$ 730	13.0%
Personal Computers	\$8,424	\$11,645	8.4%
Automotive/Engine Control	\$2,734	\$ 4,278	11.8%

Source: Dataquest



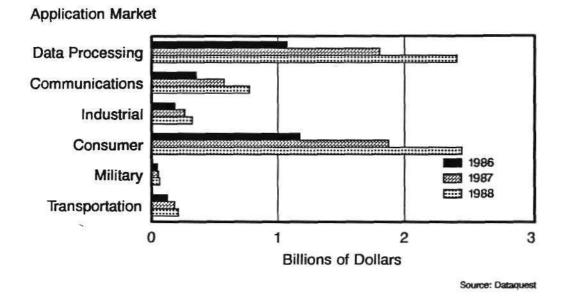
REST OF WORLD ELECTRONICS PRODUCTION

Application Market



REST OF WORLD SEMICONDUCTOR CONSUMPTION

By Application Market



OUTLOOK FOR REST OF WORLD MAJOR SEMICONDCUTOR MARKETS

(Millions of Dollars)

	1987	1991	CAGR 1987-1991
Personal Computers	\$ 931	\$2,168	23.5%
TVs	\$1,440	\$1,937	7.7%
VCRs	\$ 325	\$ 518	12.3%

Note: Includes Republic of China, Hong Kong, and Singapore

Source: Dataquest



DATA PROCESSING ISSUES

- Japan's new focus on the information processing industry
- Product availability:
 Leading-edge memories and microprocessors
- IBM PS/2 clonability
- Acceptance of OS/2

COMMUNICATIONS ISSUES

- ISDN
- FDDI
- Upgrade analog to digital switching technology
- Integration of voice and data communications
- Connecting the desk

INDUSTRIAL ISSUES

- Technology upgrade: move from analog to digital
- Network standards for manufacturing automation
- Islands of automation instead of centralized control
- Automation growth in industries other than automotive

CONSUMER ISSUES

- Base of manufacturing shifting
- Searching for the next VCR
- Only one major U.S.-based company exists
- Increased functionality to drive sales

MILITARY ISSUES

- Slowing of Reagan era
- Upgraded programs
- Foreign dependency on technology
- Defense sharing (NATO, Japanese involvement)
- · Keeping up with competition

TRANSPORTATION ISSUES

- Component reliability
- Emerging semiconductor applications:
 - Antilock braking
 - Electronic suspension
 - Airbags/seat restraints
 - Electronic steering
- Continued automotive semiconductor growth despite slowing auto production
- Semiconductor products to be integrated in near term:
 16-bit microcontrollers
 - Application-specific standard products
 - Power ICs

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WHAT'S ON THE USERS' MINDS?



WHAT'S ON THE USERS' MINDS?

The Major Issues

1986

Pricing Quality/reliability On-time delivery Supply/availability/shortages JIT/inventory control Reducing vendor base Product obsolescence Second-sourcing Forecasting 1987

Pricing Availability/lead times Quality/reliability On-time delivery FMVs/trade agreement Cost control JIT/inventory control Surface mount New products/obsolescence ASICs Offshore manufacturing and procurement

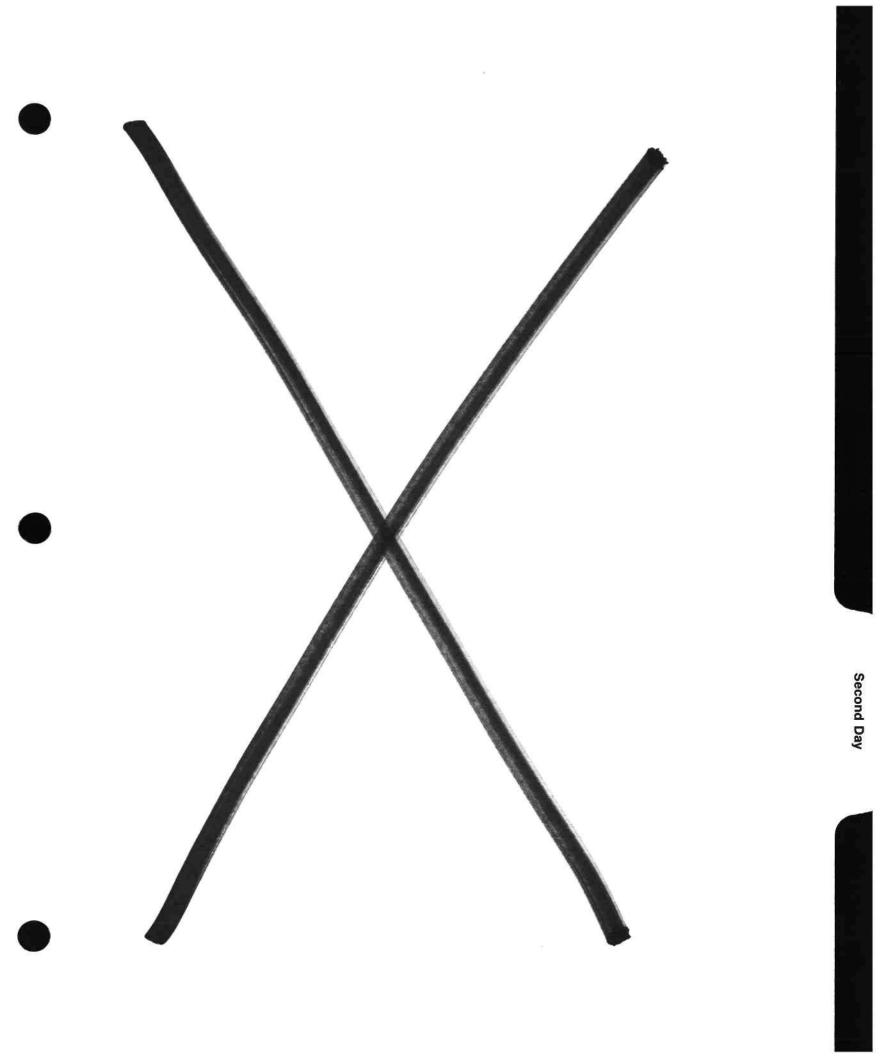
CONCLUSIONS

- Critical markets for success:
 - Data processing
 - Consumer
- Demand drivers:
 - Personal computers
 - VCRs
- Issues:
 - Semiconductor availability
 Technology dependence

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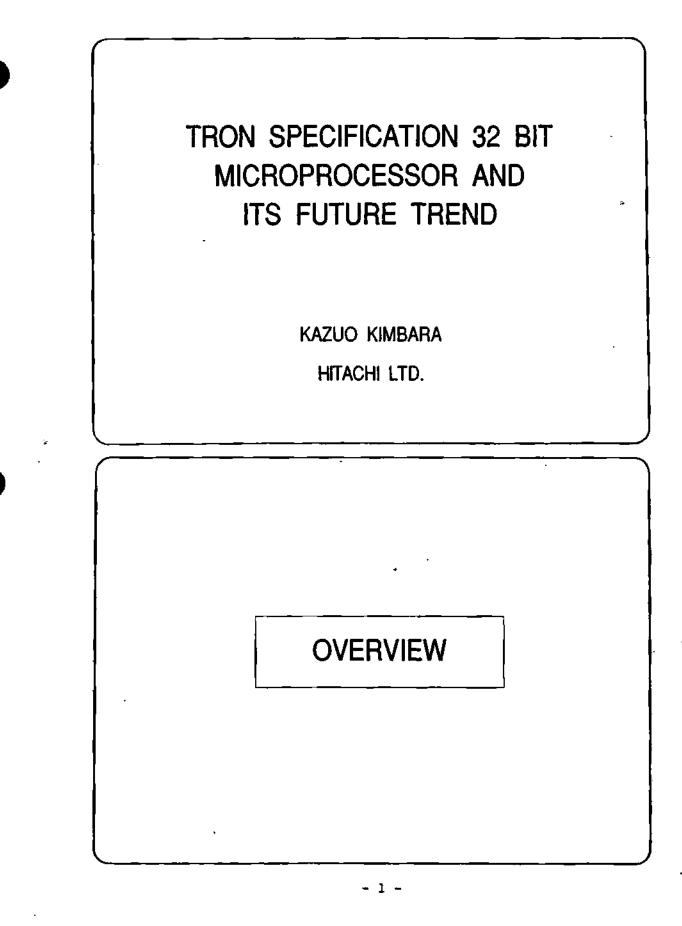
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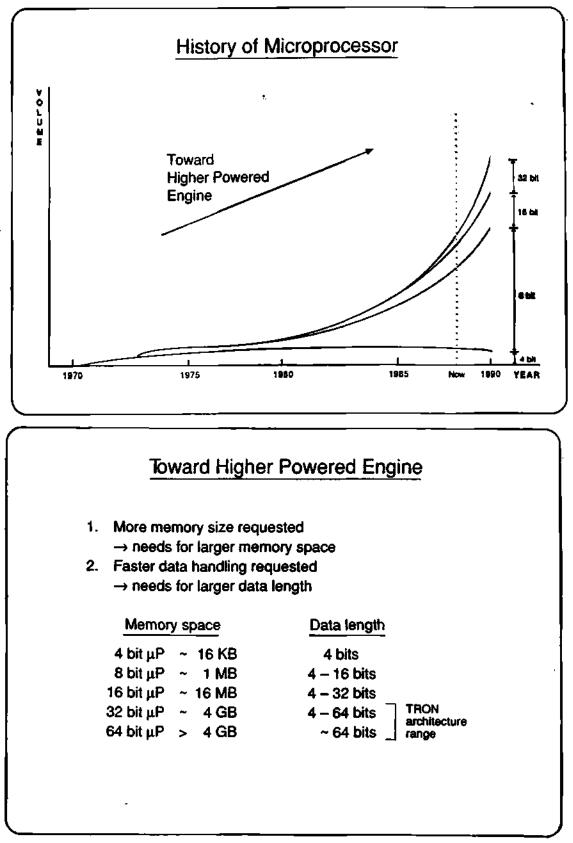
FUTURE TRENDS OF 32-BIT TRON MICROPROCESSOR

Kazuo Kimbara Board Director, Group Executive Electronic Devices Group Hitachi, Ltd.

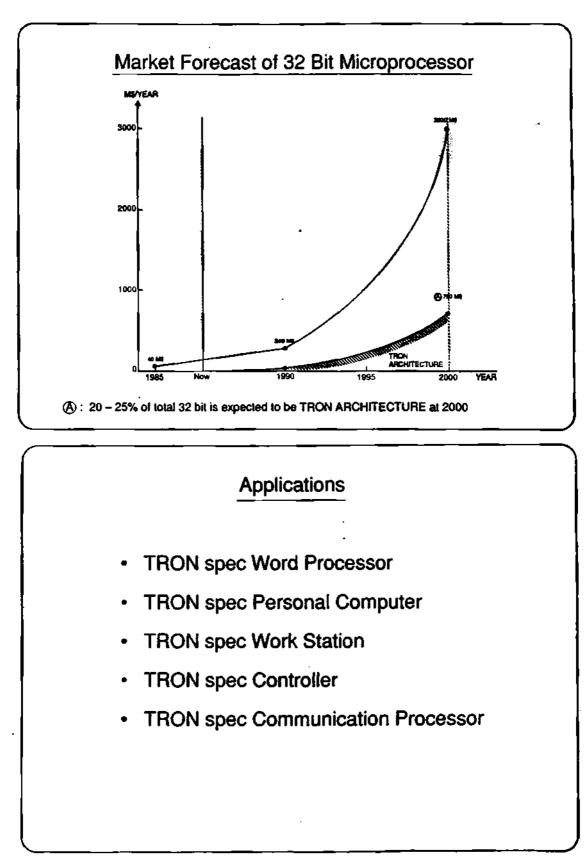
Mr. Kimbara is Board Director and Group Executive of the Electronic Devices Group at Hitachi, Ltd. He is also Chairman of the TRON Association. At Hitachi, he is in charge of semiconductor devices and electron tube products. His previous positions at Hitachi have included General Manager of the Takasaki Works, General Manager of the Musashi Works, and General Manager of the Semiconductor and IC Division. Mr. Kimbara received a Bachelor of Engineering degree at the School of Engineering at Nagoya University.

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- 2 -



- 3 -

TRON PROJECT

TRON Project

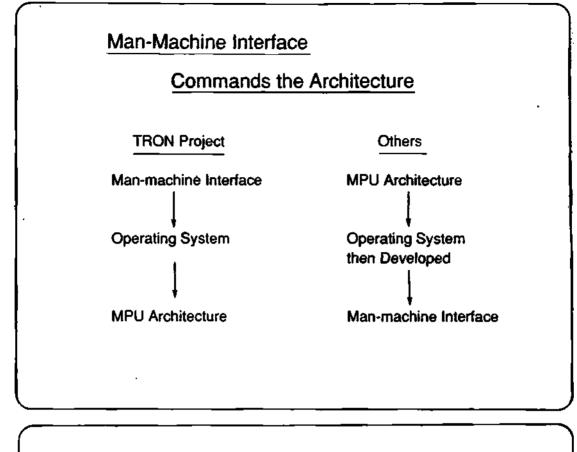
Basic Philosophy

• For more persons

For easier man-machine communications

- Highest technology optimized in 1990's
- Architecture shall be put in public domain

- 4 -



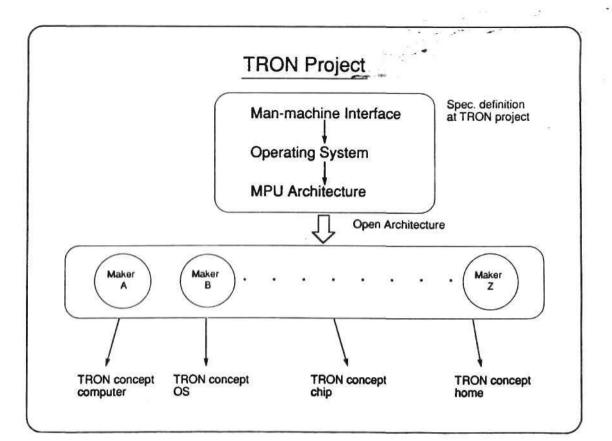
TRON (The Beal-Time Operating System Nucleus)

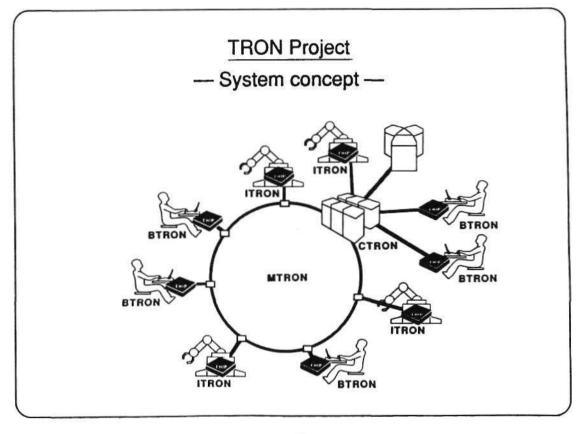
- TRON Project
 - Started in June, 1984
 - Proposed and conducted by Dr. Ken Sakamura of Science Department of the University of Tokyo

TRON Association

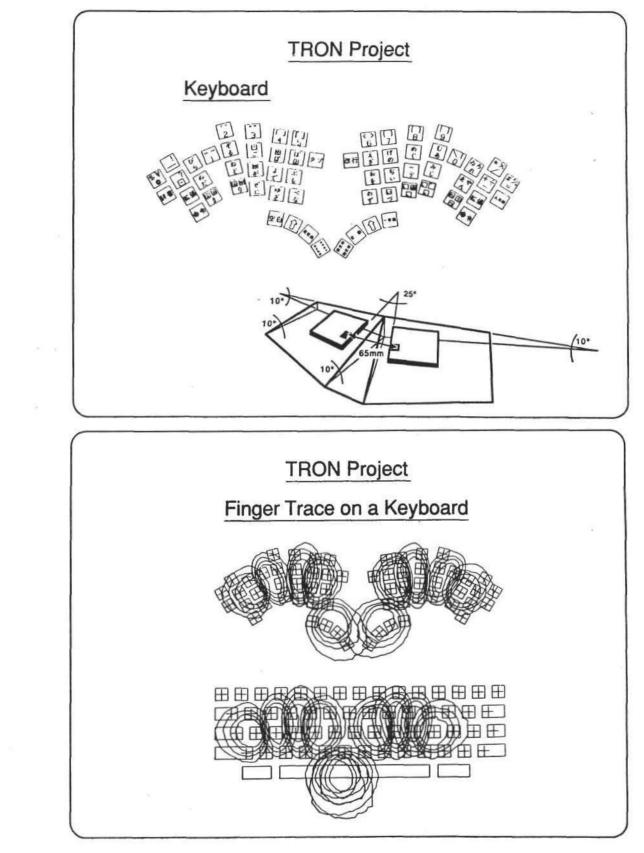
- Started in June, 1986
- Chairman: Mr. T. Yamamoto President of Fujitsu Ltd.
 Vice chairman: Mr. K. Kimbara Board Director of Hitachi LTD.
- Over 100 companies participate in the association

- 5 -

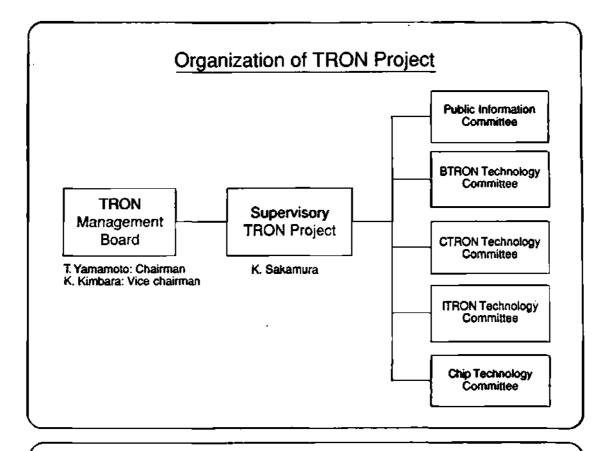




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- 7 -



TRON Project

WHO and WHAT

WHO	Board Members of TRON Association							
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В	0	0	0	0	0	0	0	
C	0	0	0	0	0		0	0
M			1					
32 B MPU	0	0	0	0	1	0	0	
					-	veloped or creo Famil	-	_
Above table	is compo:	sed of pro	ess and/o	r magazi	ne news	released t	Nikkei	Byte Feb. 1987

Asahi 29 Sept. 1987 Nikkei Sangyo 3 Sept. 1987

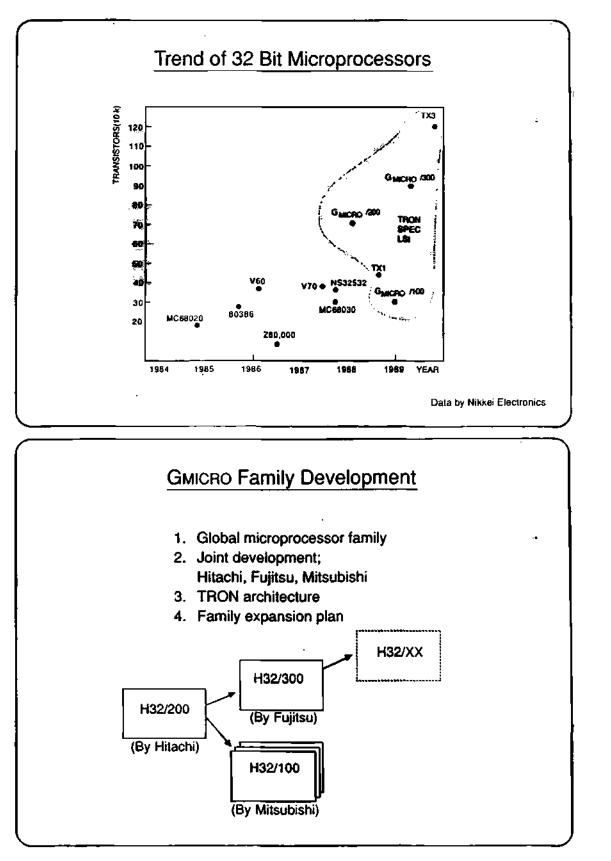
- 8 -

TRON SPECIFICATION 32 BIT MICROPROCESSOR

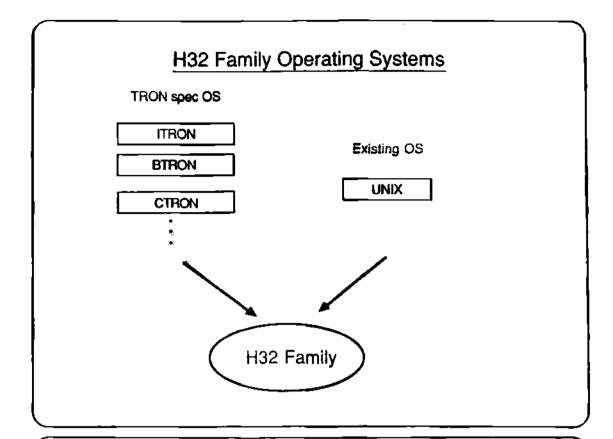
TRON Spec Chip Architecture

- Fast response time
- · Efficient handling of international languages
- Powerful graphic handling
- Well suited for
 - TRON spec operating systems
 - High level language
- Future expandability to 64 bit

- 9 -



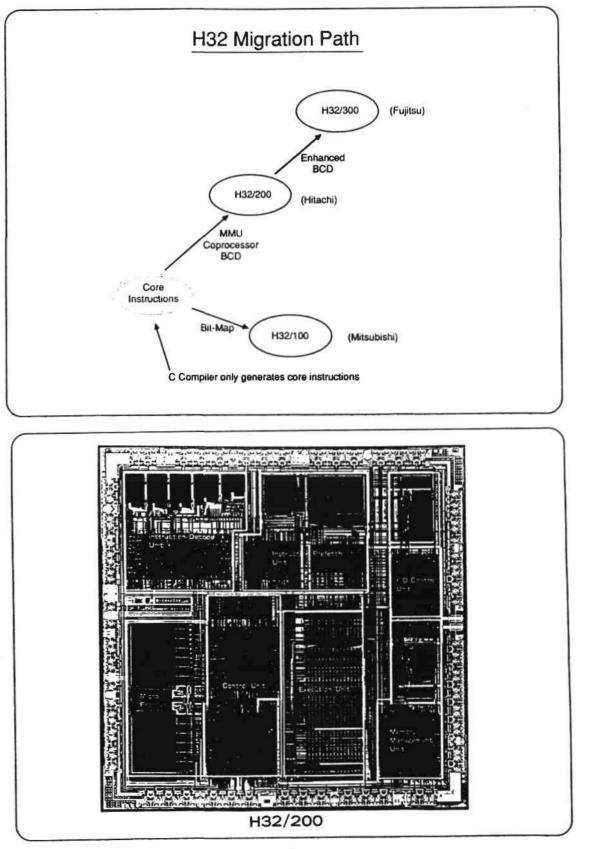
- 10 -



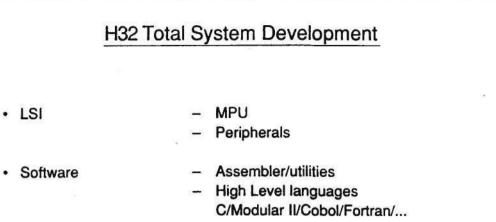
Specifications of H32 Family

	H32/100	H32/200	H32/300		
Performance - EDN MIPS - Whetstone	4.5	6 4			
Coprocessor Interface	No	Yes	Yes		
MMU on chip	No	Yes	Yes		
On chip caches	No	Yes	Yes		
Features -	Strong bit map operation	High performance TRON spec chip	Enhanced BCD operation		
Terget Market	• µ8TRON • I/O Controlier • ASIC core	EWS Embedded controller Communication processor	• EWS • Office machine • Super-minicon		
Sample	'89/2Q	'88/2Q	'89/2Q		

- 11 -



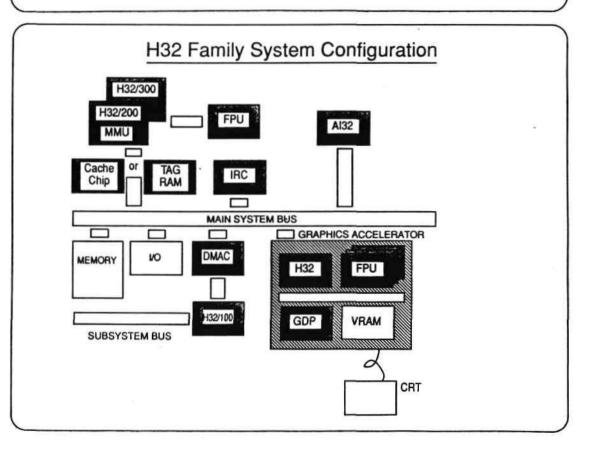
- 12 -





3rd party development .

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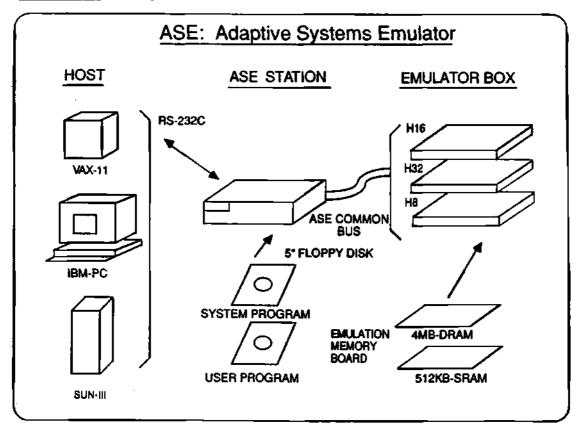
- 13 -



Peripherals - Shared Efforts

- FPU Floating Point Arithmetic Unit (Hitachi)
- DMAC Direct Memory Access Controller (Fujitsu)
- TAGM TAG Memory (Fujitsu)
 - CCM Cache Control and Memory (Mitsubishi)
- IRC Interrupt Request Controller
 (Fujitsu)
- Al32 Artificial Intelligent Coprocessor (Hitachi)
 - GDP Graphic Data Processor

(Hitachi)



- 14 -

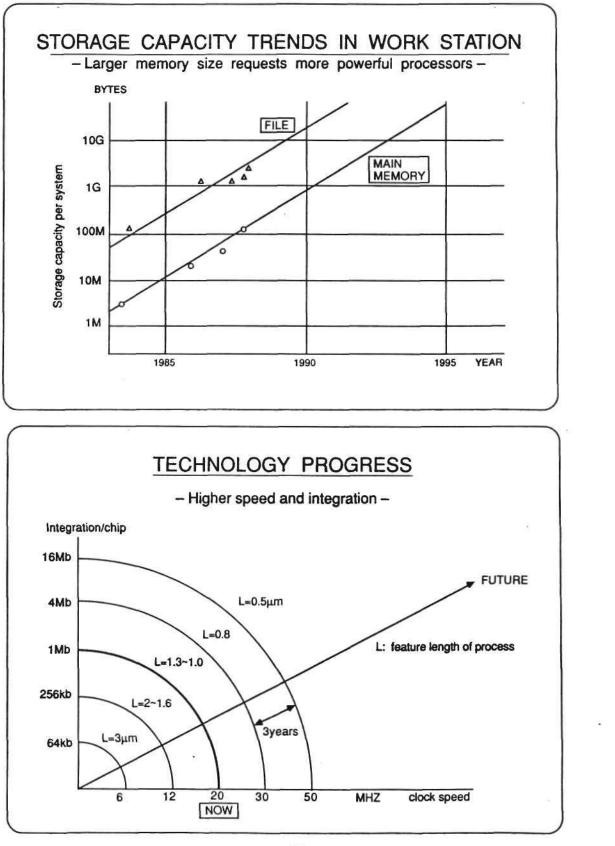
	Sampling Schedule								
		'88/1Q	2Q	3Q	4Q	89/1Q	2Q	3Q	4Q
	H32/100			1			0	<u> </u>	
	H32/200		0						
	H32/300						0		
	FPU		_		0				
LSI	DMAC			0					1
	IRC		0						
	TAGM	0 T		1					
	CCM				0				
	CPG		_	0					
Tool	Assembler		0						
	С		0						
	ASE (Emulator)				0				
	SBC				0				

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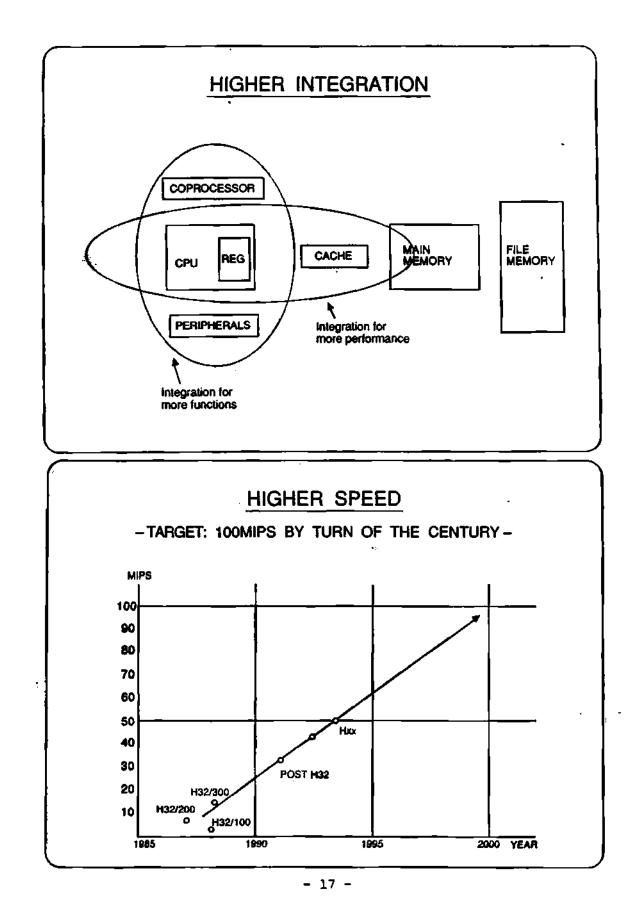
FUTURE TREND

2

- 15 -



- 16 -



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OTHER TOPICS

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1. MULTI PROCESSOR SYSTEM

2. ARTIFICIAL INTELLIGENT ENGINE

3. FAULT TORELANT SYSTEM

Conclusions

- Hitachi participates in TRON project in several different areas.
- Major efforts are put on the development of H32 microprocessor family.

Sharing developing man-power with Fujitsu and Mitsubishi.

 H32 microprocessor family will be introduced to the customers in this year, as a kit, with great performance advantages and unique features.

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JOINT VENTURE STRATEGIES

Murray A. Goldman Senior Vice President and General Manager Microprocessor Products Group Motorola Incorporated

Dr. Goldman is a Senior Vice President and General Manager of the Microprocessor Products Group at Motorola. He has spent 27 years in the electronics industry, including 7 years at Bell Telephone Laboratories, 2 years at New York University, and the last 19 years at Motorola. His experience spans the areas of computer design, CAD, factory automation, and semiconductor production engineering. Dr. Goldman has managed Motorola's Microprocessor Products Operation for the past 12 years. He and his staff have provided the leadership to help create major industry standards with 8-, 16-, and 32-bit microprocessor products.

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Joint Venture Strategies

Murray Goldman

Sr. Vice President & General Manager

٠,

Microprocessor Products Group

Motorola

Why Joint Ventures?

- Market penetration
- Reduce R&D expenditures
- Share complementary strengths
- Expand product portfolio

- 1 -

Complexities and Issues

- Culture differences
- Corporate philosophy
- Perceived value of intellectual assets
- Execution
- Win / Win agreement
- Trust ... Patience

Requirements for Entering Japanese Market

- Leadership product portfolio
- Top quality is mandatory
- Complete customer support
- Strong relationships
- Long term commitment
- Utilize local talent

- 2 -

Motorola's Thrust into Japanese Market

- Leadership MPU products
- Superb quality
- Nippon Motorola
- Local capabilities
- Toshiba alliance

Toshiba Relationship

- Corporate cultures compatible
- Complementary strengths
 (Motoroia MPUs and Toshiba RAMs)
- Joint factory
 - Engineering efficiency
 - Eases product transfer
 - Common process
 - Long term compatibility
 - Better serve local market
- Trust

- 3 -



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LEADING ASIC TECHNOLOGIES

Gordon A. Campbell Chairman of the Board, President, and CEO Chips and Technologies, Inc.

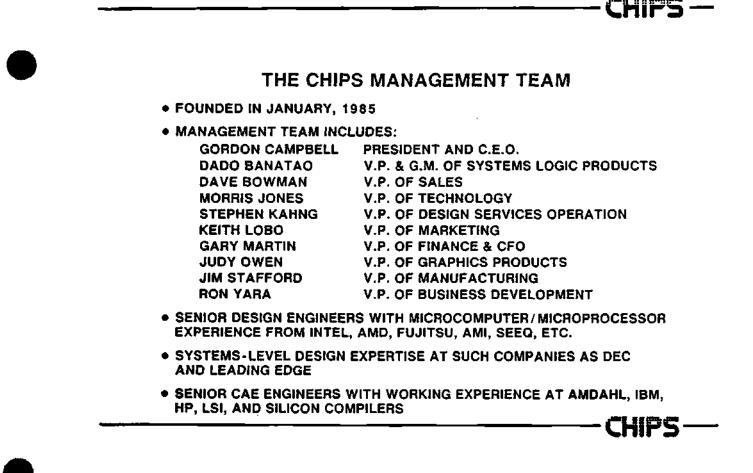
Mr. Campbell founded Chips and Technologies, Inc., in January 1985, and since then has served as the company's Chairman of the Board, President, and Chief Executive Officer. Prior to founding Chips, he was a founder of Seeq Technology, Inc., a semiconductor manufacturer, and served as that company's President and Chief Executive Officer for more than three years. Earlier, he served in various management positions at Intel Corporation, most recently as Marketing Manager, Special Products Division.

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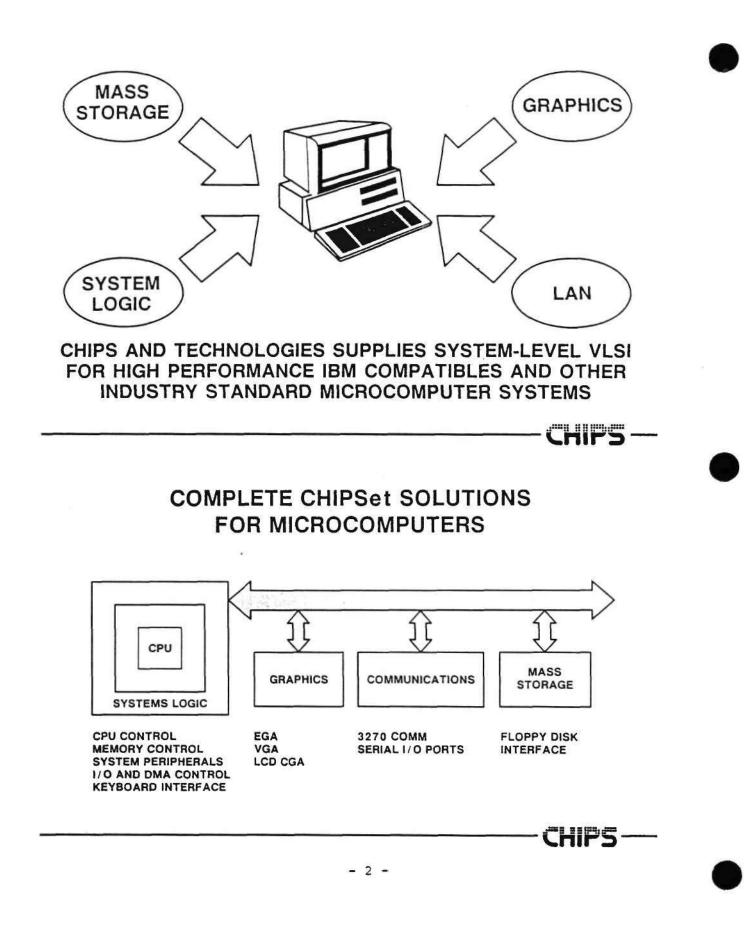


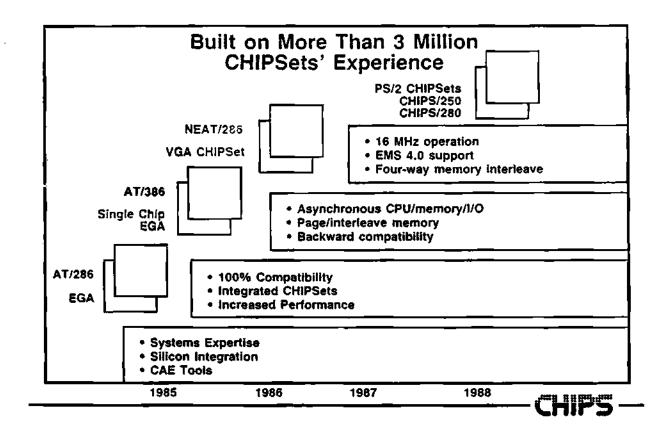
Chips and Technologies, Inc.

Solutions for a Changing World



- 1 -





Manufacturing Strategy

UTILIZE SUBCONTRACT MANUFACTURING

LEVERAGE VARIABLE COST STRUCTURE

VS

FIXED COST OF OWN FAB FACILITY

- DESIGN WITH TECHNOLOGY INDEPENDENCE
 - CAN USE BEST TECHNOLOGY FOR EACH APPLICATION
 - NO TECHNOLOGY DEVELOPMENT COSTS

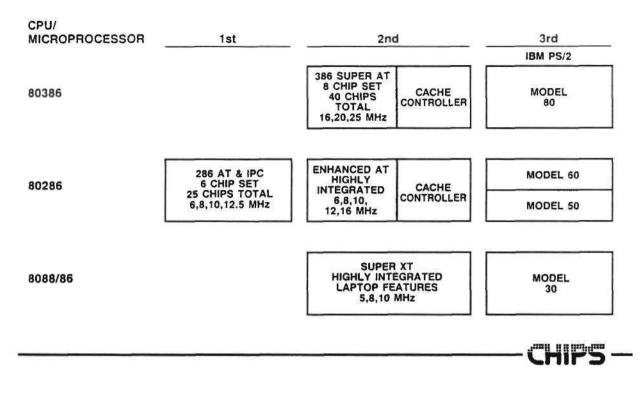
FLEXIBILITY IN SUPPLY/CAPACITY

- MULTIPLE SOURCES OF SUPPLY
- BEST PROCUREMENT COST STRUCTURE
- FASTEST RAMPING CAPABILITY
- LOWEST PROBABILITY OF PROBLEMS

CHIPS-

- 3 -

PERSONAL COMPUTER GENERATIONS



CHIPS' STRATEGY FOR PS/2

- PROVIDE COMPLETE CHIPSet SOLUTIONS
 - COMPATIBILITY



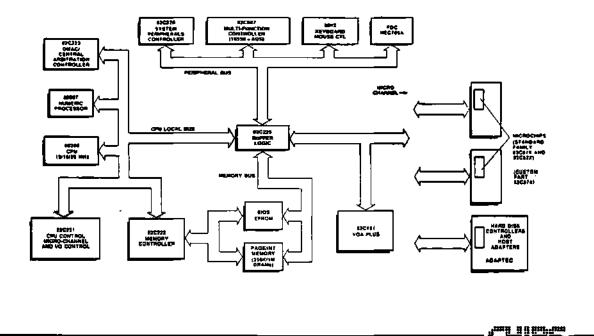
- PLUS
- PERFORMANCE
- INTEGRATION
- FUNCTIONALITY

CHIPS

- 4 -

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Meeting the Challenge: System Integration



CHIPS' "Plus" Scoreboard

Performance

- 2× faster than IBM Model 50
- 50% higher Micro Channel memory bandwidth
- 50% faster VGA memory & I/O cycles

Integration

- 66 versus 179 for the Model 80
- 68 versus 119 for the Model 50

• Functionality

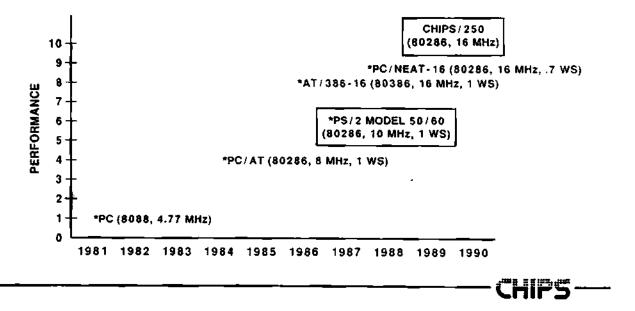
- Asynchronous CPU/memory/DMA
- Four-way interleaved memory
- VGA with graphics cursor
- Integrated EMS 4.0

- 5 -

Introducing CHIPS' PS/2 Family

Function	Model 50/60	Model 80
System Logic	CS8225	CS8238
Graphics	82C451/2	82C451/2
COMM/FD I/O	82C607	82C607
Micro Channel Adapter Interface	82C6XX	82C6XX
	CHIPS/250	CHIPS/280

MEETING THE CHALLENGE: PERFORMANCE SUPERIORITY

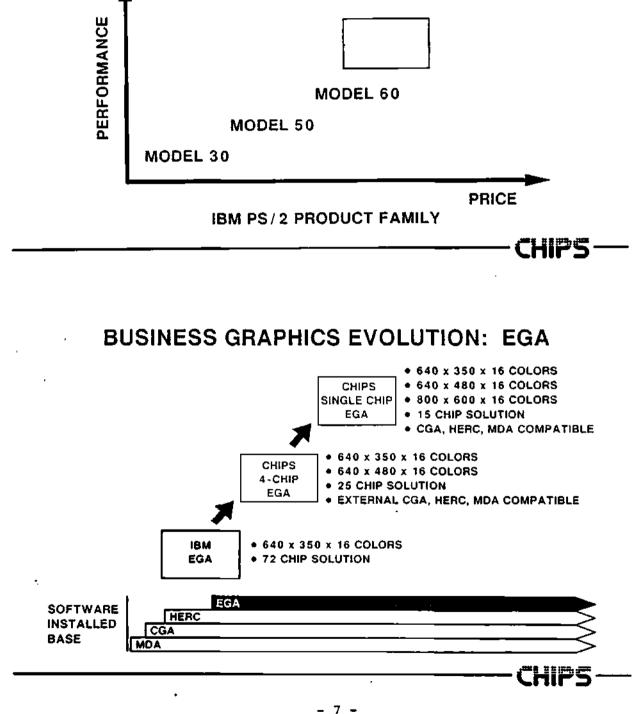


- 6 -

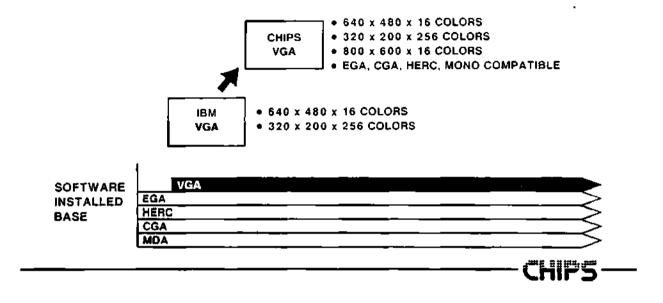
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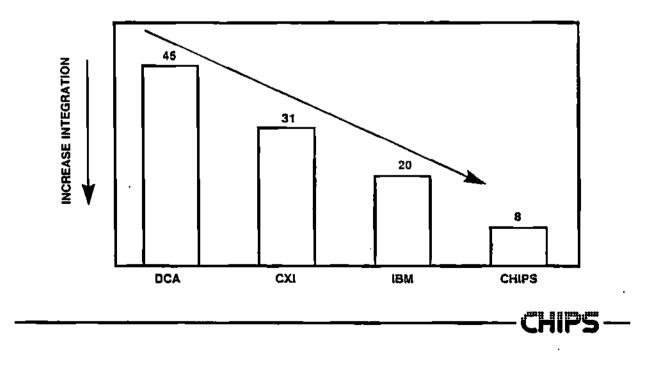
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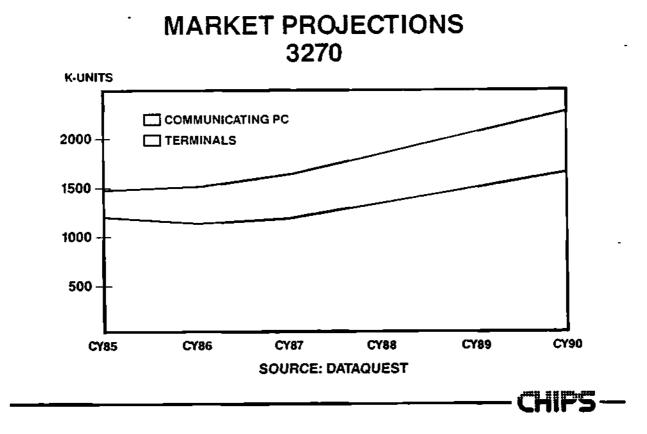
BUSINESS GRAPHICS EVOLUTION: VGA



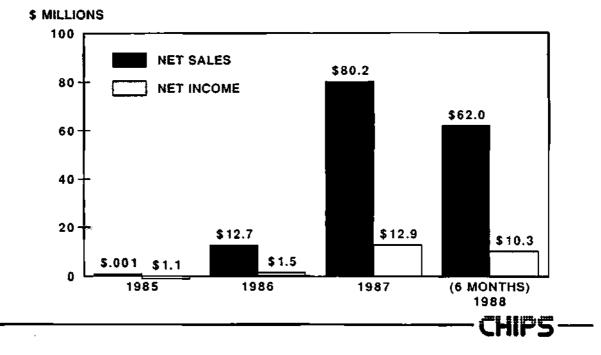
3270 INTEGRATION



- 8 -

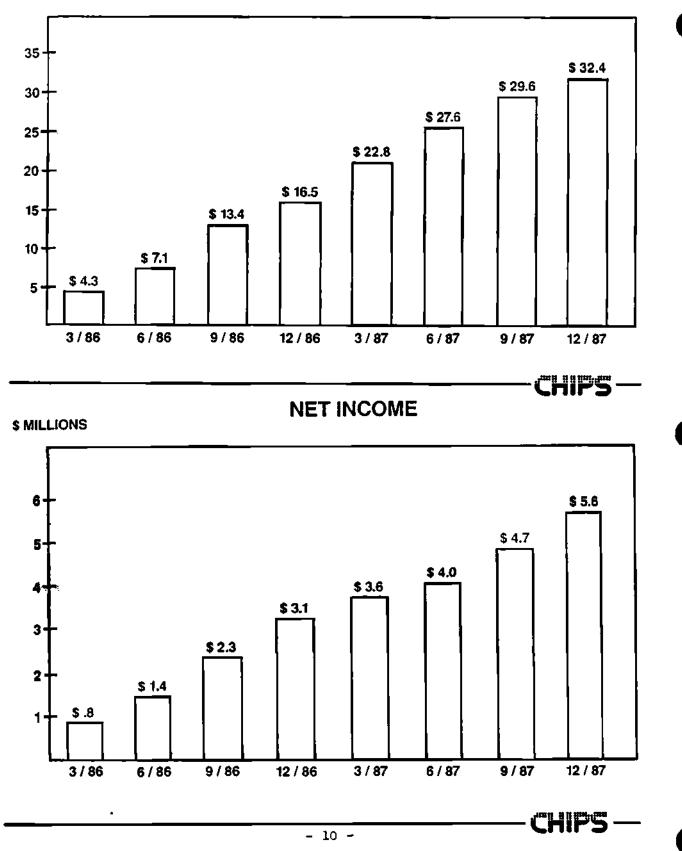


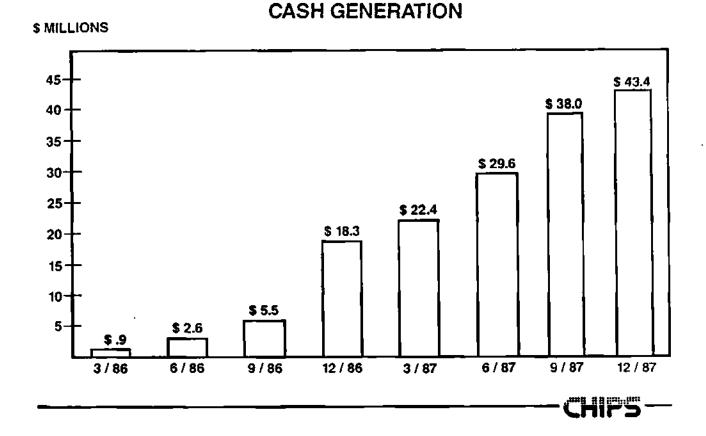
ANNUAL NET SALES AND NET INCOME



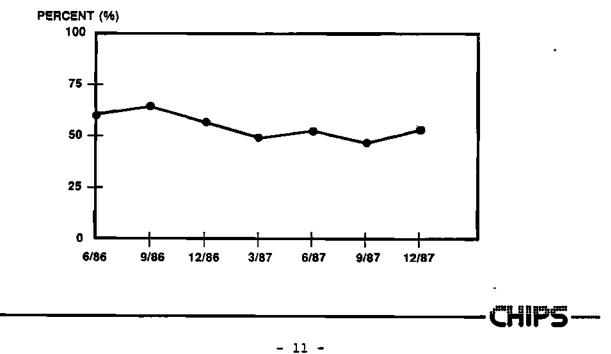
- 9 -





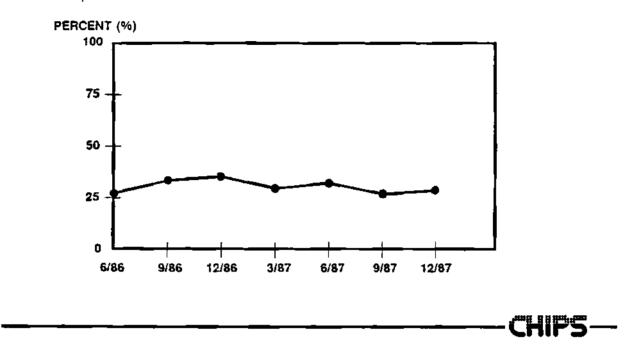


GROSS MARGIN ANALYSIS



- 11 -

PRETAX MARGIN ANALYSIS



QUARTER ENDED DECEMBER 31, 1987

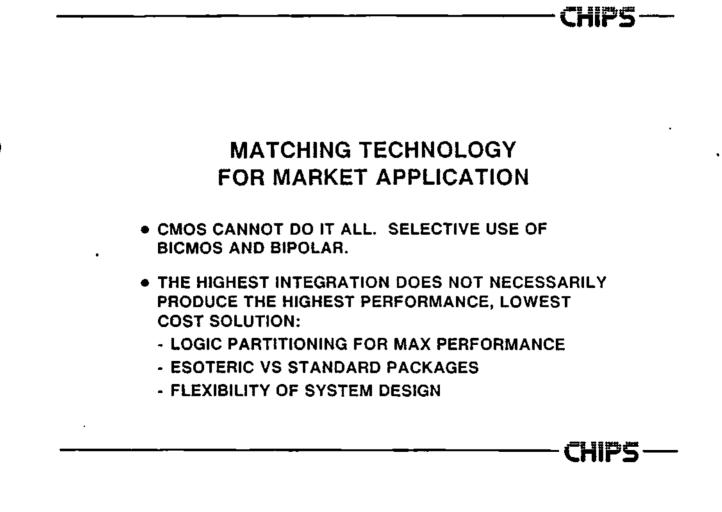
\$43.4 MILLION CASH \$3.05 CASH PER SHARE 4.5 TO 1 CURRENT RATIO LONG TERM DEBT \$2.9 MILLION DEBT TO EQUITY .92 TO 1 INVENTORY TURNS 11.6x • RETURN ON EQUITY **48% ANNUALLY** CASH FLOW PER SHARE \$.42 PER QUARTER

CHIPS-

- 12 -

THE CHANGING ROLE OF ASIC TECHNOLOGIES

GORDON A. CAMPBELL PRESIDENT AND CEO CHIPS AND TECHNOLOGIES, INCORPORATED



- 13 -

MATCHING TECHNOLOGY FOR MARKET APPLICATION

- SOME APPLICATIONS DO NOT NEED MORE THAN MEDIUM DENSITY ASICS. VALUE ADDED IS IN SYSTEMS INTEGRATION KNOWLEDGE AND SOFTWARE.
- LIKE ANY OTHER TECHNOLOGY ASICS HAS A HIGH AND A LOW END. KNOWING WHEN TO APPLY A SPECIFIC SOLUTION WILL BE MORE IMPORTANT IN THE FUTURE THAN THE SOLUTION ITSELF.



CHIPS

CHIP5-

- SYSTEM SIMULATION INCORPORATING PROCESSOR MODEL AND OTHER SUPPORT LOGIC REQUIRES MIXED BEHAVIORAL, GATE LEVEL AND HARDWARE MODELING.
- ASIC DESIGN ISN'T COMPLETE UNTIL SYSTEM INTEGRATION HAS BEEN TESTED. TOTAL ELAPSED TIME \approx 9-12 MONTHS.

- 14 -

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IMPACT OF LEADING ASIC TECHNOLOGIES ON PRODUCT DEVELOPMENT

- SEA OF GATES APPROACHES WILL DOMINATE HIGH END ASIC DESIGN AND WILL WIN MARKET SHARE FROM CELL BASED TECHNOLOGIES
 - FASTER TURNAROUND
 - ON-CHID MEMORY CAPABILITY
 - EASE OF IMPLEMENTATION OF COMPLEX CORE CELLS
 - BETTER CHARACTERIZATION; LESS RISK



CHIPS-

CHIPS-

- FEASIBILITY OF NEW APPLICATIONS
 - CACHE CONTROLLERS AND MEMORY MANAGEMENT
 - HIGHER RESOLUTION BIT MAPPED GRAPHICS
 - SINGLE CHIP CUSTOM PROCESSORS
- CUSTOMIZATION OF SYSTEM LEVEL CONTENT AS OPPOSED TO CHIP LEVEL CONTENT
- FUTURE VALUE ADDED WILL BE IN SYSTEM LEVEL HARDWARE/SOFTWARE INTEGRATION



WHAT ARE LEADING ASIC TECHNOLOGIES IN 1988?

- SUB 1.0μ SEA OF GATES AND STANDARD CELL.
 - 2-LAYER AND 3-LAYER METAL INTERCONNECT
 - HCMOS AND BICMOS
- EPLDS AND PROGRAMMABLE GATE ARRAYS OFFERING DENSITIES OF SEVERAL THOUSAND USEABLE GATES.
- EXTENSIVE AND WELL CHARACTERIZED CELL AND FUNCTION LIBRARIES.
- MULTI VENDOR SILICON SPECIFIC CAD CAPABILITY.
- SYSTEM DESIGN AND APPLICATION KNOWLEDGE.

PRODUCT DEVELOPMENT CYCLES USING LEADING ASIC TECHNOLOGIES

CHIPS-

CHIPS

- REQUIREMENT FOR ARCHITECTURAL LEVEL DEFINITION AND SIMULATION.
- ACCELERATED GATE LEVEL SIMULATION. COMPLEX ASICS REQUIRE SEVERAL MAN MONTHS OF DETAILED LOGIC DESIGN WORK.
- BIOS DEVELOPMENT AND OTHER SYSTEM LEVEL SOFTWARE NEEDS TO BE DEVELOPED IN PARALLEL WITH HARDWARE.

- 16 -





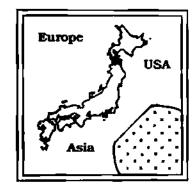


EMERGING TECHNOLOGIES

Sheridan M. Tatsuno Senior Industry Analyst Japanese Semiconductor Industry Service Dataquest Incorporated

Mr. Tatsuno is a Senior Industry Analyst for Dataquest's Japanese Semiconductor Industry Service. He is reponsible for analyzing trends in Japanese government policies, procurement, financial markets, industrial financing, subsidized R&D, overall economics, and industrial plant siting. Prior to joining Dataquest, he had seven years of experience in market research, planning, and international finance with Bechtel Corporation and Woodward-Clyde Consultants. Mr. Tatsuno received a B.A. degree in Political Science from Yale University and an M.A. degree in Planning and Policy Analysis from Harvard University's Kennedy School for Government. In addition to these credentials, Mr. Tatsuno is fluent in Japanese, French, and Spanish, and has authored a book called <u>The Technololis Strategy: Japan High</u> Technology and the Control of the <u>21st Century</u>.

> Dataquest Incorporated JAPANESE SEMICONDUCTOR INDUSTRY CONFERENCE April 11-12, 1988 Tokyo, Japan



Japan's New International Role: Competition and Cooperation

EMERGING TECHNOLOGIES IN THE 1990s

SHERIDAN TATSUNO

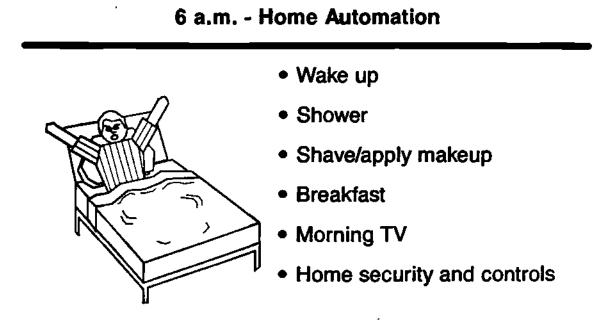
Senior Industry Analyst Japanese Semiconductor Industry Service Dataquest Incorporated

OVERVIEW - A DAY IN THE LIFE OF A. JOE AMERICA

- 6 a.m. Home automation (HA)
- 7 a.m. Car electronics
- 8 a.m. Office automation (OA)
- 5 p.m. Electronic shopping
- 7 p.m. Home entertainment

Where there is a daily inconvenience, there is a market need.

INVENT THE FUTURE!

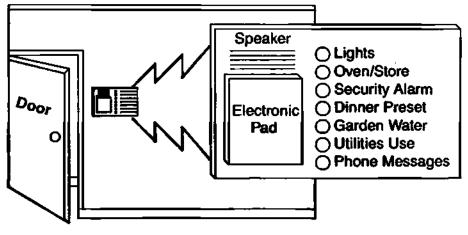


HOME AUTOMATION IN THE 1990s

Problems	Needs	Devices Required
Get Kids Up	Stereo wake-up	MCU, DRAM, S/C lasers
Shower Too Hot/Cold	Preset temperature	Sensor, 4-bit MCU
Breakfast Rushed	Preset cooking	4-bit MCU, DRAM
Traffic Jams	Interactive TV/ traffic advisory	16-bit MCU
Forget Lights, Oven, Alarm and Other Items	House control panel at door	Voice-synthesis chips, audio RAM, 8-/16-bit MCU: sensors

Source: Dataquest

HOME CONTROL SYSTEM OF THE 1990s



Source: Dataquest

7 a.m. - Car Electronics

Problems	Needs	Devices Required
Traffic Jams	Navigation system	Modern ICs, sensors, 16-/32-bit RISC graphics chips, 4Mb/16Mb RAM and ROM
Business Calls	Built-in phone/ fax system	Modem ICs, 16-bit MPUs, 4Mb/16Mb memories

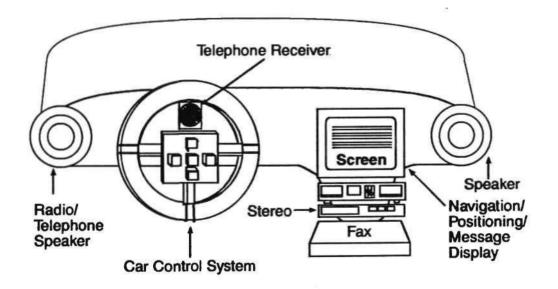
Source: Dataquest

7 a.m. - Car Electronics

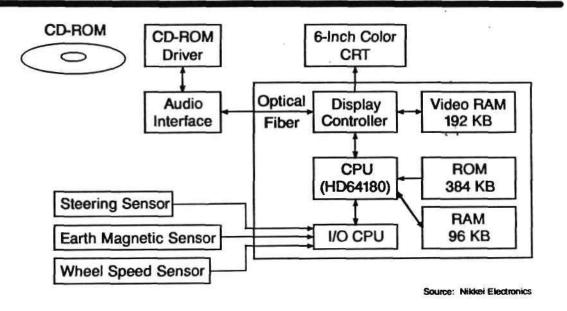
Problems	Needs	Devices Required
Reach for Dials	Built-in steering wheel control system	Voice recognition chips, 16-/32-bit MPUs
Maintenance (Tires, Repairs, Oil)	Maintenance advisory system	4Mb/16Mb ROMs and RAMs 4-bit MCUs
Locked Out	Voice door key	Voice recognition chips

Source: Dataquest

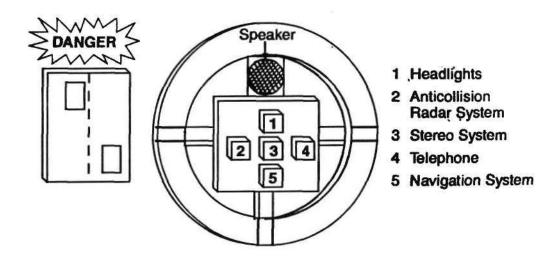
THE AUTOMOTIVE OFFICE OF THE 1990s



TOYOTA'S CD-ROM NAVIGATION SYSTEM



STEERING WHEEL CONTROL SYSTEM

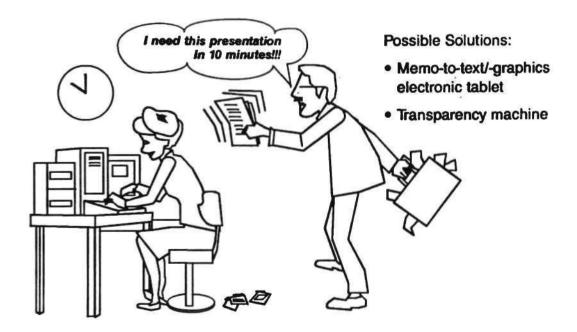


8 a.m. - OFFICE AUTOMATION

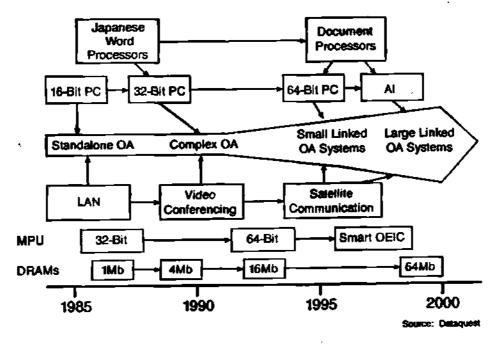
Problems	Needs	Devices Required
Phone Tag	Office wrist phone	Modem ICs, DRAMs, MCUs
Copier and Fax Backed Up	Personal, plain paper fax/copier/printer	32-bit MPUs, DRAMs, ROMs, semiconductor lasers
Where is Person?	Office locator system	Sensors, voice-synthesis ICs
Long Phone Calls	Phone stopwatch and cost calculator	4-bit MCUs, DRAMs
Fax or Phone Cheaper?	Fax/phone alternative cost calculator	MCUs, DRAMs, ROMs

Source: Dataquest

11 a.m. - OFFICE CHAOS



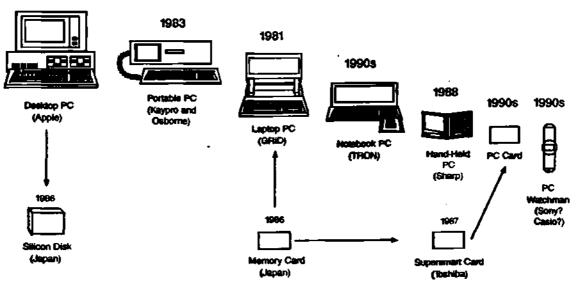
OFFICE SYSTEM TRENDS



THE SHRINKING PERSONAL COMPUTER

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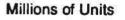


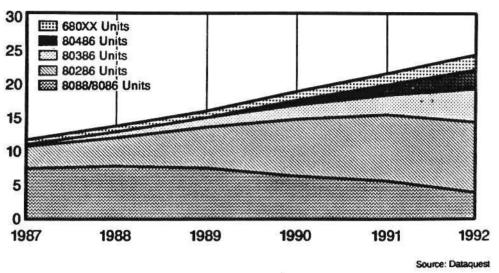
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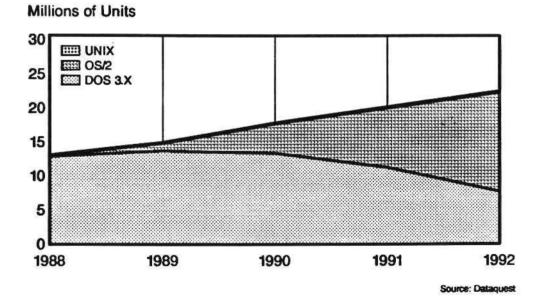
ESTIMATED PC SHIPMENTS

by Microprocessor Type





ESTIMATED PERSONAL COMPUTER OPERATING SYSTEM SHIPMENTS



VIDEOPHONE PC OF THE 1990s

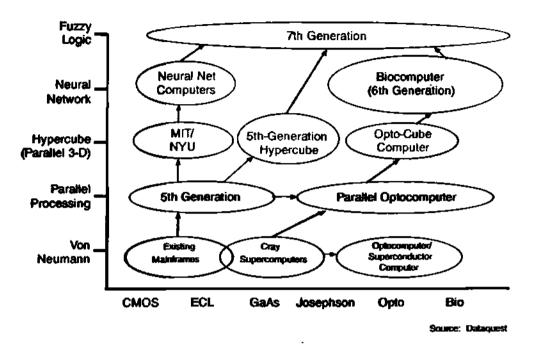
- 4-8 mips
- 4-8MB RAM
- Megapixel color displays
 8-10 inches
- 3.5-inch storage
- Built-in LAN
- Coprocessing
- 80MB hard disk

HOT NEW SEMICONDUCTORS FOR THE OFFICE

Emerging Systems	Semiconductors Needed
Laptop PC	Sea-of-gates ASICs, megabit memories (IC cards) specialized 32-bit MPUs, voice recognition chips
Videophone PC	CCD sensors, voice recognition chips, IC card readers
Personal fax/copier	Advanced telecom ICs, printer font ROM cartridges,

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megabit memory storage



FUTURE COMPUTING TRENDS

5 p.m. - ELECTRONIC COMPARISON SHOPPING

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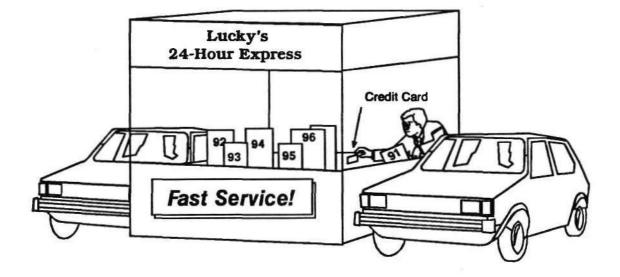
ltem	Lucky's	Safeway	Alpha-Beta
Whole Wheat Bread	\$1.39	\$1.49	\$1.25
1/2-Gallon Skim Milk	2.00	1.80	1.95
Boned Chicken	3.75	4.50	4.25
Raisin Bran Cereal	2.75	3.20	3.10
6-Pack Budweiser	3.50	4.20	3.99
Total Send Order	\$13.39 t	\$15.19	\$14.54

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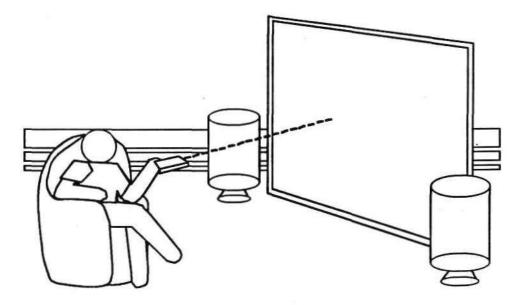
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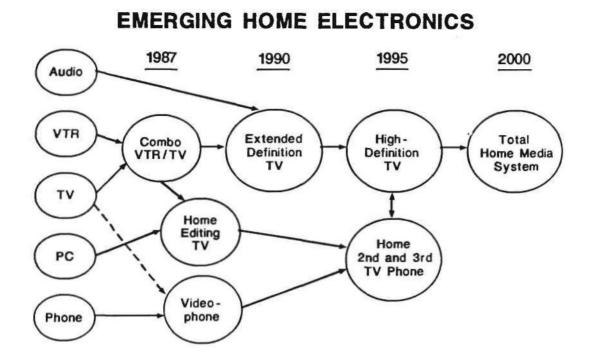
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6 p.m. - SHOPPING PICKUP



7 p.m. - HOME ENTERTAINMENT





HOT NEW HOME ELECTRONIC SEMICONDUCTORS

Emerging Systems	Semiconductors Needed
Large - Screen	Video RAMs (4Mb/16Mb/64Mb)
Combo VTR/TV	32-bit video processors
	Sea-of-gates ASICs
Remote Control	Semiconductor lasers
Handsets	Voice recognition chips
	32-bit controllers
Videophone Sets	Voice recognition chips
(Second or	Video RAMs
Third TVs)	CCD sensors
un rokosan operni – (venn rakovijst 🖝)	Specialized 32-bit video processors

FUTURE KEY TECHNOLOGIES

Devices

Megabit Memories (2-D and 3-D)

Specialized 32-bit MPUs

Optoelectronic ICs (OECs)

Applications

Video and voice storage PC data cards Icon generators

Video and voice processing Parallel processing Complex system controllers (handsets, PCs)

Semiconductor laser controllers Optical computing Video transmission processing Sensors

Superconductors

Ultrasupercomputing

MEETING THE COMING TECHNOLOGY EXPLOSION

- Service:
 - Closer vendor-user ties
 - Linkage of marketing and after-sales servicing
- Design:
 - 3-D CAD tools
 - Stronger applications engineering
- Manufacturing:
 - Flexible modular fabs
 - Increased status of manufacturing "researchers"
 - Rotation between production and R&D
 - Development of proprietary fab equipment

Dataquest

BB a company of The Dun & Bradstreet Corporation





SILICON AND EPITAXIAL WAFERS: STATUS AND FUTURE

Taro Sugawara Executive Vice President Shin-etsu Handotai Co., Ltd.

Mr. Sugawara is Executive Vice President of Shin-etsu Handotai Co., Ltd. He is also Senior Managing Director/General Manager of the Semiconductor Material Division of Shin-etsu Chemical Co., Ltd. Before attaining his current postions, Mr. Sugawara held a variety of executive positions at Shin-etsu Chemical Co., Ltd. He joined the company in 1952. Mr. Sugawara graduated from Hokkaido University (Faculty of Science).

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PRESENT AND FUTURE PROSPECT OF .. SILICON/EPITAXIAL WAFER MARKET

APRIL 12 1988

SHIN-ETSU HANDOTAI CO., LTD.

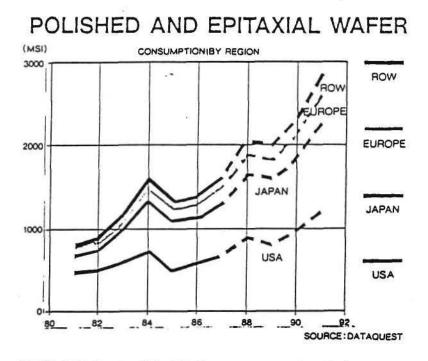
EXECUTIVE VICE PRESIDENT

TARO SUGAWARA

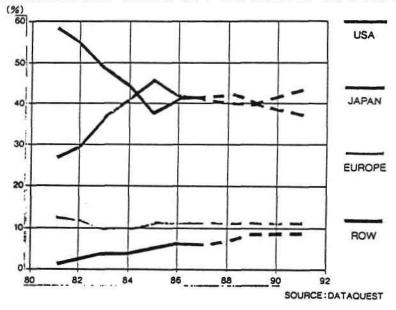
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SILICON MARKET TRENDS
 WAFERS FOR VLSI TECHNOLOGY
 EPI TRENDS
 SEH GLOBAL ORGANIZATION

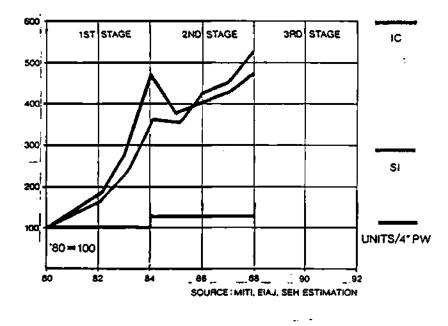
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REGIONAL SILICON MARKET SHARE



IC PRODUCTION VS SI CONSUMPTION IN JAPAN PRODUCTION UNITS AND PW USED



LESS SILICON CONSUMPTION DURING '85-'87

YIELD SUBSTANTIALLY IMPROVED

CHIP SIZE SHRUNK

LESS WAFERS CONSUMED FOR MONITOR

- 3 -



1. IMPURITY CONTROL

2. CRYSTALLOGRAPHIC DEFECTS CONTROL

3. THERMAL HISTORY

4. OXYGEN CONTROL

WAFERING

1. SURFACE INTEGRITY

2. FLATNESS FROM GLOBAL TO SITE

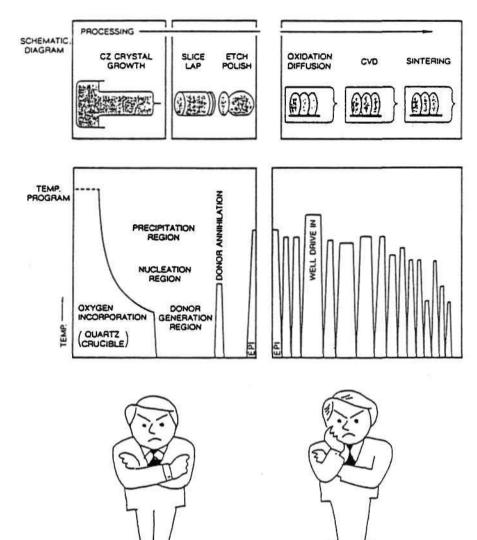
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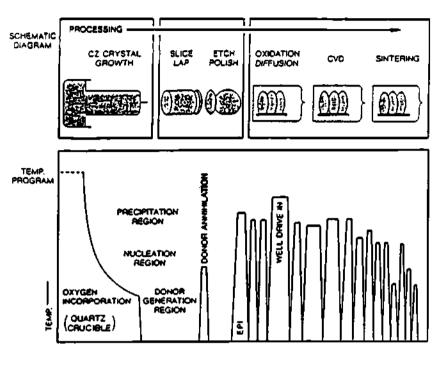


CRYSTAL WORLD DEVICE WORLD



- 5 -

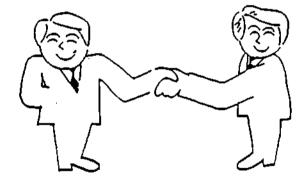
CRYSTAL WORLD DEVICE WORLD



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- 6 -

4



1. IMPURITY CONTROL

1

2. CRYSTALLOGRAPHIC DEFECTS CONTROL

3. THERMAL HISTORY

4. OXYGEN CONTROL

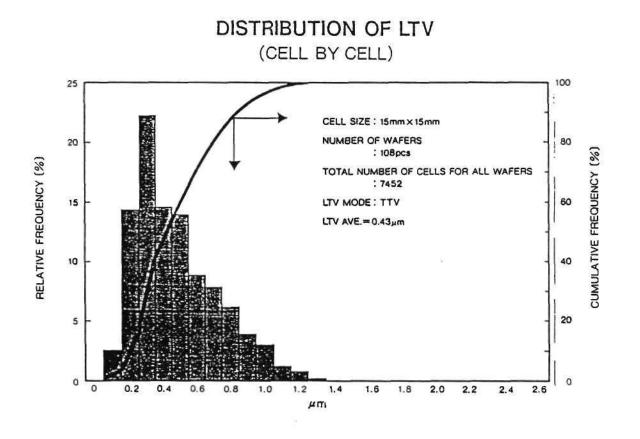
WAFERING

1. SURFACE INTEGRITY

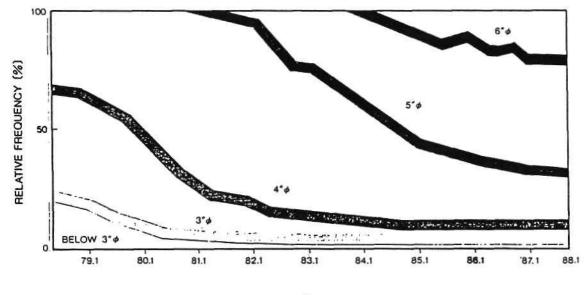
2. FLATNESS FROM GLOBAL TO SITE

- 7 -

SEH



DIAMETER TREND OF CZ WAFERS (SHIPPING BASE IN JAPAN)





CAN 8" ERA BE AROUND CORNER?

12

STATUS QUO: PILOT PRODUCTION

NEEDS FOR LARGER WAFER: MASS PRODUCTION TRADITIONAL YIELD IMPROVEMENT GROWING CHIP SIZE

AREAS OF IMPROVEMENT REQUIRED: HIGH COST MACHINE, INSPECTION GEAR CONSISTENT QUALITY

PROSPECTS:

1) LIMITED USE MEMORY CPU

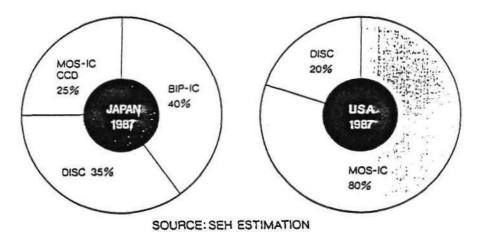
2) MASS PRODUCTION FROM 1990 ONWARD

- 9 -

-SEH-

EPI TRENDS

EPW MERCHANT MARKET



CHARACTERISTICS OF USA AND JAPANESE MARKET

	J	APAN		l	JSA	
MERCHANT PRODUCTS	BIP	DISC	MOS	BIP	DISC	MOS
	40%	35%	25%	0%	20%	80%
GROWING MARKET	CCD	BI-CM	os	C-M	OS BI	-CMOS
c		C-MOS LOGIC		POWER MOS FET		
	POWE	R MOS	FET			

IMPROVEMENTS REQUIRED IN EPI AREA

1. EPI PROCESS COST TO BE LOWERED

2. MACHINERY TO BE IMPROVED

LOW COST, HIGH PRODUCTIVITY

LARGE DIAMETER

3. QUALITY TO BE IMPROVED

FLATNESS,

LPD, PROFILE ETC

4. STRATEGY FOR VALUE ADDED PRODUCTS

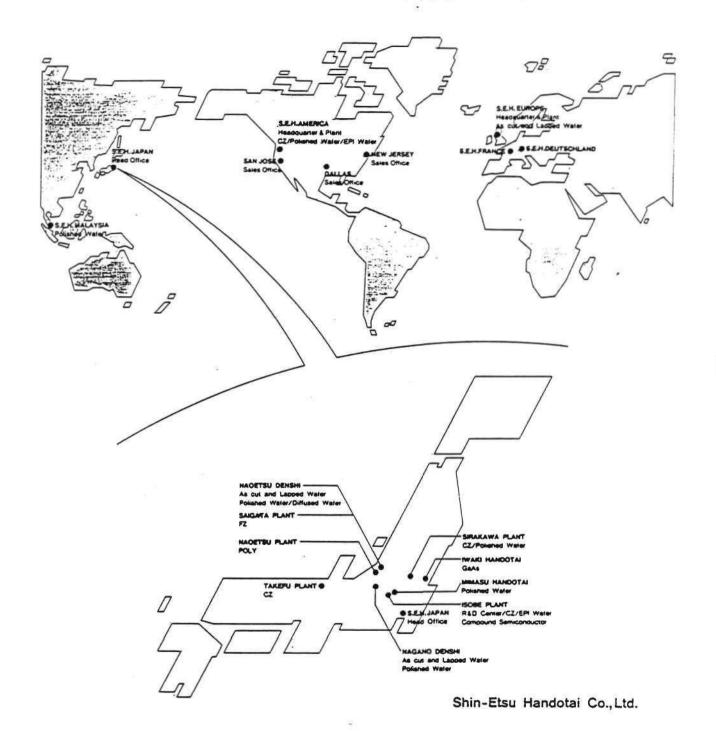
BURIED LAYER, EPI

5. OTHER TECHNOLOGICAL RIVALRY

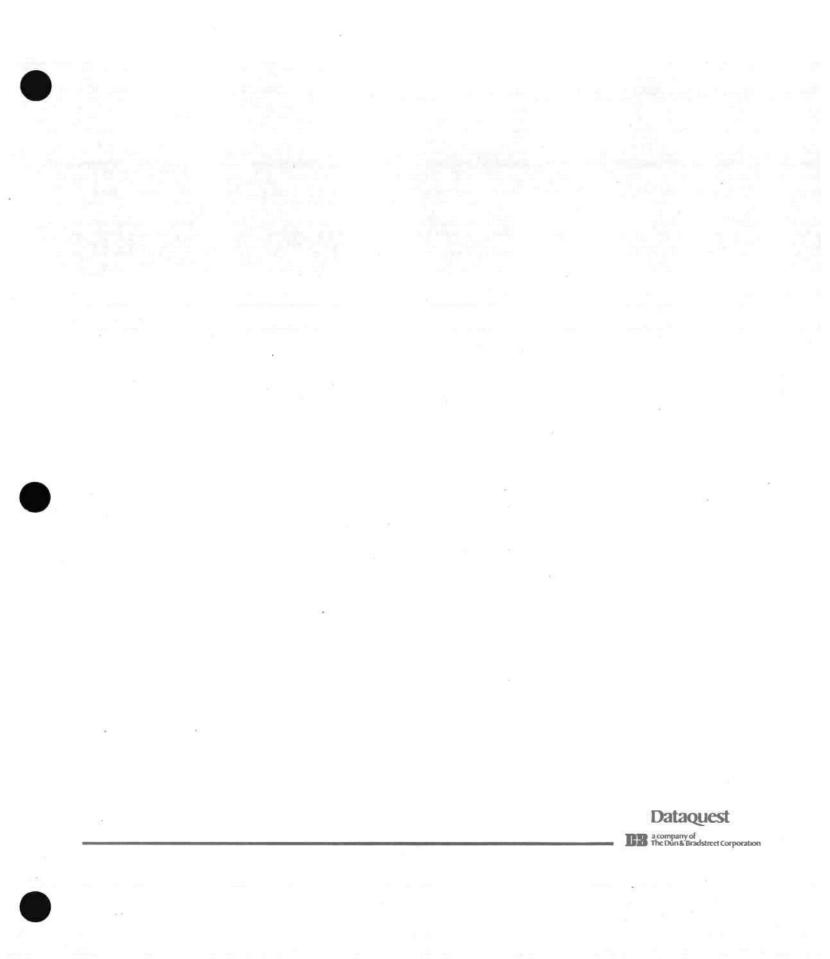
- 11 -

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S.E.H.'S WORLD WIDE LOCATIONS



- 12 -



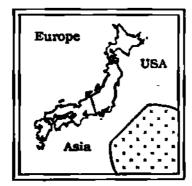


FUTURE TRENDS OF THE WORLD MEMORY MARKET

Victor de Dios Senior Industry Analyst Semiconductor Industry Service Dataquest Incorporated

Mr. de Dios is a Senior Industry Analyst for Dataquest's Semiconductor Industry Service, focusing on analysis of the memory IC market. He has responsibility for tracking and evaluating market movements, forecasting market size, and tracking technology trends. Prior to joining Dataquest, Mr. de Dios held positions in product marketing management for a variety of leading MOS memory device companies. He was responsible for introducing several new memory products into the U.S. market and developing major account penetration strategies. Mr. de Dios received a B.S.E.E. degree from the University of the Philippines and an M.B.A. degree from Wharton School, University of Pennsylvania.

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Japan's New International Role: Competition and Cooperation

FUTURE TRENDS OF THE WORLD MEMORY MARKET

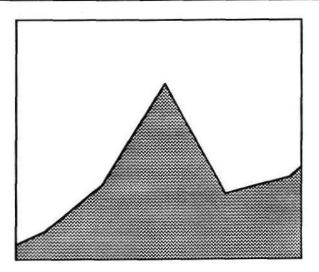
VICTOR DE DIOS

Senior Industry Analyst Semiconductor Industry Service Dataquest Incorporated

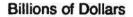
AGENDA

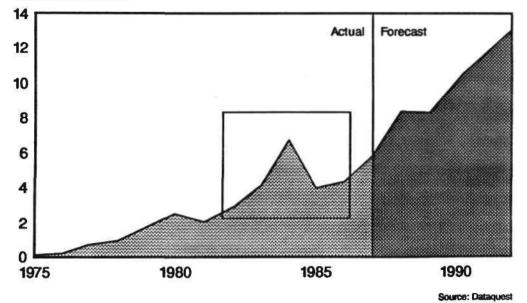
- Market forecast
- Near-term outlook
- Long-term outlook

THE HIGHER THE MOUNTAIN, THE DEEPER THE VALLEY



MOS MEMORY REVENUE





AGENDA

Market forecast

MEMORY MARKET INFLUENCES

- Slower electronic equipment growth
- Increased pervasiveness
- Another recession?
- Submicron processes: higher capital, costs
- Political intervention: FMV, MITI
- Devaluing dollar, stronger yen

MOS MEMORY FORECAST

	(Million	ns of Dollars)		
	1987 1 9 88 19 92			1987-19 92 CAGR
MOS Memory	5,846	8,388	13,107	17.5%
DRAM	2,761	4,605	7,017	20.5%
SRAM (>70ns)	718	1,016	1,530	16.3%
SRAM (<70ns)	369	450	645	11.8%
EPROM	1,259	1,399	2,625	15.8%
ROM	485	496	454	(1.3%)
EEPROM	189	309	576	25.0%
Others	65	113	260	32.0%

Source: Dataquest

AGENDA

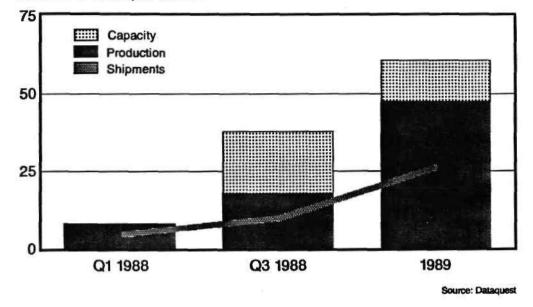
- Market forecast
- Near-term outlook

NEAR-TERM OUTLOOK

- Sufficient capacity in 1988
- Yield improvement may ease shortage by late Q3 1988
- Threat of slowing demand
- Effect of reentry of political influences

ESTIMATED 1Mb DRAM PRODUCTION RATES

Millions of Units per Month



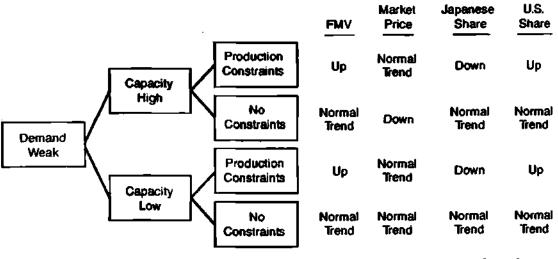
MEMORY DEMAND POSSIBLE EARLY WARNING SIGNALS

- New product manufacturing rates versus sales rates
- Demand double-counting
- Conversion to new products
- New operating systems need larger memories: immediate demand?

MEMORY DEMAND POSSIBLE EARLY WARNING SIGNALS

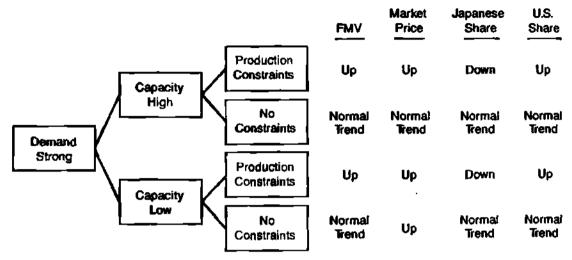
- More memory per system: upward and downward accelerator
- Uncertainty over U.S. economy
- Shortage causes revised demand projections
- 256K versus 1Mb product mix

POTENTIAL EFFECT OF POLITICAL INFLUENCES ON DRAM MARKET



Source: Dataquest

POTENTIAL EFFECT OF POLITICAL INFLUENCES ON DRAM MARKET



Source: Dataquest

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AGENDA

- Market forecast
- Near-term outlook
- Long-term outlook

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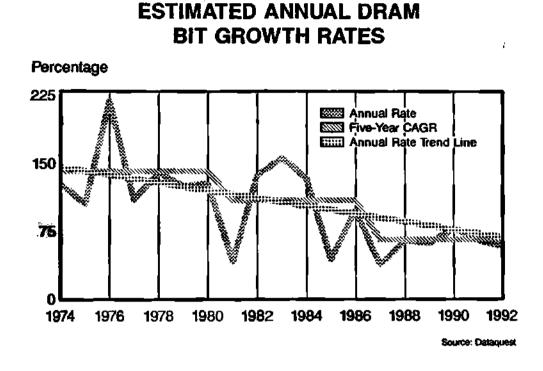
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LONG-TERM OUTLOOK

- Slower bit growth until 1991
 Slower electronic equipment growth
- Beyond 1992: new applications
- New technologies emerging
- Specialty memories more significant
- Rising cost of technology and production

BIT GROWTH CONTRIBUTORS

- New applications
- Memory bits/system
- System shipments
- Conversion from other memory technologies



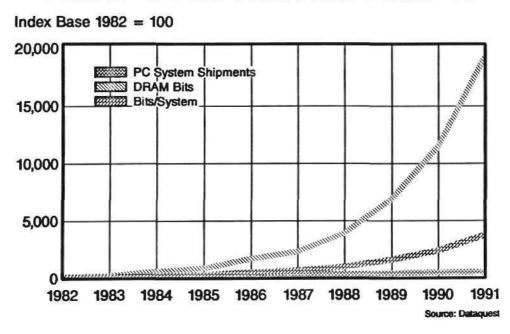
WORLDWIDE ELECTRONIC EQUIPMENT UNIT GROWTH FORECAST

	1982-1986 <u>CAGR</u>	1987-1991 CAGR
Personal Computers	34%	10%
Computer Storage	46%	12%
Business Computers	23%	10%

Source: Dataquest

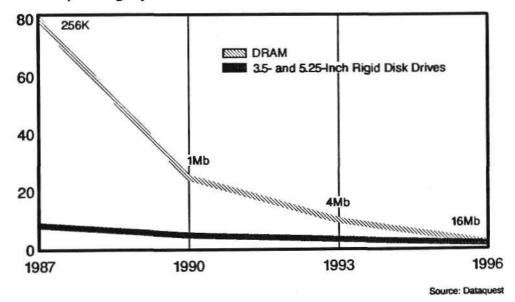
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PERSONAL COMPUTER DRAM FORECAST



ESTIMATED DRAM COST/BYTE TREND

Dollars per Megabyte



HIGH-PERFORMANCE COMPUTER APPLICATIONS

Application	Requirements	Devices
Primary Memory	Speed, density	BICMOS DRAMs, cache tags, cache data RAMs
Secondary Memory	Nonvolatility, density	Low-power DRAM, flash memory
Graphics Memory	Speed, density interface	Video RAM, video DAC (SRAM), color palette memory, fast SRAMs/FIFOs, high-density ROMs
Control Storage	Speed, diagnostics, organization	Smart fast SRAM/EPROM/ EEPROM

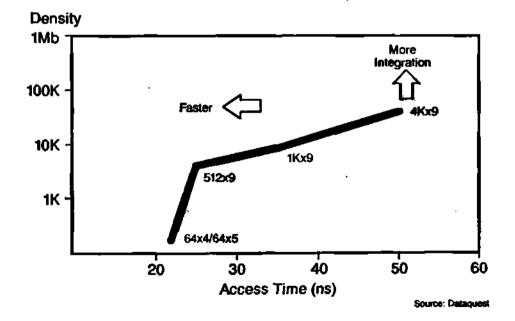
HIGH-PERFORMANCE COMPUTER APPLICATIONS

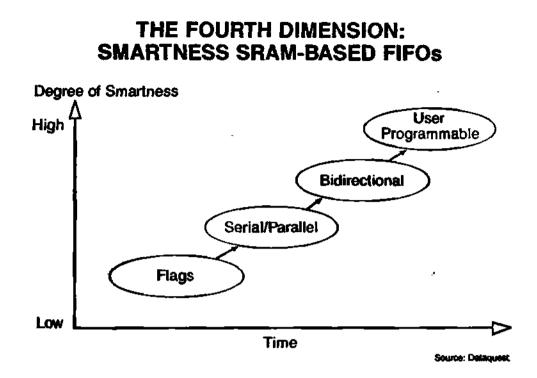
Application	Requirements	Devices
Program Storage	Density, speed	Faster, larger EPROMs, flash memory, faster, larger EEPROMs
Processor-to-Processor Communication	Density, speed, buffering features	Smart fast FIFOs, smart fast dual-port ROMs
Processor-to-Peripheral Communication	Density, buffering features	Smart slow FIFOs
Peripheral Memory	Density, buffering features	Frame DRAM, pseudo-SRAM, EPROMs

EMERGING APPLICATIONS

- Graphics/imaging memory
- Digital TV: IDTV, HDTV
- Fixed-drive replacements
- Memory IC cards
- Color laser printers
- Neural network systems
- Speech recognition

SRAM-BASED FIFO SPEED/DENSITY TRENDS





MAJOR TECHNOLOGICAL ISSUES

- Return of ECL interface levels?
- DRAM 3-D cell issues
- Packaging: surface mount to TAB
- Rising cost of technology

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SUBMICRON PROCESS CHALLENGES

- Higher capital requirements
- Higher production costs
- Smaller surface-mount packages
- Increased performance
- Yield problems of 3-D cells

SUMMARY

- Good memory market prospects
- Changing markets
- Manage cyclical nature

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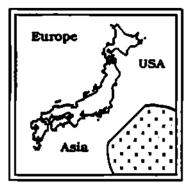


JAPANESE SEMICONDUCTOR EQUIPMENT INDUSTRY: STATUS AND FUTURE

Kazunori Hayashi Industry Analyst Japanese Semiconductor Industry Service Dataquest Japan Limited

Mr. Hayashi is an Industry Analyst for Dataquest's Japanese Semiconductor Industry Service (JSIS) and is based in Tokyo. He covers the semiconductor equipment and materials area. Among his responsibilities are researching and compiling the JSIS capacity analysis data base and updating the semiconductor equipment and materials data base. Prior to joining Dataquest, Mr. Hayashi was a founder of Innov Japan and Techno System Research Corporation. He has had 12 years experience in the industry. During this time, he has authored publications and performed research and consulting on the Japanese semiconductor equipment industry. Mr. Hayashi is a Commercial Sciences graduate of Meiji University.

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Japan's New International Role: Competition and Cooperation

JAPANESE SEMICONDUCTOR EQUIPMENT INDUSTRY: STATUS AND FUTURE

KAZUNORI HAYASHI

Japanese Semiconductor Industry Service Dataquest Japan Limited

AGENDA

- Capital spending
- Wafer fab equipment forecast
- Wafer fab equipment data base by region

ESTIMATED WORLDWIDE SEMICONDUCTOR PRODUCTION AND CAPITAL SPENDING

(Millions of Dollars)						
	1983	1984	1985	1986	<u>1987</u>	CAGR 1983-1987
Semiconductor Production	23,242	33,464	29,698	36,431	44,508	18%
Capital Spending	4,238	8,738	7,238	5,303	5,924	9%
Wafer Fabrication Equipment	2,127	3,530	3,341	2,598	2,725	6%

Source: Dataquest

ESTIMATED WORLDWIDE SEMICONDUCTOR PRODUCTION AND CAPITAL SPENDING

(Millions of Dollars)						
	<u>1988</u>	1989	1990	1991	1992	CAGR 1988-1992
Semiconductor Production	54,723	55,332	62,865	73,488	87,778	13%
Capital Spending	7,660	7,889	9,897	12,564	16,122	20%
Wafer Fabrication Equipment	3,419	3,591	4,459	5,622	7,120	20% Source: Dataquest

CAPITAL SPENDING BY REGION (PRELIMINARY ESTIMATES)

	(Millions of	CAGR	
	1987	1988	1987-1988
United States	1,908	2,539	33%
Japan	1,683	2,300	37%
Europe	823	906	10%
ROW	406	606	49%
Captive	1,104	1,309	18%
Total	5,924	7,660	29%
	<i>'</i> -		Source: Dataquest

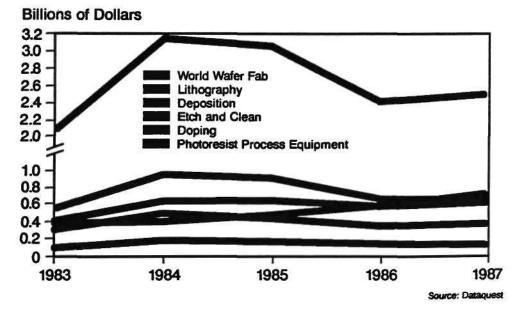
WORLDWIDE WAFER FAB EQUIPMENT HISTORY

(Millions of Dollars)

	1983	1984	1985	1986	1987	CAGR 1983-1987
Lithography	567	954	909	661	667	4%
Photoresist						
Process Equipment	100	185	166	144	133	7%
Etch and Clean	320	499	446	358	384	5%
Deposition	414	637	650	584	641	12%
Doping	300	495	532	311	323	2%

Source: Dataquest

WORLDWIDE WAFER FAB EQUIPMENT HISTORY



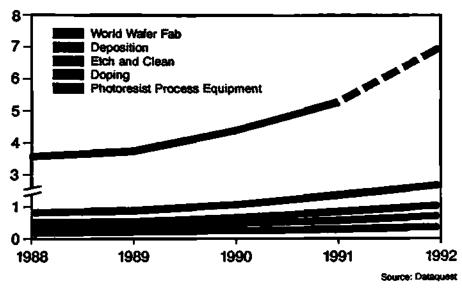
WORLDWIDE WAFER FAB EQUIPMENT FORECAST

	(N	lillions o	f Dollars))		
	<u>1988</u>	1989	1990	1991	<u>1992</u>	CAGR 1988-1992
Lithography Photoresist	811	877	1,086	1,375	1,749	21%
Process Equipment	162	175	217	275	350	21%
Etch and Clean	496	514	650	828	1,057	21%
Deposition	829	866	1,078	1,360	1,715	20%
Doping	386	395	478	584	720	17%

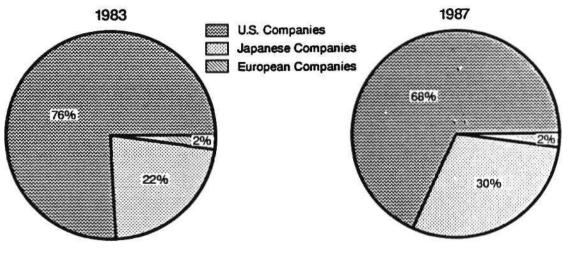
Source: Dataquest

WORLDWIDE WAFER FAB EQUIPMENT FORECAST

Billions of Dollars

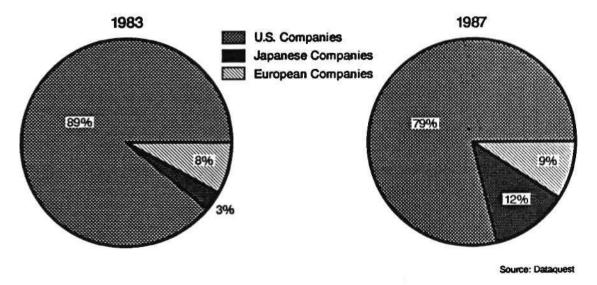


ESTIMATED WORLDWIDE WAFER FAB EQUIPMENT MARKET SHARE BY REGION

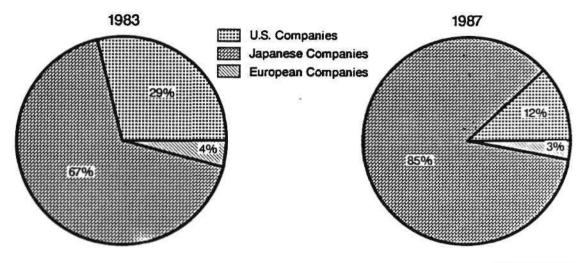


Source: Dataquest

ESTIMATED U.S. WAFER FAB EQUIPMENT MARKET SHARE BY REGION

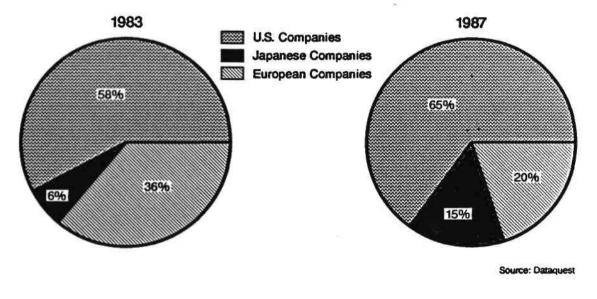


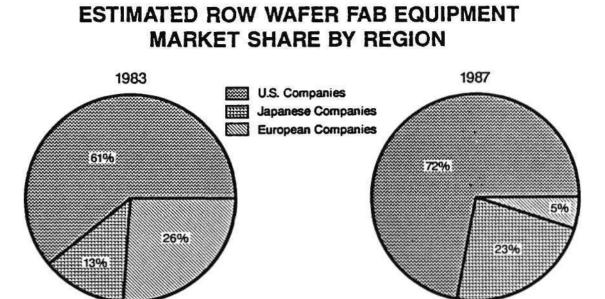
ESTIMATED JAPANESE WAFER FAB EQUIPMENT MARKET SHARE BY REGION



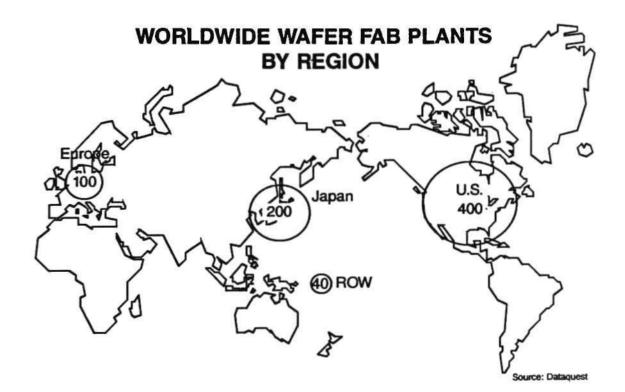
Source: Dataquest

ESTIMATED EUROPEAN WAFER FAB EQUIPMENT MARKET SHARE BY REGION





Source: Dataquest



JAPANESE SEMICONDUCTOR EQUIPMENT ALLIANCES

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Process	Company A	Company B	Product	Type of Alliance
Litho	Citizen Watch	Perkin Elmer	Stepper	Joint development
	Dai Nippon Screen	MRS Technology	Stepper for LCD	Sales agent
	JEOL	NTT	E-8	Joint development
	Mitsubishi	Sortech	SOR	Joint development
	Nikon	Matsushita	I-line stepper	
			and excimer	Joint development
Eich	Anelva	Branson IPC	Stripper	Sales agent
	Sumitomo Metal	Lam Research	Plasma etcher	Sales agent
Implant	Innotech	General Ionex	High current	Sales agent
				Source: Dataquest

JAPANESE SEMICONDUCTOR EQUIPMENT ALLIANCES

Process	Company A	Company B	Product	Type of Alliance
Diffusion	Sumisho Ele	Silicon Valley Group	Vertical thermal reactor	Sales agent
CVD	Nippon Sanso Marubemi Hitec Seki Company Sumisho Ele	Spire Watkins-Johnson Novelus SVG	MOCVD APCVD LPCVD LPCVD	Sales agent Sales agent Sales agent Sales agent
Testers	Kobe Steel	Megatest	IC tester	Joint development
Assembly	lkegami Tsushinki	Pacific Semiconductor Equipment	Bonder	Joint development with Kamematsu

Source: Dataquest

CONCLUSION

	CAGR 1988-1992
Semiconductor Production	13%
Capital Spending	20%
Wafer Fab Equipment	20%
Stepper	26%
Dry Etch	29%
CVD	. 23%
R.T.P.	35%
ion Implantation	24%
	Source: Dataquest

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